

DSP1629 Digital Signal Processor

1 Features

- Optimized for mobile communications applications with a bit manipulation unit for higher coding efficiency.
- On-chip, programmable, PLL clock synthesizer.
- 10 ns and 16.7 ns instruction cycle times at 3.0 V, and 19.2 ns and 12.5 ns instruction cycle times at 2.7 V.
- Mask-programmable memory map option: the DSP1629x16 features 16 Kwords on-chip dual-port RAM. The DSP1629x10 features 10 Kwords on-chip dual-port RAM. Both feature 48 Kwords on-chip ROM with a secure option.
- Low power consumption:
 - <1.9 mW/MIPS typical at 2.7 V.
- Flexible power management modes:
 - Standard sleep: 0.2 mW/MIPS at 2.7 V.
 - Sleep with slow internal clock: 0.7 mW at 2.7 V.
 - Hardware STOP (pin halts DSP): <20 μ A.
- Mask-programmable clock options: small signal and CMOS.
- 100-TQFP package, providing excellent second-level reliability.
- Sequenced accesses to X and Y external memory.
- Object code and pin compatible with the DSP1627.
- Single-cycle squaring.
- 16 x 16-bit multiplication and 36-bit accumulation in one instruction cycle.
- Instruction cache for high-speed, program-efficient, zero-overhead looping.
- Dual 25 Mbits/s serial I/O ports with multiprocessor capability:
 - 16-bit data channel, 8-bit protocol channel.
- 8-bit parallel host interface:
 - Supports 8-bit or 16-bit transfers.
 - *Motorola*® or *Intel*® compatible.
- 8-bit control I/O interface.
- 256 memory-mapped I/O ports.
- *IEEE*® P1149.1 test port (JTAG boundary scan).
- Full-speed in-circuit emulation hardware development system on-chip.

- Supported by DSP1629 software and hardware development tools.

2 Description

The DSP1629 is Agere Systems Inc.'s first digital signal processor offering 100 MIPS operation at 3.0 V and 80 MIPS operation at 2.7 V with a reduction in power consumption. Designed specifically for applications requiring low power dissipation in mobile communications systems, the DSP1629 is a signal-coding device that can be programmed to perform a wide variety of fixed-point signal processing functions. The device is based on the DSP1600 core with a bit manipulation unit for enhanced signal coding efficiency. The DSP1629 includes a mix of peripherals specifically intended to support processing-intensive but cost-sensitive applications in the area of digital wireless communications.

The DSP1629x16 contains 16 Kwords of internal dual-port RAM (DPRAM), which allows simultaneous access to two RAM locations in a single instruction cycle. The DSP1629x10 supports the use of 10 Kwords of DPRAM. Both devices contain 48 Kwords of internal ROM (IROM).

The DSP1629 is object code compatible with the DSP1627 while providing more memory. The DSP1629 is pin compatible with the DSP1627. Note that TRST (JTAG test reset) replaces a VDD pin.

The DSP1629 supports 2.7 V and 3.0 V operation and features flexible power management modes. Several control mechanisms achieve low-power operation, including a STOP pin for placing the DSP into a fully static, halted state, and a programmable power control register used to power down unused on-chip I/O units. These power management modes allow for trade-offs between power reduction and wake-up latency requirements. During system standby, power consumption is reduced to less than 20 μ A.

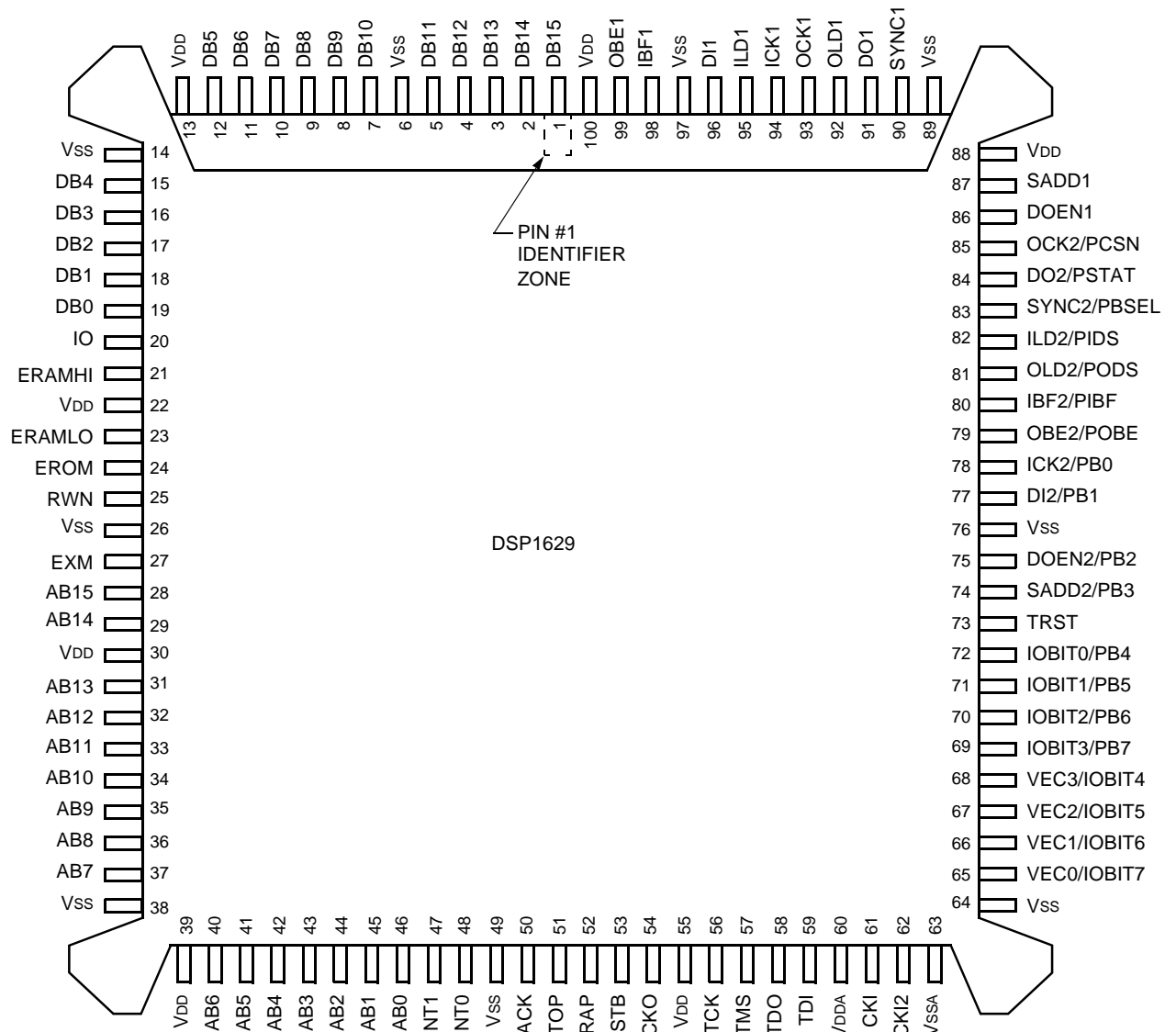
The on-chip clock synthesizer can be driven by an external clock whose frequency is a fraction of the instruction rate.

The device is packaged in a 144-pin PBGA, a 100-pin BQFP, or a 100-pin TQFP, and is available with 10 ns and 16.7 ns instruction cycle times at 3.0 V, and 19.2 ns and 12.5 ns instruction cycle times at 2.7 V.

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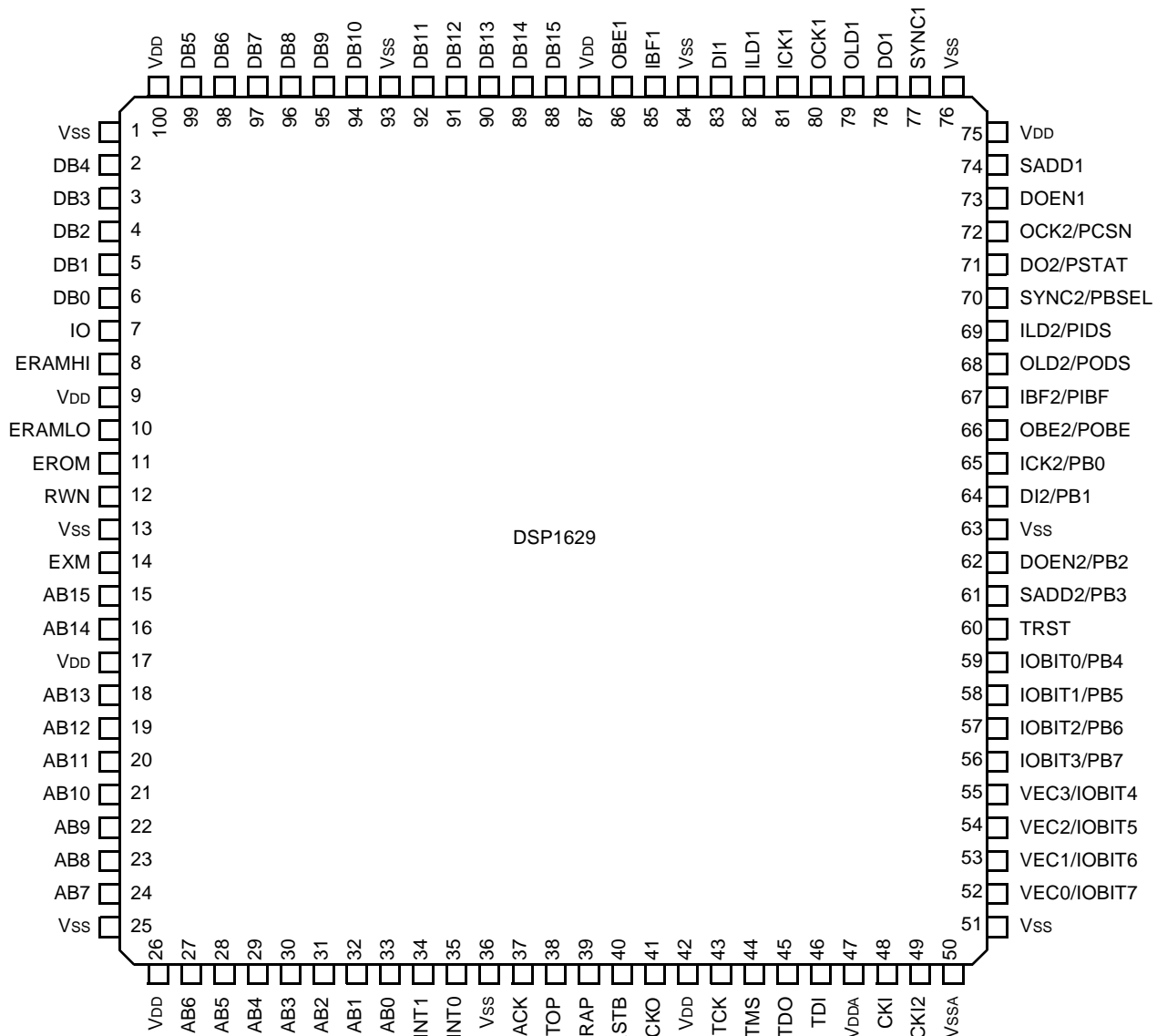
3 Pin Information



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Figure 1. DSP1629 BQFP Pin Diagram

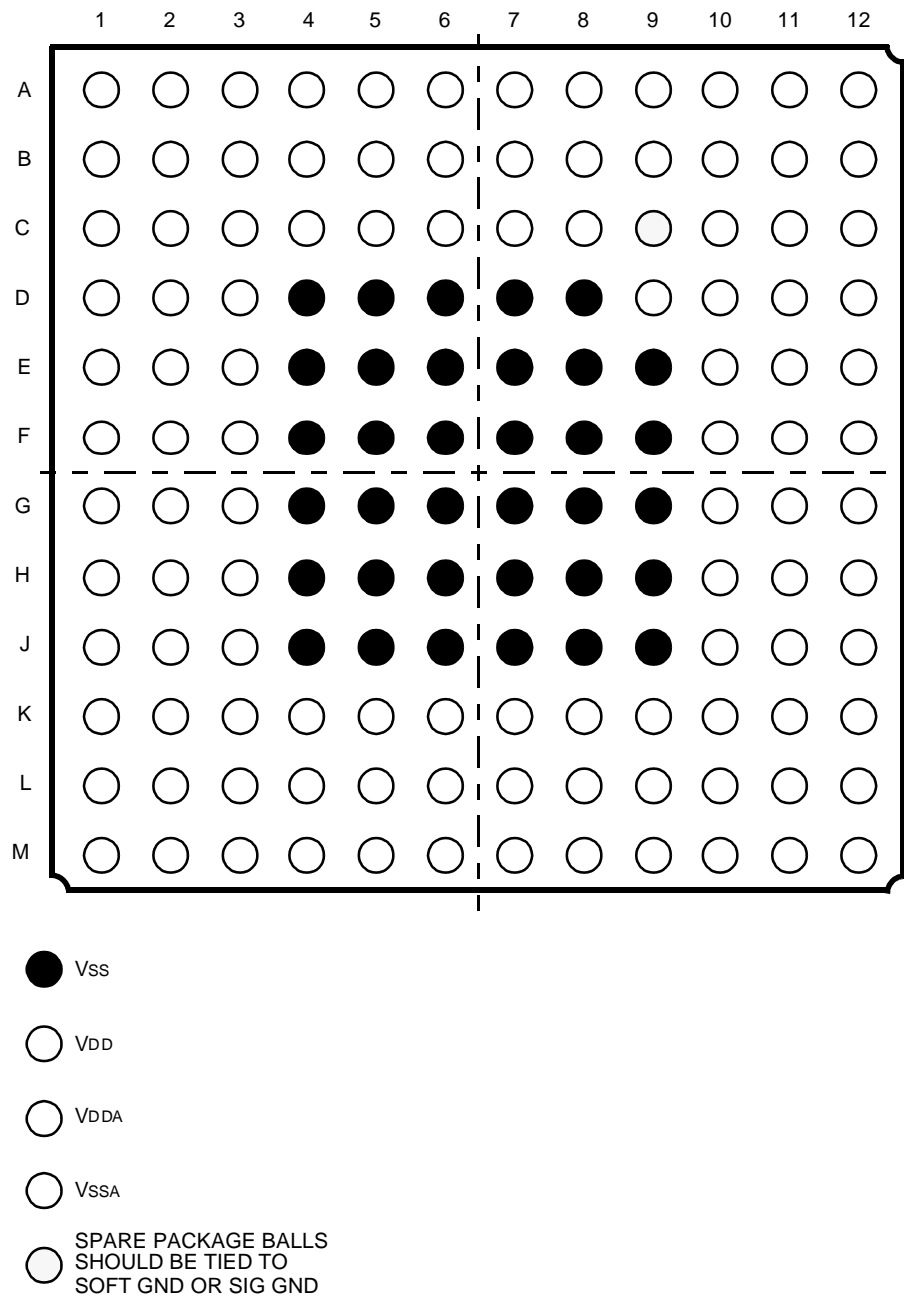
3 Pin Information (continued)



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Figure 2. DSP1629 TQFP Pin Diagram

3 Pin Information (continued)



5-5224 (C)

Note: Solder balls viewed through package.

Figure 3. 144-Pin Plastic Ball Grid Array (Top View)

3 Pin Information (continued)

Functional descriptions of pins 1—100 are found in Section 6, Signal Descriptions. The functionality of CKI and CKI2 pins are mask-programmable (see Section 7, Mask-Programmable Options). Input levels on all I and I/O type pins are designed to remain at full CMOS levels when not driven by the DSP.

Table 1. Pin Descriptions

PBGA Pin	BQFP Pin	TQFP Pin	Symbol	Type	Name/Function	
B6, A6, B5, A5, B4, A4, B3, A3, B2, A2, A1, B1, C2, C1, C3, D1	1, 2, 3, 4, 5, 7, 8, 9, 10, 11, 12, 15, 16, 17, 18, 19	88, 89, 90, 91, 92, 94, 95, 96, 97, 98, 99, 2, 3, 4, 5, 6	DB[15:0]	I/O*	External Memory Data Bus 15—0.	
D2	20	7	IO	O†	Data Address 0x4000 to 0x40FF I/O Enable.	
E1	21	8	ERAMHI	O†	Data Address 0x8000 to 0xFFFF External RAM Enable.	
E2	23	10	ERAMLO	O†	Data Address 0x4100 to 0x7FFF External RAM Enable.	
F1	24	11	EROM	O†	Program Address External ROM Enable.	
F2	25	12	RWN	O†	Read/Write Not.	
G1	27	14	EXM	I	External ROM Enable.	
G2, H1, H2, J1, J2, K1, K2, L1, L2, M1, K3, M2, L3, M3, L4, M4	28, 29, 31, 32, 33, 34, 35, 36, 37, 40, 41, 42, 43, 44, 45, 46	15, 16, 18, 19, 20, 21, 22, 23, 24, 27, 28, 29, 30, 31, 32, 33	AB[15:0]	O*	External Memory Address Bus 15—0.	
L5	47	34	INT1	I	Vectored Interrupt 1.	
M5	48	35	INT0	I	Vectored Interrupt 0.	
L6	50	37	IACK	O*	Interrupt Acknowledge.	
M6	51	38	STOP	I	STOP Input Clock.	
L7	52	39	TRAP	I/O*	Nonmaskable Program Trap/Breakpoint Indication.	
M7	53	40	RSTB	I	Reset Bar.	
L8	54	41	CKO	O†	Processor Clock Output.	
M8	56	43	TCK	I	JTAG Test Clock.	
L9	57	44	TMS	I‡	JTAG Test Mode Select.	
M9	58	45	TDO	O§	JTAG Test Data Output.	
L10	59	46	TDI	I‡	JTAG Test Data Input.	
					Mask-Programmable Input Clock Option	
					CMOS	Small Signal
L11	61	48	CKI**	I	CKI	VAC
M11	62	49	CKI2**	I	VSSA	VCM
K10	65	52	VEC0/IOBIT7	I/O*	Vectored Interrupt Indication 0/Status/Control Bit 7.	
L12	66	53	VEC1/IOBIT6	I/O*	Vectored Interrupt Indication 1/Status/Control Bit 6.	
K11	67	54	VEC2/IOBIT5	I/O*	Vectored Interrupt Indication 2/Status/Control Bit 5.	
K12	68	55	VEC3/IOBIT4	I/O*	Vectored Interrupt Indication 3/Status/Control Bit 4.	
J11	69	56	IOBIT3/PB7	I/O*	Status/Control Bit 3/PHIF Data Bus Bit 7.	
J12	70	57	IOBIT2/PB6	I/O*	Status/Control Bit 2/PHIF Data Bus Bit 6.	
H11	71	58	IOBIT1/PB5	I/O*	Status/Control Bit 1/PHIF Data Bus Bit 5.	
H12	72	59	IOBIT0/PB4	I/O*	Status/Control Bit 0/PHIF Data Bus Bit 4.	
G11	73	60	TRST	I‡	JTAG Test Reset.	

* 3-states when RSTB = 0, or by JTAG control.

† 3-states when RSTB = 0 and INT0 = 1. Output = 1 when RSTB = 0 and INT0 = 0, except CKO, which is free-running.

‡ Pull-up devices on input.

§ 3-states by JTAG control.

** See Section 7, Mask-Programmable Options.

†† For SIO multiprocessor applications, add 5 kΩ external pull-up resistors to SADD1 and/or SADD2 for proper initialization.

3 Pin Information (continued)

Functional descriptions of pins 1—100 are found in Section 6, Signal Descriptions.

Table 1. Pin Descriptions (continued)

PBGA Pin	BQFP Pin	TQFP Pin	Symbol	Type	Name/Function
G12	74	61	SADD2/PB3 ^{††}	I/O*	SIO2 Multiprocessor Address/PHIF Data Bus Bit 3.
F11	75	62	DOEN2/PB2	I/O*	SIO2 Data Output Enable/PHIF Data Bus Bit 2.
F12	77	64	DI2/PB1	I/O*	SIO2 Data Input/PHIF Data Bus Bit 1.
E11	78	65	ICK2/PB0	I/O*	SIO2 Input Clock/PHIF Data Bus Bit 0.
E12	79	66	OBE2/POBE	O*	SIO2 Output Buffer Empty/PHIF Output Buffer Empty.
D11	80	67	IBF2/PIBF	O*	SIO2 Input Buffer Full/PHIF Input Buffer Full.
D12	81	68	OLD2/PODS	I/O*	SIO2 Output Load/PHIF Output Data Strobe.
C11	82	69	ILD2/PIDS	I/O*	SIO2 Input Load/PHIF Input Data Strobe.
C12	83	70	SYNC2/PBSEL	I/O*	SIO2 Multiprocessor Synchronization/PHIF Byte Select.
C10	84	71	DO2/PSTAT	I/O*	SIO2 Data Output/PHIF Status Register Select.
B12	85	72	OCK2/PCSN	I/O*	SIO2 Output Clock/PHIF Chip Select Not.
B11	86	73	DOEN1	I/O*	SIO1 Data Output Enable.
A12	87	74	SADD1 ^{††}	I/O*	SIO1 Multiprocessor Address.
A11	90	77	SYNC1	I/O*	SIO1 Multiprocessor Synchronization.
B10	91	78	DO1	O*	SIO1 Data Output.
A10	92	79	OLD1	I/O*	SIO1 Output Load.
B9	93	80	OCK1	I/O*	SIO1 Output Clock.
A9	94	81	ICK1	I/O*	SIO1 Input Clock.
B8	95	82	ILD1	I/O*	SIO1 Input Load.
A8	96	83	DI1	I	SIO1 Data Input.
B7	98	85	IBF1	O*	SIO1 Input Buffer Full.
A7	99	86	OBE1	O*	SIO1 Output Buffer Empty.
D4, D5, D6, D7, D8, E4, E5, E6, E7, E8, E9, F4, F5, F6, F7, F8, F9, G4, G5, G6, G7, G8, G9, H4, H5, H6, H7, H8, H9, J4, J5, J6, J7, J8, J9	6, 14, 26, 38, 49, 64, 76, 89, 97	93, 1, 13, 25, 36, 51, 63, 76, 84	Vss	P	Ground.
C4, C5, C6, C7, C8, D3, D9, D10, E3, E10, F3, F10, G3, G10, H3, H10, J3, J10, K4, K5, K6, K7, K8, K9	13, 22, 30, 39, 55, 88, 100	100, 9, 17, 26, 42, 75, 87	VDD	P	Power Supply.
M10	60	47	VDDA	P	Analog Power Supply.
M12	63	50	VSSA	P	Analog Ground.
C9	—	—	—	—	No Die Connect—Unused.

* 3-states when RSTB = 0, or by JTAG control.

† 3-states when RSTB = 0 and INT0 = 1. Output = 1 when RSTB = 0 and INT0 = 0, except CKO, which is free-running.

‡ Pull-up devices on input.

§ 3-states by JTAG control.

** See Section 7, Mask-Programmable Options.

†† For SIO multiprocessor applications, add 5 kΩ external pull-up resistors to SADD1 and/or SADD2 for proper initialization.

4 Hardware Architecture

The DSP1629 device is a 16-bit, fixed-point programmable digital signal processor (DSP). The DSP1629 consists of a DSP1600 core together with on-chip memory and peripherals. Added architectural features give the DSP1629 high program efficiency for signal coding applications.

4.1 DSP1629 Architectural Overview

Figure 4, DSP1629 Block Diagram, shows a block diagram of the DSP1629. The following modules make up the DSP1629.

DSP1600 Core

The DSP1600 core is the heart of the DSP1629 chip. The core contains data and address arithmetic units, and control for on-chip memory and peripherals. The core provides support for external memory wait-states and on-chip, dual-port RAM, and features vectored interrupts and a trap mechanism.

Dual-Port RAM (DPRAM)

The DSP1629x16 contains 16 banks of zero wait-state memory and the DSP1629x10 contains 10 banks of zero wait-state memory. Each bank consists of 1K 16-bit words and has separate address and data ports to the instruction/coefficient and data memory spaces. A program can reference memory from either space. The DSP1600 core automatically performs the required multiplexing. If references to both ports of a single bank are made simultaneously, the DSP1600 core automatically inserts a wait-state and performs the data port access first, followed by the instruction/coefficient port access.

A program can be downloaded from slow, off-chip memory into DPRAM, and then executed without wait-states. DPRAM is also useful for improving convolution performance in cases where the coefficients are adaptive. Since DPRAM can be downloaded through the JTAG port, full-speed remote in-circuit emulation is possible. DPRAM can also be used for downloading self-test code via the JTAG port.

Read-Only Memory (ROM)

The DSP1629 contains 48K 16-bit words of zero wait-state, mask-programmable ROM for program and fixed coefficients.

External Memory Multiplexer (EMUX)

The EMUX is used to connect the DSP1629 to external memory and I/O devices. It supports read/write operations from/to instruction/coefficient memory (X memory

space) and data memory (Y memory space). The DSP1600 core automatically controls the EMUX. Instructions can transparently reference external memory from either set of internal buses. A sequencer allows a single instruction to access both the X and the Y external memory spaces.

Clock Synthesis

The DSP powers up with a 1X input clock (CKI/CKI2) as the source for the processor clock. An on-chip clock synthesizer (PLL) can also be used to generate the system clock for the DSP, which will run at a frequency multiple of the input clock. The clock synthesizer is deselected and powered down on reset. For low-power operation, an internally generated slow clock can be used to drive the DSP. If both the clock synthesizer and the internally generated slow clock are selected, the slow clock will drive the DSP; however, the synthesizer will continue to run.

The clock synthesizer and other programmable clock sources are discussed in Section 4.12, Clock Synthesis. The use of these programmable clock sources for power management is discussed in Section 4.13, Power Management.

Bit Manipulation Unit (BMU)

The BMU extends the DSP1600 core instruction set to provide more efficient bit operations on accumulators. The BMU contains logic for barrel shifting, normalization, and bit field insertion/extraction. The unit also contains a set of 36-bit alternate accumulators. The data in the alternate accumulators can be shuffled with the data in the main accumulators. Flags returned by the BMU mesh seamlessly with the DSP1600 conditional instructions.

Bit Input/Output (BIO)

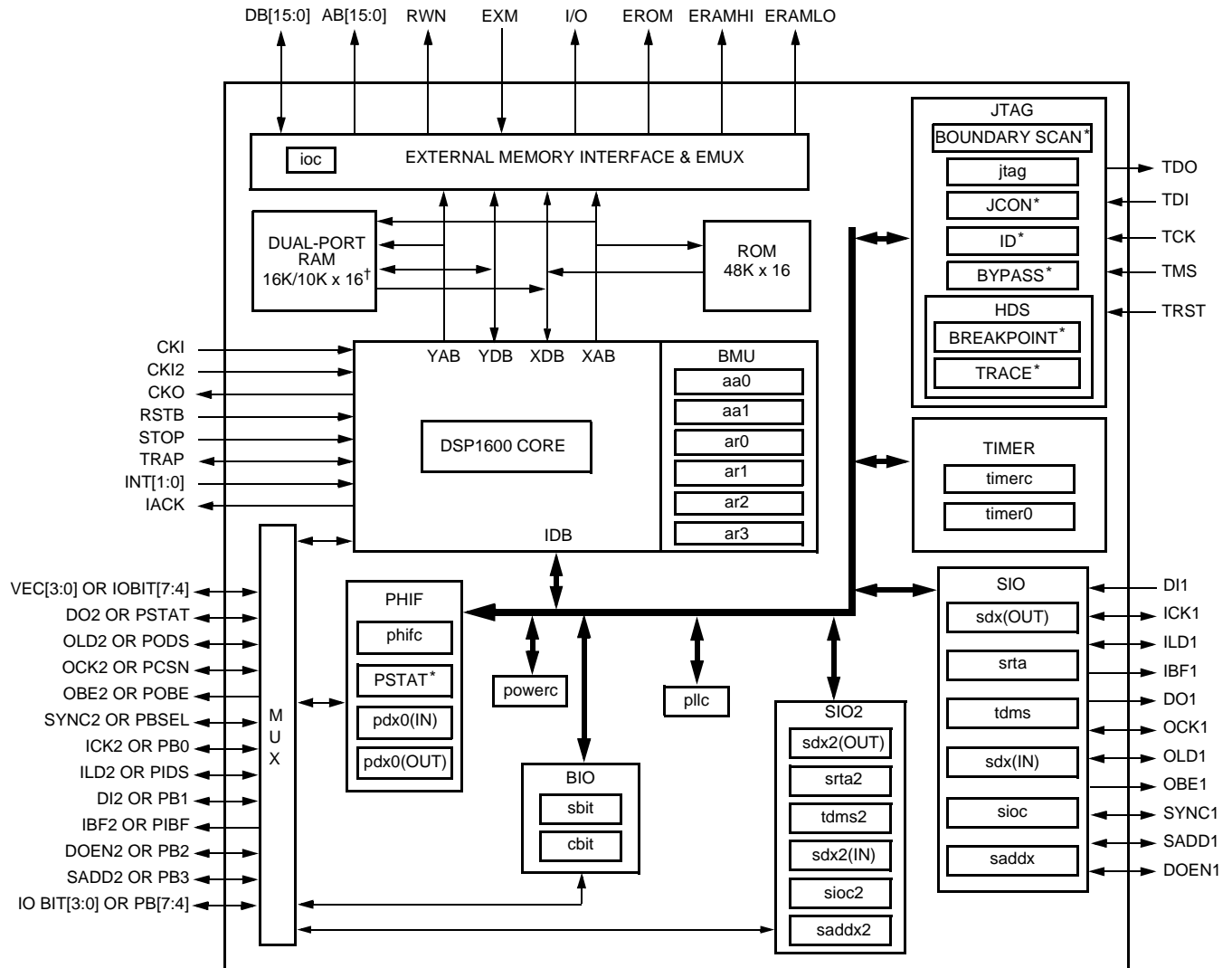
The BIO provides convenient and efficient monitoring and control of eight individually configurable pins. When configured as outputs, the pins can be individually set, cleared, or toggled. When configured as inputs, individual pins or combinations of pins can be tested for patterns. Flags returned by the BIO mesh seamlessly with conditional instructions.

Serial Input/Output Units (SIO and SIO2)

SIO and SIO2 offer asynchronous, full-duplex, double-buffered channels that operate at up to 25 Mbits/s (for a 20 ns instruction cycle in a nonmultiprocessor configuration), and easily interface with other Agere Systems' fixed-point DSPs in a multiple-processor environment. Commercially available codecs and time-division multiplex (TDM) channels can be interfaced to the serial I/O ports with few, if any, additional components. SIO2 is identical to SIO.

4 Hardware Architecture (continued)

An 8-bit serial protocol channel may be transmitted in addition to the address of the called processor in multiprocessor mode. This feature is useful for transmitting high-level framing information or for error detection and correction. SIO2 and BIO are pin-multiplexed with the PHIF.



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* These registers are accessible through the pins only.

† 16K x 16 for the DSP1629x16, 10K x 16 for the DSP1629x10.

Figure 4. DSP1629 Block Diagram

4 Hardware Architecture (continued)

Table 2. DSP1629 Block Diagram Legend

Symbol	Name
aa<0—1>	Alternate Accumulators.
ar<0—3>	Auxiliary BMU Registers.
BIO	Bit Input/Output Unit.
BMU	Bit Manipulation Unit.
BREAKPOINT	Four Instruction Breakpoint Registers.
BYPASS	JTAG Bypass Register.
cbit	Control Register for BIO.
Dual-Port RAM	Internal RAM (16 Kwords for DSP1629x16, 10 Kwords for DSP1629x10).
EMUX	External Memory Multiplexer.
HDS	Hardware Development System.
ID	JTAG Device Identification Register.
IDB	Internal Data Bus.
ioc	I/O Configuration Register.
JCON	JTAG Configuration Registers.
jtag	16-bit Serial/Parallel Register.
pdx0(in)	Parallel Data Transmit Input Register 0.
pdx0(out)	Parallel Data Transmit Output Register 0.
PHIF	Parallel Host Interface.
phifc	Parallel Host Interface Control Register.
pll	Phase-Locked Loop Control Register.
powerc	Power Control Register.
PSTAT	Parallel Host Interface Status Register.
saddx	Multiprocessor Protocol Register.
saddx2	Multiprocessor Protocol Register for SIO2.
sbit	Status Register for BIO.
sdx(in)	Serial Data Transmit Input Register.
sdx2(in)	Serial Data Transmit Input Register for SIO2.
sdx(out)	Serial Data Transmit Output Register.
sdx2(out)	Serial Data Transmit Output Register for SIO2.
SIO	Serial Input/Output Unit.
SIO2	Serial Input/Output Unit #2.
sioc	Serial I/O Control Register.
sioc2	Serial I/O Control Register for SIO2.
srt	Serial Receive/Transmit Address Register.
srt2	Serial Receive/Transmit Address Register for SIO2.
tdms	Serial I/O Time-division Multiplex Signal Control Register.
tdms2	Serial I/O Time-division Multiplex Signal Control Register for SIO2.
TIMER	Programmable Timer.
timer0	Timer Running Count Register.
timerc	Timer Control Register.
TRACE	Program Discontinuity Trace Buffer.
XAB	Program Memory Address Bus.
XDB	Program Memory Data Bus.
YAB	Data Memory Address Bus.
YDB	Data Memory Data Bus.

4 Hardware Architecture (continued)

Parallel Host Interface (PHIF)

The PHIF is a passive, 8-bit parallel port which can interface to an 8-bit bus containing other Agere Systems' DSPs, microprocessors, or peripheral I/O devices. The PHIF port supports either *Motorola* or *Intel* protocols, as well as 8-bit or 16-bit transfers, configured in software. The port data rate depends upon the instruction cycle rate. A 25 ns instruction cycle allows the PHIF to support data rates up to 11.85 Mbytes/s, assuming the external host device can transfer 1 byte of data in 25 ns.

The PHIF is accessed in two basic modes: 8-bit or 16-bit mode. In 8-bit mode, only the low byte is accessed. In 16-bit mode, the host determines an access of the high or low byte. Software-programmable features allow for a glueless host interface to microprocessors (see Section 4.8, Parallel Host Interface (PHIF)).

Timer

The timer can be used to provide an interrupt at the expiration of a programmed interval. The interrupt may be single or repetitive. More than nine orders of magnitude of interval selection are provided. The timer may be stopped and restarted at any time.

Hardware Development System (HDS) Module

The on-chip HDS performs instruction breakpointing and branch tracing at full speed without additional off-chip hardware. Using the JTAG port, the breakpointing is set up and the trace history is read back. The port works in conjunction with the HDS code in the on-chip ROM and the hardware and software in a remote computer. The HDS code must be linked to the user's application code and reside in the first 4 Kwords of ROM. The on-chip HDS cannot be used with the secure ROM masking option (see Section 7.3, ROM Security Options).

Four hardware breakpoints can be set on instruction addresses. A counter can be preset with the number of breakpoints to receive before trapping the core. Breakpoints can be set in interrupt service routines. Alternately, the counter can be preset with the number of cache instructions to execute before trapping the core.

Every time the program branches instead of executing the next sequential instruction, the addresses of the instructions executed before and after the branch are caught in circular memory. The memory contains the last four pairs of program discontinuities for hardware tracing.

In systems with multiple processors, the processors may be configured so that any processor reaching a

breakpoint will cause all the other processors to be trapped (see Section 4.3, Interrupts and Trap).

Pin Multiplexing

In order to allow flexible device interfacing while maintaining a low package pin count, the DSP1629 multiplexes 16 package pins between BIO, PHIF, VEC[3:0], and SIO2.

Upon reset, the vectored interrupt indication signals, VEC[3:0], are connected to the package pins while IOBIT[4:7] are disconnected. Setting bit 12, EBIOH, of the ioc register connects IOBIT[4:7] to the package pins and disconnects VEC[3:0].

Upon reset, the parallel host interface (PHIF) is connected to the package pins while the second serial port (SIO2) and IOBIT[3:0] are disconnected. Setting bit 10, ESIO2, of the ioc register connects the SIO2 and IOBIT[3:0] and disconnects the PHIF.

Power Management

Many applications require programmable sleep modes for power management. There are three different control mechanisms for achieving low-power operation: the powerc control register, the STOP pin, and the AWAIT bit in the alf register. The AWAIT bit in the alf register allows the processor to go into a power-saving standby mode until an interrupt occurs. The powerc register configures various power-saving modes by controlling internal clocks and peripheral I/O units. The STOP pin controls the internal processor clock. The various power management options may be chosen based on power consumption and/or wake-up latency requirements.

4.2 DSP1600 Core Architectural Overview

Figure 5, DSP1600 Core Block Diagram, shows a block diagram of the DSP1600 core.

System Cache and Control Section (SYS)

This section of the core contains a 15-word cache memory and controls the instruction sequencing. It handles vectored interrupts and traps, and also provides decoding for registers outside of the DSP1600 core. SYS stretches the processor cycle if wait-states are required (wait-states are programmable for external memory accesses). SYS sequences downloading via JTAG of self-test programs to on-chip, dual-port RAM.

The cache loop iteration count can be specified at run time under program control as well as at assembly time.

4 Hardware Architecture (continued)

Data Arithmetic Unit (DAU)

The data arithmetic unit (DAU) contains a 16 x 16-bit parallel multiplier that generates a full 32-bit product in one instruction cycle. The product can be accumulated with one of two 36-bit accumulators. The accumulator data can be directly loaded from, or stored to, memory in two 16-bit words with optional saturation on overflow. The arithmetic logic unit (ALU) supports a full set of arithmetic and logical operations on either 16-bit or 32-bit data. A standard set of flags can be tested for conditional ALU operations, branches, and subroutine calls. This procedure allows the processor to perform as a powerful 16-bit or 32-bit microprocessor for logical and control applications. The available instruction set is fully compatible with the DSP1627 instruction set. See Section 5.1, Instruction Set, for more information on the instruction set.

The user also has access to two additional DAU registers. The psw register contains status information from the DAU (see Table 26, Processor Status Word (psw) Register). The arithmetic control register, auc, is used to configure some of the features of the DAU (see Table 27, Arithmetic Unit Control (auc) Register), including single-cycle squaring. The auc register alignment field supports an arithmetic shift left by one and left or right by two. The auc register is cleared by reset.

The counters c0 to c2 are signed, 8 bits wide, and may be used to count events such as the number of times the program has executed a sequence of code. They are controlled by the conditional instructions and provide a convenient method of program looping.

Y-Space Address Arithmetic Unit (YAAU)

The YAAU supports high-speed, register-indirect, compound, and direct addressing of data (Y) memory. Four general-purpose, 16-bit registers, r0 to r3, are available in the YAAU. These registers can be used to supply the read or write addresses for Y-space data. The YAAU also decodes the 16-bit data memory address and outputs individual memory enables for the data access. The YAAU can address the six 1 Kword banks of on-chip DPRAM or three external data memory segments. Up to 48 Kwords of off-chip RAM are addressable, with 16K addresses reserved for internal RAM.

Two 16-bit registers, rb and re, allow zero-overhead modulo addressing of data for efficient filter implementations. Two 16-bit signed registers, j and k, are used to hold user-defined postmodification increments. Fixed increments of +1, -1, and +2 are also available. Four compound-addressing modes are provided to make read/write operations more efficient.

The YAAU allows direct (or indexed) addressing of data memory. In direct addressing, the 16-bit base register (ybase) supplies the 11 most significant bits of the address. The direct data instruction supplies the remaining 5 bits to form an address to Y memory space and also specifies one of 16 registers for the source or destination.

X-Space Address Arithmetic Unit (XAAU)

The XAAU supports high-speed, register-indirect, instruction/coefficient memory addressing with postmodification of the register. The 16-bit pt register is used for addressing coefficients. The signed register i holds a user-defined postincrement. A fixed postincrement of +1 is also available. Register PC is the program counter. Registers pr and pi hold the return address for subroutine calls and interrupts, respectively.

The XAAU decodes the 16-bit instruction/coefficient address and produces enable signals for the appropriate X memory segment. The addressable X segments are 48 Kwords of internal ROM, up to 16 Kwords of DPRAM for the DSP1629x16 or up to 10 Kwords of DPRAM for the DSP1629x10, and external ROM.

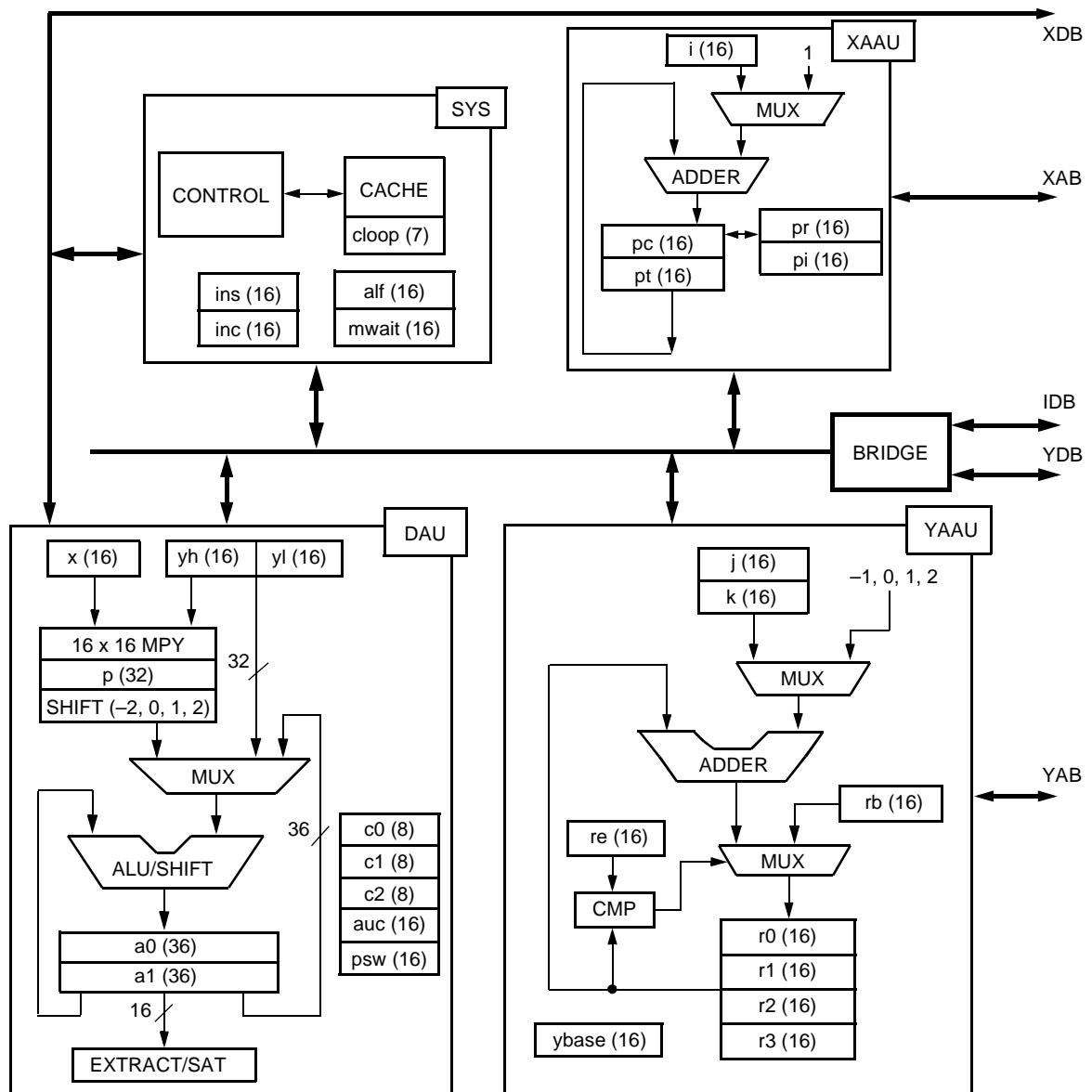
The locations of these memory segments depend upon the memory map selected (see Table 5, Instruction/Coefficient Memory Maps). A security mode can be selected by mask option. This prevents unauthorized access to the contents of on-chip ROM (see Section 7, Mask-Programmable Options).

4.3 Interrupts and Trap

The DSP1629 supports prioritized, vectored interrupts and a trap. The device has eight internal hardware sources of program interrupt and two external interrupt pins. Additionally, there is a trap pin and a trap signal from the hardware development system (HDS). A software interrupt is available through the ical instruction. The ical instruction is reserved for use by the HDS. Each of these sources of interrupt and trap has a unique vector address and priority assigned to it.

The software interrupt and the traps are always enabled and do not have a corresponding bit in the ins register. Other vectored interrupts are enabled in the inc register (see Table 29, Interrupt Control (inc) Register) and monitored in the ins register (see Table 30, Interrupt Status (ins) Register). When the DSP1629 goes into an interrupt or trap service routine, the IACK pin is asserted. In addition, pins VEC[3:0] encode which interrupt/trap is being serviced. Table 4, Interrupt Vector Table, details the encoding used for VEC[3:0].

4 Hardware Architecture (continued)



5-1741 (F).b

Figure 5. DSP1600 Core Block Diagram

4 Hardware Architecture (continued)

Table 3. DSP1600 Core Block Diagram Legend

Symbol	Name
16 x 16 MPY	16-bit x 16-bit Multiplier.
a0—a1	Accumulators 0 and 1 (16-bit halves specified as a0, a0l, a1, and a1l).*
alf	AWAIT, LOWPR, Flags.
ALU/SHIFT	Arithmetic Logic Unit/Shifter.
auc	Arithmetic Unit Control.
c0—c2	Counters 0—2.
cloop	Cache Loop Count.
CMP	Comparator.
DAU	Digital Arithmetic Unit.
i	Increment Register for the X Address Space.
IDB	Internal Data Bus.
inc	Interrupt Control.
ins	Interrupt Status.
j	Increment Register for the Y Address Space.
k	Increment Register for the Y Address Space.
MUX	Multiplexer.
mwait	External Memory Wait-states Register.
p	Product Register (16-bit halves specified as p, pl).
PC	Program Counter.
pi	Program Interrupt Return Register.
pr	Program Return Register.
psw	Processor Status Word.
pt	X Address Space Pointer.
r0—r3	Y Address Space Pointers.
rb	Modulo Addressing Register (begin address).
re	Modulo Addressing Register (end address).
SYS	System Cache and Control Section.
x	Multiplier Input Register.
XAAU	X-Space Address Arithmetic Unit.
XAB	X-Space Address Bus.
XDB	X-Space Data Bus.
YAAU	Y-Space Address Arithmetic Unit.
YAB	Y-Space Address Bus.
YDB	Y-Space Data Bus.
ybase	Direct Addressing Base Register.
y	DAU Register (16-bit halves specified as y, yl).

* F3 ALU instructions with immediates require specifying the high half of the accumulators as a0h and a1h.

4 Hardware Architecture (continued)

Interruptibility

Vectored interrupts are serviced only after the execution of an interruptible instruction. If more than one vectored interrupt is asserted at the same time, the interrupts are serviced sequentially according to their assigned priorities. See Table 4, Interrupt Vector Table, for the priorities assigned to the vectored interrupts. Interrupt service routines, branch and conditional branch instructions, cache loops, and instructions that only decrement one of the RAM pointers, r0 to r3 (e.g., *r3--), are not interruptible.

A trap is similar to an interrupt, but it gains control of the processor by branching to the trap service routine even when the current instruction is noninterruptible. It may not be possible to return to normal instruction execution from the trap service routine since the machine state cannot always be saved. In particular, program execution cannot be continued from a trapped cache loop or interrupt service routine. While in a trap service routine, another trap is ignored.

When set to 1, the status bits in the ins register indicate that an interrupt has occurred. The processor must reach an interruptible state (completion of an interruptible instruction) before an enabled vectored interrupt will be acted on. An interrupt will not be serviced if it is not enabled. Polled interrupt service can be implemented by disabling the interrupt in the inc register and then polling the ins register for the expected event.

Vectored Interrupts

Table 29, Interrupt Control (inc) Register, and Table 30, Interrupt Status (ins) Register, show the inc and ins registers, respectively. A logic 1 written to any bit of inc enables (or unmask) the associated interrupt. If the bit is cleared to a logic 0, the interrupt is masked. Note that neither the software interrupt nor traps can be masked.

The occurrence of an interrupt that is not masked will cause the program execution to transfer to the memory location pointed to by that interrupt's vector address, assuming no other interrupt is being serviced (see Table 4, Interrupt Vector Table). The occurrence of an interrupt that is masked causes no automatic processor action, but will set the corresponding status bit in the ins register. If a masked interrupt occurs, it is latched in the ins register, but the interrupt is not taken. When unlatched, this latched interrupt will initiate automatic processor interrupt action. See the *DSP1611/17/18/27/28/29 Digital Signal Processor Information Manual* for a more detailed description of the interrupts.

Signaling Interrupt Service Status

Five pins of DSP1629 are devoted to signaling interrupt service status. The IACK pin goes high while any interrupt or user trap is being serviced, and goes low when the ireturn instruction from the service routine is issued. Four pins, VEC[3:0], carry a code indicating which of the interrupts or trap is being serviced. Table 4, Interrupt Vector Table, contains the encodings used by each interrupt.

Traps due to HDS breakpoints have no effect on either the IACK or VEC[3:0] pins. Instead, they show the interrupt state or interrupt source of the DSP when the trap occurred.

Clearing Interrupts

The PHIF interrupts (PIBF and POBE) are cleared by reading or writing the parallel host interface data transmit registers pdx0[in] and pdx0[out], respectively. The SIO and SIO2 interrupts (IBF, IBF2, OBE, and OBE2) are cleared one instruction cycle AFTER reading or writing the serial data registers, (sdx[in], sdx2[in], sdx[out], or sdx2[out]). To account for this added latency, the user must ensure that a single instruction (NOP or any other valid DSP16XX instruction) follows the sdx register read or write instruction prior to exiting an interrupt service routine (via an ireturn or goto pi instruction) or before checking the ins register for the SIO flag status. Adding this instruction ensures that interrupts are not reported incorrectly following an ireturn or that stale flags are not read from the ins register. The JTAG interrupt (JINT) is cleared by reading the jtag register.

Three of the vectored interrupts are cleared by writing to the ins register. Writing a 1 to the INT0, INT1, or TIME bits in the ins will cause the corresponding interrupt status bit to be cleared to a logic 0. The status bit for these vectored interrupts is also cleared when the ireturn instruction is executed, leaving set any other vectored interrupts that are pending.

Traps

The TRAP pin of the DSP1629 is a bidirectional signal. At reset, it is configured as an input to the processor. Asserting the TRAP pin will force a user trap. The trap mechanism is used for two purposes. It can be used by an application to rapidly gain control of the processor for asynchronous time-critical event handling (typically for catastrophic error recovery). It is also used by the HDS for breakpointing and gaining control of the processor. Separate vectors are provided for the user trap (0x46) and the HDS trap (0x3). Traps are not maskable.

4 Hardware Architecture (continued)

Table 4. Interrupt Vector Table

Source	Vector	Priority	VEC[3:0]	Issued by
No Interrupt	—	—	0x0	—
Software Interrupt	0x2	1	0x1	icall
INT0	0x1	2	0x2	pin
JINT	0x42	3	0x8	jtag in
INT1	0x4	4	0x9	pin
TIME	0x10	7	0xc	timer
IBF2	0x14	8	0xd	SIO2 in
OBE2	0x18	9	0xe	SIO2 out
Reserved	0x1c	10	0x0	—
Reserved	0x20	11	0x1	—
Reserved	0x24	12	0x2	—
IBF	0x2c	14	0x3	SIO in
OBE	0x30	15	0x4	SIO out
PIBF	0x34	16	0x5	PHIF in
POBE	0x38	17	0x6	PHIF out
TRAP from HDS	0x3	18	—*	breakpoint, jtag, or pin
TRAP from User	0x46	19 = highest	0x7	pin

* Traps due to HDS breakpoints have no effect on VEC[3:0] pins.

A trap has four cycles of latency. At most, two instructions will execute from the time the trap is received at the pin to when it gains control. An instruction that is executing when a trap occurs is allowed to complete before the trap service routine is entered. (Note that the instruction could be lengthened by wait-states.) During normal program execution, the pi register contains either the address of the next instruction (two-cycle instruction executing), or the address following the next instruction (one-cycle instruction executing). In an interrupt service routine, pi contains the interrupt return address. When a trap occurs during an interrupt service routine, the value of the pi register may be overwritten. Specifically, it is not possible to return to an interrupt service routine from a user trap (0x46) service routine. Continuing program execution when a trap occurs during a cache loop is also not possible.

The HDS trap causes circuitry to force the program memory map to MAP1 (with on-chip ROM starting at address 0x0) when the trap is taken. The previous memory map is restored when the trap service routine exits by issuing an ireturn. The map is forced to MAP1 because the HDS code, if present, resides in the on-chip ROM.

Using the Agere Systems development tools, the TRAP pin may be configured to be an output, or an input vectoring to address 0x3. In a multiprocessor environment, the TRAP pins of all the DSPs present can be tied to-

gether. During HDS operations, one DSP is selected by the host software to be the master. The master processor's TRAP pin is configured to be an output.

The TRAP pins of the slave processors are configured as inputs. When the master processor reaches a breakpoint, the master's TRAP pin is asserted. The slave processors will respond to their TRAP input by beginning to execute the HDS code.

AWAIT Interrupt (Standby or Sleep Mode)

Setting the AWAIT bit (bit 15) of the alf register (alf = 0x8000) causes the processor to go into a power-saving standby or sleep mode. Only the minimum circuitry on the chip required to process an incoming interrupt remains active. After the AWAIT bit is set, one additional instruction will be executed before the standby power-saving mode is entered. A PHIF or SIO word transfer will complete if already in progress. The AWAIT bit is reset when the first interrupt occurs. The chip then wakes up and continues executing.

Two nop instructions should be programmed after the AWAIT bit is set. The first nop (one cycle) will be executed before sleeping; the second will be executed after the interrupt signal awakens the DSP and before the interrupt service routine is executed.

4 Hardware Architecture (continued)

The AWAIT bit should be set from within the cache if the code which is executing resides in external ROM where more than one wait-state has been programmed. This ensures that an interrupt will not disturb the device from completely entering the sleep state.

For additional power savings, set $ioc = 0x0180$ and $timerc = 0x0040$, in addition to setting $alf = 0x8000$. This will hold the CKO pin low and shut down the timer and prescaler (see Table 38, ioc Register, and Table 31, $timerc$ Register).

For a description of the control mechanisms for putting the DSP into low-power modes, see Section 4.13, Power Management.

4.4 Memory Maps and Wait-States

The DSP1600 core implements a modified Harvard architecture that has separate on-chip 16-bit address and data buses for the instruction/coefficient (X) and data (Y) memory spaces. Table 5, Instruction/Coefficient Memory Maps, shows the instruction/coefficient memory space maps for both the DSP1629x16 and DSP1629x10.

The DSP1629 provides a multiplexed external bus which accesses external RAM (ERAM) and ROM (EROM). Programmable wait-states are provided for external memory accesses. The instruction/coefficient memory map is configurable to provide application flexibility. Table 6, Data Memory Maps, shows the data memory space, which has one map.

Instruction/Coefficient Memory Map Selection

In determining which memory map to use, the processor evaluates the state of two parameters. The first is the LOWPR bit (bit 14) of the alf register. The LOWPR bit of the alf register is initialized to 0 automatically at reset. LOWPR controls the starting address in memory assigned to 1K banks of dual-port RAM. If LOWPR is low, internal dual-port RAM begins at address $0xC000$. If LOWPR is high, internal dual-port RAM begins at address $0x0$. LOWPR also moves IROM from $0x0$ in MAP1 to $0x4000$ in MAP3, and EROM from $0x0$ in MAP2 to $0x4000$ in MAP4.

The second parameter is the value of the EXM pin at reset (pin 27 or pin 14, depending upon the package type). EXM determines whether the internal 48 Kwords ROM (IROM) will be addressable in the memory map.

The Agere Systems development system tools, together with the on-chip HDS circuitry and the JTAG port, can independently set the memory map. Specifically, during

an HDS trap, the memory map is forced to MAP1. The user's map selection is restored when the trap service routine has completed execution.

MAP1

MAP1 has the IROM starting at $0x0$ and 1 Kword banks of DPRAM starting at $0xC000$. MAP1 is used if DSP1629 has EXM low at reset and the LOWPR parameter is programmed to zero. It is also used during an HDS trap.

MAP2

MAP2 differs from MAP1 in that the lowest 48 Kwords reference external ROM (EROM). MAP2 is used if EXM is high at reset, the LOWPR parameter is programmed to zero, and an HDS trap is not in progress.

MAP3

MAP3 has the 1 Kword banks of DPRAM, starting at address $0x0$. In MAP3, the 48 Kwords of IROM start at $0x4000$. MAP3 is used if EXM is low at reset, the LOWPR bit is programmed to 1, and an HDS trap is not in progress. Note that this map is not available if the secure mask-programmable option has been ordered.

MAP4

MAP4 differs from MAP3 in that addresses above $0x4000$ reference external ROM (EROM). This map is used if the LOWPR bit is programmed to 1, an HDS trap is not in progress, and, either EXM is high during reset, or the secure mask-programmable option has been ordered.

Whenever the chip is reset using the RSTB pin, the default memory map will be MAP1 or MAP2, depending upon the state of the EXM pin at reset. A reset through the HDS will not reinitialize the alf register, so the previous memory map is retained.

Boot from External ROM

After RSTB goes from low to high, the DSP1629 comes out of reset and fetches an instruction from address zero of the instruction/coefficient space. The physical location of address zero is determined by the memory map in effect. If EXM is high at the rising edge of RSTB, MAP2 is selected. MAP2 has EROM at location zero; thus, program execution begins from external memory. If EXM is high and INT1 is low when RSTB rises, the $mwait$ register defaults to 15 wait-states for all external memory segments. If INT1 is high, the $mwait$ register defaults to 0 wait-states.

4 Hardware Architecture (continued)

Table 5. Instruction/Coefficient Memory Maps

DSP1629x16

X Address	AB[0:15]	MAP 1* EXM = 0 LOWPR = 0 [†]	MAP 2 EXM = 1 LOWPR = 0	MAP 3 [‡] EXM = 0 LOWPR = 1	MAP 4 EXM = 1 LOWPR = 1
0	0x0000	IROM (48K)	EROM (48K)	DPRAM (16K)	DPRAM (16K)
4K	0x1000				
6K	0x1800				
12K	0x3000				
16K	0x4000				
20K	0x5000				
24K	0x6000				
28K	0x7000				
32K	0x8000				
36K	0x9000				
40K	0xA000				
44K	0xB000				
48K	0xC000	DPRAM (16K)	DPRAM (16K)	IROM (48K)	EROM (48K)
52K	0xD000				
54K	0xD800				
56K	0xE000				
60K—64K	0xFFFF				

DSP1629x10

X Address	AB[0:15]	MAP 1* EXM = 0 LOWPR = 0 [†]	MAP 2 EXM = 1 LOWPR = 0	MAP 3 [‡] EXM = 0 LOWPR = 1	MAP 4 EXM = 1 LOWPR = 1
0	0x0000	IROM (48K)	EROM (48K)	DPRAM (10K)	DPRAM (10K)
4K	0x1000				
6K	0x1800				
10K	0x2800				
12K	0x3000				
16K	0x4000				
20K	0x5000				
24K	0x6000				
28K	0x7000				
32K	0x8000				
36K	0x9000				
40K	0xA000				
44K	0xB000				
48K	0xC000	DPRAM (10K)	DPRAM (10K)	IROM (48K)	EROM (48K)
52K	0xD000				
54K	0xD800				
56K	0xE000				
58K	0xE800				
60K—64K	0xFFFF				
		Reserved (6K)	Reserved (6K)		

* MAP1 is set automatically during an HDS trap. The user-selected map is restored at the end of the HDS trap service routine.

[†] LOWPR is an alf register bit. The Agere Systems development system tools can independently set the memory map.

[‡] MAP3 is not available if the secure mask-programmable option is selected.

4 Hardware Architecture (continued)

Table 6. Data Memory Maps

1629x16 Data Memory Map (Not to Scale)

Decimal Address	Address in r0, r1, r2, r3	Segment
0	0x0000	DPRAM[1:16]
16K	0x4000	IO
16,640	0x4100	ERAMLO
32K	0x8000	ERAMHI
64K – 1	0xFFFF	

On the data memory side (see Table 6, Data Memory Maps), the 1K banks of dual-port RAM are located starting at address 0. Addresses from 0x4000 to 0x40FF reference a 256-word memory-mapped I/O segment (IO). Addresses from 0x4100 to 0x7FFF reference the low external data RAM segment (ERAMLO). Addresses above 0x8000 reference high external data RAM (ERAMHI).

1629x10 Data Memory Map (Not to Scale)

Decimal Address	Address in r0, r1, r2, r3	Segment
0	0x0000	DPRAM[1:10]
10K	0x2800	Reserved (6 K)
16K	0x4000	IO
16,640	0x4100	ERAMLO
32K	0x8000	ERAMHI
64K – 1	0xFFFF	

Wait-States

The number of wait-states (from 0 to 15) used when accessing each of the four external memory segments (ERAMLO, IO, ERAMHI, and EROM) is programmable in the mwait register (see Table 36, mwait Register). When the program references memory in one of the four external segments, the internal multiplexer is automatically switched to the appropriate set of internal buses, and the associated external enable of ERAMLO, IO, ERAMHI, or EROM is issued. The external memory cycle is automatically stretched by the number of wait-states configured in the appropriate field of the mwait register.

4 Hardware Architecture (continued)

4.5 External Memory Interface (EMI)

The external memory interface supports read/write operations from instruction/coefficient memory, data memory, and memory-mapped I/O devices. The DSP1629 provides a 16-bit external address bus, AB[15:0], and a 16-bit external data bus, DB[15:0]. These buses are multiplexed between the internal buses for the instruction/coefficient memory and the data memory. Four external memory segment enables, ERAMLO, IO, ERAMHI, and EROM, select the external memory segment to be addressed.

If a data memory location with an address between 0x4100 and 0x7FFF is addressed, ERAMLO is asserted low.

If one of the 256 external data memory locations, with an address greater than or equal to 0x4000, and less than or equal to 0x40FF, is addressed, IO is asserted low. IO is intended for memory-mapped I/O.

If a data memory location with an address greater than or equal to 0x8000 is addressed, ERAMHI is asserted low. When the external instruction/coefficient memory is addressed, EROM is asserted low.

The flexibility provided by the programmable options of the external memory interface (see Table 36, mwait Register, and Table 38, ioc Register) allows the DSP1629 to interface gluelessly with a variety of commercial memory chips.

Each of the four external memory segments, ERAMLO, IO, ERAMHI, and EROM, has a number of wait-states that is programmable (from 0 to 15) by writing to the mwait register. When the program references memory in one of the four external segments, the internal multiplexer is automatically switched to the appropriate set of internal buses, and the associated external enable of ERAMLO, IO, ERAMHI, or EROM is issued. The external memory cycle is automatically stretched by the number of wait-states in the appropriate field of the mwait register.

When writing to external memory, the RWN pin goes low for the external cycle. The external data bus, DB[15:0], is driven by the DSP1629, starting halfway through the cycle. The data driven on the external data bus is automatically held after the cycle for one additional clock period unless an external read cycle immediately follows.

The DSP1629 has one external address bus and one external data bus for both memory spaces. Since some instructions provide the capability of simultaneous access to both X space and Y space, some provision must be made to avoid collisions for external accesses. The DSP1629 has a sequencer that does the external X ac-

cess first, and then the external Y access, transparently to the programmer. Wait-states are maintained as programmed in the mwait register. For example, let two instructions be executed: the first reads a coefficient from EROM and writes data to ERAM; the second reads a coefficient from EROM and reads data from ERAM. The sequencer carries out the following steps at the external memory interface: read EROM, write ERAM, read EROM, and read ERAM. Each step is done in sequential one-instruction cycle steps, assuming zero wait-states are programmed. Note that the number of instruction cycles taken by the two instructions is four. Also, in this case, the write hold time is zero.

The DSP1629 allows writing into external instruction/coefficient memory. By setting bit 11, WEROM, of the ioc register (see Table 38, ioc Register), writing to (or reading from) data memory or memory-mapped I/O asserts the EROM strobe instead of ERAMLO, IO, or ERAMHI. Therefore, with WEROM set, EROM appears in both Y space (replacing ERAM) and X space, in its normal position.

Bit 14 of the ioc register (see Table 38, ioc Register), EXTROM, may be used with WEROM to download to a full 64K of external memory. When WEROM and EXTROM are both asserted, address bit 15 (AB15) is held low, aliasing the upper 32K of external memory into the lower 32K.

When an access to internal memory is made, the AB[15:0] bus holds the last valid external memory address. Asserting the RSTB pin low 3-states the AB[15:0] bus. After reset, the AB[15:0] value is undefined.

The leading edge of the memory segment enables can be delayed by approximately one-half a CKO period by programming the ioc register (see Table 38, ioc Register). This is used to avoid a situation in which two devices drive the data bus simultaneously.

Bits 7, 8, and 13 of the ioc register select the mode of operation for the CKO pin (see Table 38, ioc Register). Available options are a free-running unstretched clock, a wait-stated sequenced clock (runs through two complete cycles during a sequenced external memory access), and a wait-stated clock based on the internal instruction cycle. These clocks drop to the low-speed internal ring oscillator when SLOWCKI is enabled (see Section 4.13, Power Management). The high-to-low transitions of the wait-stated clock are synchronized to the high-to-low transition of the free-running clock. Also, the CKO pin provides either a continuously high level, a continuously low level, or changes at the rate of the internal processor clock. This last option, only available with the small-signal input clock options, enables the DSP1629 CKI input buffer to deliver a full-rate clock to other devices while the DSP1629 itself is in one of the low-power modes.

4 Hardware Architecture (continued)

4.6 Bit Manipulation Unit (BMU)

The BMU interfaces directly to the main accumulators in the DAU, providing the following features:

- Barrel shifting—logical and arithmetic, left and right shift
- Normalization and extraction of exponent
- Bit-field extraction and insertion

These features increase the efficiency of the DSP in applications such as control or data encoding and decoding. For example, data packing and unpacking, in which short data words are packed into one 16-bit word for more efficient memory storage, is very easy.

In addition, the BMU provides two auxiliary accumulators, aa0 and aa1. In one instruction cycle, 36-bit data can be shuffled, or swapped, between one of the main accumulators and one of the alternate accumulators. The ar<0—3> registers are 16-bit registers that control the operations of the BMU. They store a value that determines the amount of shift or the width and offset fields for bit extraction or insertion. Certain operations in the BMU set flags in the DAU psw register and the alf register (see Table 26, Processor Status Word (psw) Register, and Table 35, alf Register). The ar<0—3> registers can also be used as general-purpose registers.

The BMU instructions are detailed in Section 5.1, Instruction Set. For a thorough description of the BMU, see the *DSP1611/17/18/27/28/29 Digital Signal Processor Information Manual*.

4.7 Serial I/O Units (SIOs)

The serial I/O ports on the DSP1629 device provide a serial interface to many codecs and signal processors with little, if any, external hardware required. Each high-speed, double-buffered port (sdx and sdx2) supports back-to-back transmissions of data. SIO and SIO2 are identical. The output buffer empty (OBE and OBE2) and input buffer full (IBF and IBF2) flags facilitate the reading and/or writing of each serial I/O port by program-driven or interrupt-driven I/O. There are four selectable active clock speeds.

A bit-reversal mode provides compatibility with either the most significant bit (MSB) first or least significant bit (LSB) first serial I/O formats (see Table 22, Serial I/O Control Registers). A multiprocessor I/O configuration is supported. This feature allows up to eight DSP161X devices to be connected together on an SIO port without requiring external glue logic.

The serial data may be internally looped back by setting the SIO loopback control bit, SIOLBC, of the ioc register. SIOLBC affects both the SIO and SIO2. The data output

signals are wrapped around internally from the output to the input (DO1 to DI1 and DO2 to DI2). To exercise loopback, the SIO clocks (ICK1, ICK2, OCK1, and OCK2) should either all be in the active mode, 16-bit condition, or each pair should be driven from one external source in passive mode. Similarly, pins ILD1 (ILD2) and OLD1 (OLD2) must both be in active mode or tied together and driven from one external frame clock in passive mode. During loopback, DO1, DO2, DI1, DI2, ICK1, ICK2, OCK1, OCK2, ILD1, ILD2, OLD1, OLD2, SADD1, SADD2, SYNC1, SYNC2, DOEN1, and DOEN2 are 3-stated.

Setting DODLY = 1 (sioc and sioc2) delays DO by one phase of OCK so that DO changes on the falling edge of OCK instead of the rising edge (DODLY = 0). This reduces the time available for DO to drive DI and to be valid for the rising edge of ICK, but increases the hold time on DO by half a cycle on OCK.

Programmable Modes

Programmable modes of operation for the SIO and SIO2 are controlled by the serial I/O control registers (sioc and sioc2). These registers, shown in Table 22, Serial I/O Control Registers, are used to set the ports into various configurations. Both input and output operations can be independently configured as either active or passive. When active, the DSP1629 generates load and clock signals. When passive, load and clock signal pins are inputs.

Since input and output can be independently configured, each SIO has four different modes of operation. Each of the sioc registers is also used to select the frequency of active clocks for that SIO. Finally, these registers are used to configure the serial I/O data formats. The data can be 8 bits or 16 bits long, and can also be input/output MSB first or LSB first. Input and output data formats can be independently configured.

Multiprocessor Mode

The multiprocessor mode allows up to eight devices that support multiprocessor mode (codecs or DSP16XX devices) to be connected together to provide data transmission among any of the multiprocessor devices in the system. Either of the DSP1629's SIO ports (SIO or SIO2) may be independently used for the multiprocessor mode. The multiprocessor interface is a four-wire interface, consisting of a data channel, an address/protocol channel, a transmit/receive clock, and a sync signal (see Figure 6, Multiprocessor Communication and Connections). The DI1 and DO1 pins of all the DSPs are connected to transmit and receive the data channel. The SADD1 pins of all the DSPs are connected to transmit and receive the address/protocol channel. ICK1 and OCK1 should be tied together and driven from one source. The SYNC1 pins of all the DSPs are connected.

4 Hardware Architecture (continued)

In the configuration shown in Figure 6, Multiprocessor Communication and Connections, the master DSP (DSP0) generates active SYNC1 and OCK1 signals while the slave DSPs use the SYNC1 and OCK1 signals in passive mode to synchronize operations. In addition, all DSPs must have their ILD1 and OLD1 signals in active mode.

While ILD1 and OLD1 are not required externally for multiprocessor operation, they are used internally in the DSP's SIO. Setting the LD field of the master's sioc register to a logic level 1 will ensure that the active generation of SYNC1, ILD1, and OLD1 is derived from OCK1 (see Table 22, Serial I/O Control Registers). With this configuration, all DSPs should use ICK1 (tied to OCK1) in passive mode to avoid conflicts on the clock (CK) line (see the *DSP1611/17/18/27/28/29 Digital Signal Processor* Information Manual for more information).

Four registers (per SIO) configure the multiprocessor mode: the time-division multiplexed slot register (tdms or tdms2), the serial receive and transmit address register (srta or srta2), the serial data transmit register (sdx or sdx2), and the multiprocessor serial address/protocol register (saddx or saddx2).

Multiprocessor mode requires no external logic and uses a TDM interface with eight 16-bit time slots per frame. The transmission in any time slot consists of 16 bits of serial data in the data channel and 16 bits of address and protocol information in the address/protocol channel. The address information consists of the transmit address field of the srta register of the transmitting device. The address information is transmitted concurrently with the transmission of the first 8 bits of data. The protocol information consists of the transmit protocol field written to the saddx register and is transmitted concurrently with the last 8 bits of data (see Table 25, Multiprocessor Protocol Registers). Data is received or recognized by other DSP(s) whose receive address matches the address in the address/protocol channel. Each SIO port has a user-programmable receive address and transmit address associated with it. The transmit and receive addresses are programmed in the srta register.

In multiprocessor mode, each device can send data in a unique time slot designated by the tdms register transmit slot field (bits 7—0). The tdms register has a fully decoded transmit slot field in order to allow one DSP1629 device to transmit in more than one time slot. This procedure is useful for multiprocessor systems with less than eight DSP1629 devices when a higher bandwidth is necessary between certain devices in that system. The DSP operating during time slot 0 also drives SYNC1.

In order to prevent multiple bus drivers, only one DSP can be programmed to transmit in a particular time slot. In addition, it is important to note that the address/protocol channel is 3-stated in any time slot that is not being driven.

Therefore, to prevent spurious inputs, the address/protocol channel should be pulled up to VDD with a 5 k Ω resistor, or it should be guaranteed that the bus is driven in every time slot. (If the SYNC1 signal is externally generated, then this pull-up is required for correct initialization.)

Each SIO also has a fully decoded transmitting address specified by the srta register transmit address field (bits 7—0). This is used to transmit information regarding the destination(s) of the data. The fully decoded receive address specified by the srta register receive address field (bits 15—8) determines which data will be received.

The SIO protocol channel data is controlled via the saddx register. When the saddx register is written, the lower 8 bits contain the 8-bit protocol field. On a read, the high-order 8 bits read from saddx are the most recently received protocol field sent from the transmitting DSP's saddx output register. The low-order 8 bits are read as 0s.

An example use of the protocol channel is to use the top 3 bits of the saddx value as an encoded source address for the DSPs on the multiprocessor bus. This leaves the remaining 5 bits available to convey additional control information, such as whether the associated field is an opcode or data, or whether it is the last word in a transfer, etc. These bits can also be used to transfer parity information about the data. Alternatively, the entire field can be used for data transmission, boosting the bandwidth of the port by 50%.

Using SIO2

The SIO2 functions the same as the SIO. Please refer to the Pin Multiplexing section for a description of pin multiplexing of BIO, PHIF, VEC[3:0], and SIO2.

4 Hardware Architecture (continued)

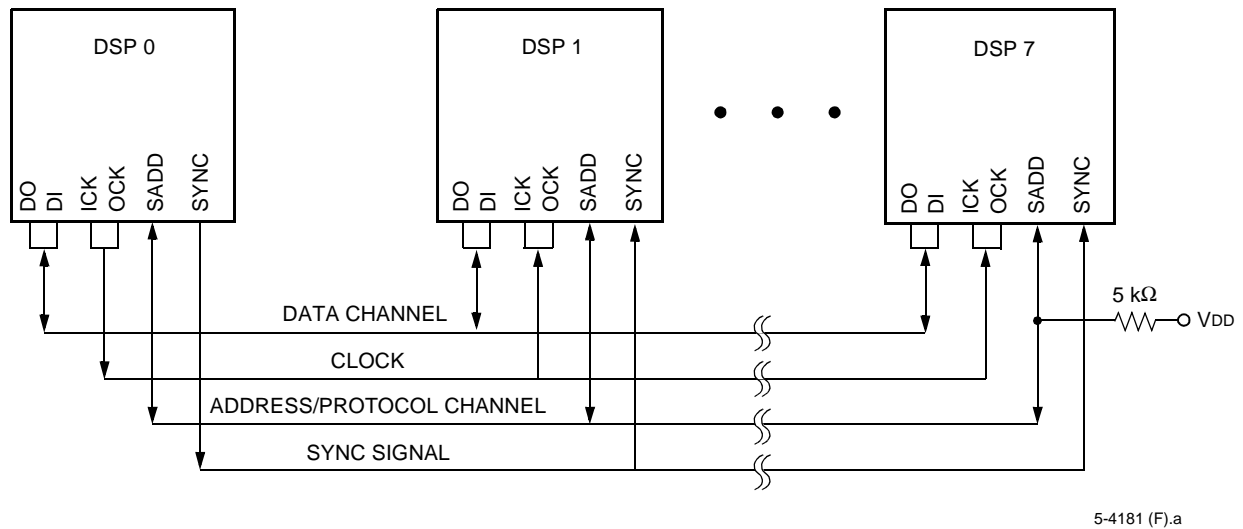


Figure 6. Multiprocessor Communication and Connections

4.8 Parallel Host Interface (PHIF)

The DSP1629 has an 8-bit parallel host interface for rapid transfer of data with external devices. This parallel port is passive (data strobes provided by an external device) and supports either *Motorola* or *Intel* microcontroller protocols. The PHIF also provides for 8-bit or 16-bit data transfers. As a flexible host interface, it requires little or no glue logic to interface to other devices (e.g., microcontrollers, microprocessors, or another DSP).

The data path of the PHIF consists of a 16-bit input buffer, *pdx0(in)*, and a 16-bit output buffer, *pdx0(out)*. Two output pins, parallel input buffer full (PIBF) and parallel output buffer empty (POBE), indicate the state of the buffers. In addition, there are two registers used to control and monitor the PHIF's operation: the parallel host interface control register (*phifc*, see Table 28, Parallel Host Interface Control (*phifc*) Register), and the PHIF status register (*PSTAT*, see Table 8, *pstat* Register as Seen on PB[7:0]). The *PSTAT* register, which reflects the state of the PIBF and POBE flags, can only be read by an external device when the *PSTAT* input pin is asserted. The *phifc* register defines the programmable options for this port.

The function of the pins, PIDS and PODS, is programmable to support both the *Intel* and *Motorola* protocols. The pin, PCSN, is an input that, when low, enables PIDS and PODS (or PRWN and PDS, depending on the protocol used). While PCSN is high, the DSP1629 ignores any activity on PIDS and/or PODS. If a DSP1629 is intended to be continuously accessed through the

PHIF port, PCSN should be grounded. If PCSN is low and the respective bits in the *inc* register are set, the assertion of PIDS and PODS by an external device causes the DSP1629 device to recognize an interrupt.

Programmability

The parallel host interface can be programmed for 8-bit or 16-bit data transfers using bit 0, *PMODE*, of the *phifc* register. Setting *PMODE* selects 16-bit transfer mode. An input pin controlled by the host, *PBSEL*, determines an access of either the high or low bytes. The assertion level of the *PBSEL* input pin is configurable in software using bit 3 of the *phifc* register, *PBSELF*. Table 7, PHIF Function (8-bit and 16-bit Modes), summarizes the port's functionality as controlled by the *PSTAT* and *PBSEL* pins and the *PBSELF* and *PMODE* fields.

For 16-bit transfers, if *PBSELF* is zero, the PIBF and POBE flags are set after the high byte is transferred. If *PBSELF* is one, the flags are set after the low byte is transferred. In 8-bit mode, only the low byte is accessed, and every completion of an input or output access sets PIBF or POBE.

Bit 1 of the *phifc* register, *PSTROBE*, configures the port to operate either with an *Intel* protocol, where only the chip select (*PCSN*) and either of the data strobes (*PIDS* or *PODS*) are needed to make an access, or with a *Motorola* protocol, where the chip select (*PCSN*), a data strobe (*PDS*), and a read/write strobe (*PRWN*) are needed. PIDS and PODS are negative assertion data strobes while the assertion level of *PDS* is programmable through bit 2, *PSTRB*, of the *phifc* register.

4 Hardware Architecture (continued)

Finally, the assertion level of the output pins, PIBF and POBE, is controlled through bit 4, PFLAG. When PFLAG is set low, PIBF and POBE output pins have positive assertion levels. By setting bit 5, PFLAGSEL, the logical OR of PIBF and POBE flags (positive assertion) is seen at the output pin PIBF. By setting bit 7 in phifc, PSOBEF, the polarity of the POBE flag in the status register, PSTAT, can be changed. PSOBEF has no effect on the POBE pin.

Pin Multiplexing

Please refer to the Pin Multiplexing section for a description of BIO, PHIF, VEC[3:0], and SIO2 pins.

Table 7. PHIF Function (8-bit and 16-bit Modes)

PMODE Field	PSTAT Pin	PBSEL Pin	PBSELF Field = 0	PBSELF Field = 1
0 (8-bit)	0	0	pdx0 low byte	reserved
0	0	1	reserved	pdx0 low byte
0	1	0	PSTAT	reserved
0	1	1	reserved	PSTAT
1 (16-bit)	0	0	pdx0 low byte	pdx0 high byte
1	0	1	pdx0 high byte	pdx0 low byte
1	1	0	PSTAT	reserved
1	1	1	reserved	PSTAT

Table 8. pstat Register as Seen on PB[7:0]

Bit	7	6	5	4	3	2	1	0
Field	RSVD						PIBF	POBE

4.9 Bit Input/Output Unit (BIO)

The BIO controls the directions of eight bidirectional control I/O pins, IOBIT[7:0]. If a pin is configured as an output, it can be individually set, cleared, or toggled. If a pin is configured as an input, it can be read and/or tested.

The lower half of the sbits register (see Table 33, sbits Register) contains current values (VALUE[7:0]) of the eight bidirectional pins IOBIT[7:0]. The upper half of the sbits register (DIREC[7:0]) controls the direction of each of the pins. A logic 1 configures the corresponding pin as an output; a logic 0 configures it as an input. The upper half of the sbits register is cleared upon reset.

The cbit register (see Table 34, cbit Register) contains two 8-bit fields: MODE/MASK[7:0] and DATA/PAT[7:0]. The values of DATA/PAT[7:0] are cleared upon reset. The meaning of a bit in either field depends on whether it has been configured as an input or an output in sbits. If a pin has been configured to be an output, the meanings are MODE and DATA. For an input, the meanings are MASK and PAT (pattern). Table 9, BIO Operations, shows the functionality of the MODE/MASK and DATA/PAT bits based on the direction selected for the associated IOBIT pin.

Those bits that have been configured as inputs can be individually tested for 1 or 0. For those inputs that are being tested, there are four flags produced: allt (all true),

allf (all false), somet (some true), and somef (some false). These flags can be used for conditional branch or special instructions. The state of these flags can be saved and restored by reading and writing bits 0 to 3 of the alf register (see Table 35, alf Register).

Table 9. BIO Operations

DIREC[n]*	MODE/MASK[n]	DATA/PAT[n]	Action
1 (Output)	0	0	Clear
1 (Output)	0	1	Set
1 (Output)	1	0	No Change
1 (Output)	1	1	Toggle
0 (Input)	0	0	No Test
0 (Input)	0	1	No Test
0 (Input)	1	0	Test for Zero
0 (Input)	1	1	Test for One

* $0 \leq n \leq 7$.

If a BIO pin is switched from being configured as an output to being configured as an input and then back to being configured as an output, the pin retains the previous output value.

Pin Multiplexing

Please refer to the Pin Multiplexing section for a description of BIO, PHIF, VEC[3:0], and SIO2 pins.

4 Hardware Architecture (continued)

4.10 Timer

The interrupt timer is composed of the timerc (control) register, the timer0 register, the prescaler, and the counter itself. The timer control register (see Table 31, timerc Register) sets up the operational state of the timer and prescaler. The timer0 register is used to hold the counter reload value (or period register) and to set the initial value of the counter. The prescaler slows the clock to the timer by a number of binary divisors to allow for a wide range of interrupt delay periods.

The counter is a 16-bit down counter that can be loaded with an arbitrary number from software. It counts down to 0 at the clock rate provided by the prescaler. Upon reaching 0 count, a vectored interrupt to program address 0x10 is issued to the DSP1629, providing the interrupt is enabled (bit 8 of inc and ins registers). The counter will then either wait in an inactive state for another command from software, or will automatically repeat the last interrupting period, depending upon the state of the RELOAD bit in the timerc register.

When RELOAD is 0, the counter counts down from its initial value to 0, interrupts the DSP1629, and then stops, remaining inactive until another value is written to the timer0 register. Writing to the timer0 register causes both the counter and the period register to be written with the specified 16-bit number. When RELOAD is 1, the counter counts down from its initial value to 0, interrupts the DSP1629, automatically reloads the specified initial value from the period register into the counter, and repeats indefinitely. This provides for either a single timed interrupt event or a regular interrupt clock of arbitrary period.

The timer can be stopped and started by software, and can be reloaded with a new period at any time. Its count value, at the time of the read, can also be read by software. Due to pipeline stages, stopping and starting the timer may result in one inaccurate count or prescaled period. When the DSP1629 is reset, the bottom 6 bits of the timerc register and the timer0 register and counter are initialized to 0. This sets the prescaler to $CKO/2^*$, turns off the reload feature, disables timer counting, and initializes the timer to its inactive state. The act of resetting the chip does not cause a timer interrupt. Note that the period register is not initialized on reset.

The T0EN bit of the timerc register enables the clock to the timer. When T0EN is a 1, the timer counts down towards 0. When T0EN is a 0, the timer holds its current count.

* Frequency of $CKO/2$ is equivalent to either $CKI/2$ for the PLL bypassed or related to CKI by the PLL multiplying factors. See Section 4.12, Clock Synthesis.

The PRESCALE field of the timerc register selects one of 16 possible clock rates for the timer input clock (see Table 31, timerc Register).

Setting the DISABLE bit of the timerc register to a logic 1 shuts down the timer and the prescaler for power savings. Setting the TIMERDIS, bit 4, in the powerc register has the same effect of shutting down the timer. The DISABLE bit and the TIMERDIS bit are cleared by writing a 0 to their respective registers to restore the normal operating mode.

4.11 JTAG Test Port

The DSP1629 uses a JTAG/IEEE 1149.1 standard five-wire test port (TDI, TDO, TCK, TMS, TRST) for self-test and hardware emulation. An instruction register, a boundary-scan register, a bypass register, and a device identification register have been implemented. The device identification register coding for the DSP1629 is shown in Table 37, DSP1629 32-Bit JTAG ID Register. The instruction register (IR) is 4 bits long. The instruction for accessing the device ID is 0xE (1110). The behavior of the instruction register is summarized in Table 10, JTAG Instruction Register. Cell 0 is the LSB (closest to TDO).

Table 10. JTAG Instruction Register

IR Cell #:	3	2	1	0
Parallel Input?	Y	Y	N	N
Always Logic 1?	N	N	N	Y
Always Logic 0?	N	N	Y	N

The first line shows the cells in the IR that capture from a parallel input in the capture-IR controller state. The second line shows the cells that always load a logic 1 in the capture-IR controller state. The third line shows the cells that always load a logic 0 in the capture-IR controller state. Cell 3 (MSB of IR) is tied to status signal PINT, and cell 2 is tied to status signal JINT. The state of these signals can therefore be captured during capture-IR and shifted out during SHIFT-IR controller states.

Boundary-Scan Register

All of the chip's inputs and outputs are incorporated in a JTAG scan path shown in Table 11, JTAG Boundary-Scan Register. The types of boundary-scan cells are as follows:

- I = input cell
- O = 3-state output cell
- B = bidirectional (I/O) cell
- OE = 3-state control cell
- DC = bidirectional control cell

4 Hardware Architecture (continued)

Note that the direction of shifting is from TDI to cell 104 to cell 103 . . . to cell 0 of TDO.

Table 11. JTAG Boundary-Scan Register

Cell	Type	Signal Name/Function	Cell	Type	Signal Name/Function
0	OE	Controls cells 1, 27—31	69	B	OCK2/PCSN*
1	O	CKO	70	DC	Controls cell 71
2	I	RSTB	71	B	DO2/PSTAT*
3	DC	Controls cell 4	72	DC	Controls cell 73
4	B	TRAP	73	B	SYNC2/PBSEL*
5	I	STOP†	74	DC	Controls cell 75
6	O	IACK	75	B	ILD2/PIDS*
7	I	INT0	76	DC	Controls cell 77
8	OE	Controls cells 6, 10—25, 49, 50, 78, 79	77	B	OLD2/PODS*
9	I	INT1	78	O	IBF2/PIBF*
10—25	O	AB[0:15]	79	O	OBE2/POBE*
26	I	EXM	80	DC	Controls cell 81
27	O	RWN	81	B	ICK2/PB0*
28—31	O	EROM, ERAMLO, ERAMHI, IO	82	DC	Controls cell 83
32—36	B	DB[0:4]	83	B	DI2/PB1*
37	DC	Controls cells 32—36, 38—48	84	DC	Controls cell 85
38—48	B	DB[5:15]	85	B	DOEN2/PB2*
49	O	OBE1	86	DC	Controls cell 87
50	O	IBF1	87	B	SADD2/PB3*
51	I	DI1	88	DC	Controls cell 89
52	DC	Controls cell 53	89	B	IOBIT0/PB4*
53	B	ILD1	90	DC	Controls cell 91
54	DC	Controls cell 55	91	B	IOBIT1/PB5*
55	B	ICK1	92	DC	Controls cell 93
56	DC	Controls cell 57	93	B	IOBIT2/PB6*
57	B	OCK1	94	DC	Controls cell 95
58	DC	Controls cell 59	95	B	IOBIT3/PB7*
59	B	OLD1	96	DC	Controls cell 97
60	OE	Controls cell 61	97	B	VEC3/IOBIT4*
61	O	DO1	98	DC	Controls cell 99
62	DC	Controls cell 63	99	B	VEC2/IOBIT5*
63	B	SYNC1	100	DC	Controls cell 101
64	DC	Controls cell 65	101	B	VEC1/IOBIT6*
65	B	SADD1	102	DC	Controls cell 103
66	DC	Controls cell 67	103	B	VEC0/IOBIT7*
67	B	DOEN1	104	I	CKI‡
68	DC	Controls cell 69	—	—	—

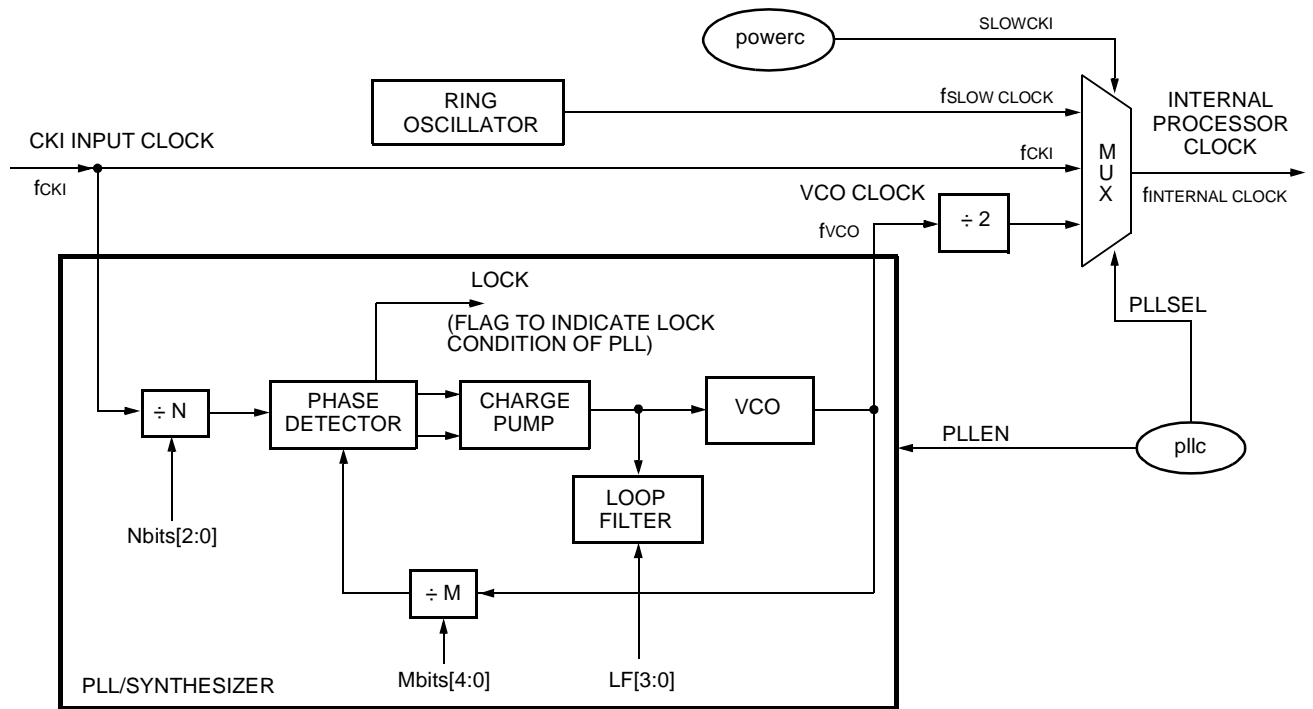
* Please refer to the Pin Multiplexing section for a description of pin multiplexing of BIO, PHIF, VEC[3:0], and SIO2.

† Note that shifting a zero into this cell in the mode to scan a zero into the chip will disable the processor clocks just as the STOP pin will.

‡ When the JTAG SAMPLE instruction is used, this cell will have a logic one regardless of the state of the pin.

4 Hardware Architecture (continued)

4.12 Clock Synthesis



5-4520 (F)

Figure 7. Clock Source Block Diagram

The DSP1629 provides an on-chip, programmable clock synthesizer. Figure 7, Clock Source Block Diagram, is the clock source diagram. The 1X CKI input clock, the output of the synthesizer, or a slow internal ring oscillator can be used as the source for the internal DSP clock. The clock synthesizer is based on a phase-locked loop (PLL), and the terms clock synthesizer and PLL are used interchangeably.

On powerup, CKI is used as the clock source for the DSP. This clock is used to generate the internal processor clocks and CKO, where $f_{CKI} = f_{CKO}$. Setting the appropriate bits in the pllcr control register (described in Table 32, Phase-Locked Loop Control (pllcr) Register) will enable the clock synthesizer to become the clock source. The powercr register, which is discussed in Section 4.13, Power Management, can override the selection to stop clocks or force the use of the slow clock for low-power operation.

PLL Control Signals

The input to the PLL comes from one of the three mask-programmable clock options: CMOS or small-signal. The PLL cannot operate without an external input clock.

To use the PLL, the PLL must first be allowed to stabilize and lock to the programmed frequency. After the PLL has locked, the LOCK flag is set and the lock detect circuitry is disabled. The synthesizer can then be used as the clock source. Setting the PLLSEL bit in the pllcr register will switch sources from f_{CKI} to $f_{VCO}/2$ without glitching. It is important to note that the setting of the pllcr register must be maintained. Otherwise, the PLL will seek the new set point. Every time the pllcr register is written, the LOCK flag is reset.

4 Hardware Architecture (continued)

The frequency of the PLL output clock, f_{VCO} , is determined by the values loaded into the 3-bit N divider and the 5-bit M divider. When the PLL is selected and locked, the frequency of the internal processor clock is related to the frequency of CKI by the following equations:

$$f_{VCO} = f_{CKI} * M/N$$

$$f_{INTERNAL\ CLOCK} = f_{CKO} = f_{VCO} + 2$$

The frequency of the VCO, f_{VCO} , must fall within the range listed in Table 63, PLL Electrical Specifications, VCO Frequency Ranges. Also note that f_{VCO} must be at least twice f_{CKI} .

The coding of the Mbits and Nbits is described as follows:

$$Mbits = M - 2$$

$$\text{if } (N = 1)$$

$$Nbits = 0x7$$

else

$$Nbits = N - 2$$

where N ranges from 1 to 8 and M ranges from 2 to 20.

The loop filter bits LF[3:0] should be programmed according to Table 64, PLL Electrical Specifications and pllC Register Settings.

Two other bits in the pllC register control the PLL. Clearing the PLLLEN bit powers down the PLL; setting this bit powers up the PLL. Clearing the PLLSEL bit deselects the PLL so that the DSP is clocked by a 1X version of the CKI input; setting the PLLSEL bit selects the PLL-generated clock for the source of the DSP internal processor clock. The pllC register is cleared on reset and powerup. Therefore, the DSP comes out of reset with the PLL deselected and powered down. M and N should be changed only while the PLL is deselected. The values of M and N should not be changed when powering down or deselecting the PLL.

As previously mentioned, the PLL also provides a user flag, LOCK, to indicate when the loop has locked. When this flag is not asserted, the PLL output is unstable. The DSP should not be switched to the PLL-based clock without first checking that the lock flag is set. The lock flag is cleared by writing to the pllC register. When the PLL is deselected, it is necessary to wait for the PLL to relock before the DSP can be switched to the PLL-based clock. Before the input clock is stopped, the PLL should be powered down. Otherwise, the LOCK flag will not be reset and there may be no way to determine if the PLL is stable, once the input clock is applied again.

The lock-in time depends on the frequency of operation and the values programmed for M and N (see Table 64, PLL Electrical Specifications and pllC Register Settings).

4 Hardware Architecture (continued)

PLL Programming Examples

The following section of code illustrates how the PLL would be initialized on powerup, assuming the following operating conditions:

- CKI input frequency = 10 MHz
- Internal clock and CKO frequency = 50 MHz
- VCO frequency = 100 MHz
- Input divide down count $N = 2$ (Set **Nbits[2:0]** = 000 to get $N = 2$, as described in Table 32, Phase-Locked Loop Control (pllcr) Register.)
- Feedback down count $M = 20$ (Set **Mbits[4:0]** = 10010 to get $M = 18 + 2 = 20$, as described in Table 32, Phase-Locked Loop Control (pllcr) Register.)

The device would come out of reset with the PLL disabled and deselected.

```
pllinit: pllcr = 0x2912 /* Running CKI input clock at 10 MHz, set up counters in PLL */
        pllcr = 0xA912 /* Power on PLL, but PLL remains deselected */
        call pllwait /* Loop to check for LOCK flag assertion */
        pllcr = 0xE912 /* Select high-speed, PLL clock */
        goto start /* User's code, now running at 50 MHz */
pllwait: if lock return
        goto pllwait
```

Programming examples which illustrate how to use the PLL with the various power management modes are listed in Section 4.13, Power Management.

Latency

The switch between the CKI-based clock and the PLL-based clock is synchronous. This method results in the actual switch taking place several cycles after the PLLSEL bit is changed. During this time, actual code can be executed, but it will be at the previous clock rate. Table 12, Latency Times for Switching Between CKI and PLL-Based Clocks, shows the latency times for switching between CKI-based and PLL-based clocks. In the example given, the delay to switch to the PLL source is 1—4 CKO cycles, and to switch back is 11—31 CKO cycles.

Table 12. Latency Times for Switching Between CKI and PLL-Based Clocks

	Minimum Latency (Cycles)	Maximum Latency (Cycles)
Switch to PLL-Based Clock	1	$N + 2$
Switch from PLL-Based Clock	$M/N + 1$	$M + M/N + 1$

Frequency Accuracy and Jitter

When using the PLL to multiply the input clock frequency up to the instruction clock rate, it is important to realize that although the average frequency of the internal clock and CKO will have about the same relative accuracy as the input clock, noise sources within the DSP will produce jitter on the PLL clock so that each individual clock period will have some error associated with it. The PLL is guaranteed only to have sufficiently low jitter to operate the DSP, and thus, this clock should not be used as an input to jitter-sensitive devices in the system.

VDDA and VSSA Connections

The PLL has its own power and ground pins, VDDA and VSSA. Additional filtering should be provided for VDDA in the form of a ferrite bead connected from VDDA to VDD and two decoupling capacitors (4.7 μ F tantalum in parallel with a 0.01 μ F ceramic) from VDDA to VSS. VSSA can be connected directly to the main ground plane. This recommendation is subject to change and may need to be modified for specific applications, depending on the characteristics of the supply noise.

Note: For devices with the CMOS clock input option, the CKI2 pin should be connected to VSSA.

4 Hardware Architecture (continued)

4.13 Power Management

There are three different control mechanisms for putting the DSP1629 into low-power modes: the powerc control register, the STOP pin, and the AWAIT bit in the alf register. The PLL can also be disabled with the PLEN bit of the pllrc register for more power saving.

Powerc Control Register Bits

The powerc register has 10 bits that power down various portions of the chip and select the clock source:

XTLOFF: Assertion of the XTLOFF bit powers down the small-signal input circuit, disabling the internal processor clock. Since the small-signal input circuit takes many cycles to stabilize, care must be taken with the turn-on sequence, as described later.

SLOWCKI: Assertion of the SLOWCKI bit selects the ring oscillator as the clock source for the internal processor clock instead of CKI or the PLL. When CKI or the PLL is selected, the ring oscillator is powered down. Switching of the clocks is synchronized so that no partial or short clock pulses occur. Two nops should follow the instruction that sets or clears SLOWCKI.

NOCK: Assertion of the NOCK bit synchronously turns off the internal processor clock, regardless of whether its source is provided by CKI, the PLL, or the ring oscillator. The NOCK bit can be cleared by resetting the chip with the RSTB pin, or asserting the INT0 or INT1 pins. Two nops should follow the instruction that sets NOCK. The PLL remains running, if enabled, while NOCK is set.

INT0EN: This bit allows the INT0 pin to asynchronously clear the NOCK bit, thereby allowing the device to continue program execution from where it left off without any loss of state. No chip reset is required. It is recommended that, when INT0EN is to be used, the INT0 interrupt be disabled in the inc register so that an unintended interrupt does not occur. After the program resumes, the INT0 interrupt in the ins register should be cleared.

INT1EN: This bit enables the INT1 pin to be used as the NOCK clear, exactly like INT0EN, previously described.

The following control bits power down the peripheral I/O units of the DSP. These bits can be used to further reduce the power consumption during standard sleep mode.

SIO1DIS: This is a powerdown signal to the SIO1 I/O unit. It disables the clock input to the unit, thus eliminating any sleep power associated with the SIO1. Since the gating of the clocks may result in incomplete transactions, it is recommended that this option be used in applications where the SIO1 is not used or when reset may be used to reenable the SIO1 unit. Otherwise, the first transaction after reenabling the unit may be corrupted.

SIO2DIS: This bit powers down the SIO2 in the same way SIO1DIS powers down the SIO1.

PHIFDIS: This is a powerdown signal to the parallel host interface. It disables the clock input to the unit, thus eliminating any sleep power associated with the PHIF. Since the gating of the clocks may result in incomplete transactions, it is recommended that this option be used in applications where the PHIF is not used, or when reset may be used to reenable the PHIF. Otherwise, the first transaction after reenabling the unit may be corrupted.

TIMERDIS: This is a timer disable signal which disables the clock input to the timer unit. Its function is identical to the DISABLE field of the timerc control register. Writing a 0 to the TIMERDIS field will continue the timer operation.

Figure 8, Power Management Using the powerc and the pllrc Registers, shows a functional view of the effect of the bits of the powerc register on the clock circuitry. It shows only the high-level operation of each bit. Not shown are the bits that power down the peripheral units.

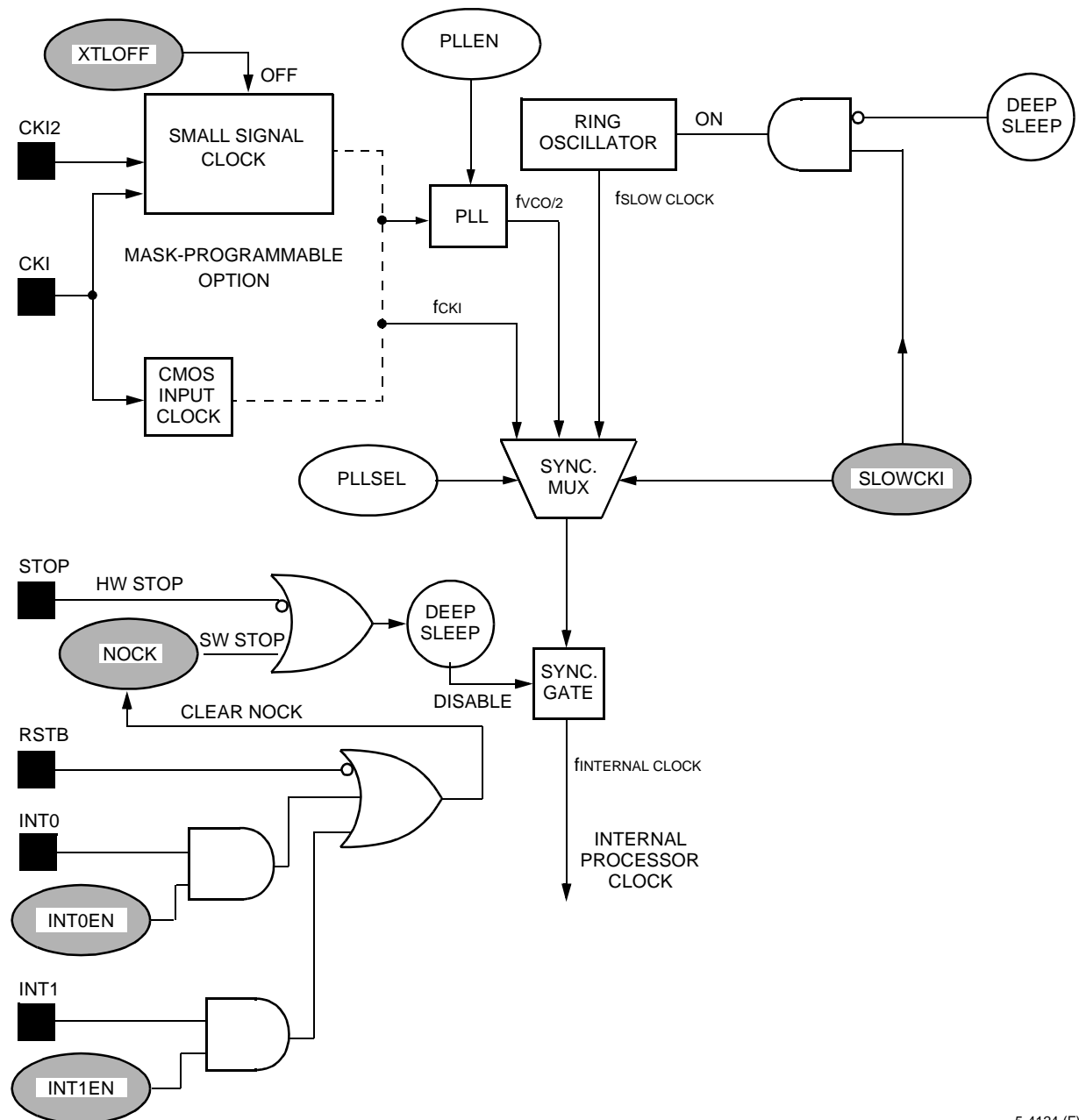
STOP Pin

Assertion (active-low) of the STOP pin has the same effect as setting the NOCK bit in the powerc register. The internal processor clock is synchronously disabled until the STOP pin is returned high. Once the STOP pin is returned high, program execution will continue from where it left off without any loss of state. No chip reset is required. The PLL remains running, if enabled, during STOP assertion.

The pllrc Register Bits

The PLEN bit of the pllrc register can be used to power down the clock synthesizer circuitry. Before shutting down the clock synthesizer circuitry, the system clock should be switched to either CKI using the PLLSEL bit of pllrc, or to the ring oscillator using the SLOWCKI bit of powerc.

4 Hardware Architecture (continued)



5-4124 (F).h

Notes:

The functions in the shaded ovals are bits in the powerc control register. The functions in the nonshaded ovals are bits in the pllcr control register. Deep sleep is the state arrived at either by a hardware or software stop of the internal processor clock.

The switching of the multiplexers and the synchronous gate is designed so that no partial clocks or glitching will occur.

When the deep sleep state is entered with the ring oscillator selected, the internal processor clock is turned off before the ring oscillator is powered down.

PLL select is the PLLSEL bit of **pllcr**; PLL powerdown is the PLLEN bit of **pllcr**.

Figure 8. Power Management Using the powerc and the pllcr Registers

4 Hardware Architecture (continued)

Await Bit of the alf Register

Setting the AWAIT bit of the alf register causes the processor to go into the standard sleep state or power-saving standby mode. Operation of the AWAIT bit is the same as in the DSP1610, DSP1611, DSP1616, DSP1617, and DSP1618. In this mode, the minimum circuitry required to process an incoming interrupt remains active, and the PLL remains active if enabled. An interrupt will return the processor to the previous state, and program execution will continue. The action resulting from setting the AWAIT bit and the action resulting from setting bits in the powerc register are mostly independent. As long as the processor is receiving a clock, whether slow or fast, the DSP may be put into standard sleep mode with the AWAIT bit. Once the AWAIT bit is set, the STOP pin can be used to stop and later restart the processor clock, returning to the standard sleep state. If the processor clock is not running, however, the AWAIT bit cannot be set.

Power Management Sequencing

There are important considerations for sequencing the power management modes. The small-signal clock input circuit has a start-up delay which must be taken into account, and the PLL requires a delay to reach lock-in. Also, the chip may or may not need to be reset following a return from a low-power state.

Devices with a small-signal input clocking option may use the XTLOFF bit in the powerc register to power down the on-chip oscillator or small-signal circuitry, thereby reducing the power dissipation. When reenabling the oscillator or the small-signal circuitry, it is important to bear in mind that a start-up interval exists, during which time the clocks are not stable.

Two scenarios exist here:

1. **Immediate Turn-Off, Turn-On with RSTB:** This scenario applies to situations where the target device is not required to execute any code while the small-signal input circuit is powered down, and where restart from a reset state can be tolerated. In this case, the processor clock derived from either the oscillator or the small-signal input is running when XTLOFF is asserted. This effectively stops the internal processor clock. When the system chooses to reenable the oscillator or small-signal input, a reset of the device will be required. The reset pulse must be of sufficient duration for the small-signal start-up interval to be satisfied (required for the small-signal input circuit to reach its dc operating point). A minimum reset pulse of 20 μ s will be adequate. The falling edge of the reset signal, RSTB, will asynchronously clear the XTLOFF field, thus reenabling the power to the small-signal circuitry. The target DSP will then start execution from a reset state, following the rising edge of RSTB.
2. **Running from Slow Clock While XTLOFF Active:** The second scenario applies to situations where the device needs to continue execution of its target code. In this case, the device switches to the slow ring oscillator clock first by enabling the SLOWCKI field. Then, if the small-signal input is being used, power down this circuitry by writing a 1 to the XTLOFF field. Two nops are needed in between the two write operations to the powerc register. The target device will then continue execution of its code at slow speed, while the small-signal input clock is turned off. Switching from the slow clock back to the high-speed clock is then accomplished in three user steps. First, XTLOFF is cleared. Then, a user-programmed routine sets the internal timer to a delay to wait for the small-signal input oscillations to become stable. When the timer counts down to zero, the high-speed clock is selected by clearing the SLOWCKI field, either in the timer's interrupt service routine or following a timer polling loop. If PLL operation is desired, then an additional routine is necessary to enable the PLL and wait for it to lock.

4 Hardware Architecture (continued)

Power Management Examples Without the PLL

The following examples show the more significant options for reducing the power dissipation. These are valid only if the pllcr register is set to disable and deselect the PLL (PLLEN = 0, PLLSEL = 0).

Standard Sleep Mode. This is the standard sleep mode. While the processor is clocked with a high-speed clock, CKI, the alfr register's AWAITS bit is set. Peripheral units may be turned off to further reduce the sleep power.

```
        powerc = 0X00F0    /* Turn off peripherals, core running with CKI */
sleep:a0 = 0x8000          /* Set alfr register in cache loop if running from */
    do 1 {                /* external memory with >1 wait state */
        alfr = a0          /* Stop internal processor clock, interrupt circuits */
        nop                /* active */
    }
    nop                    /* Needed for bedtime execution. Only sleep power */
    nop                    /* consumed here until.... interrupt wakes up the device */
cont: . . .               /* User code executes here */
        powerc = 0x0       /* Turn peripheral units back on */
```

Sleep with Slow Internal Clock. In this case, the ring oscillator is selected to clock the processor before the device is put to sleep. This will reduce the power dissipation while waiting for an interrupt to continue program execution.

```
        powerc = 0x40F0    /* Turn off peripherals and select slow clock */
        2*nop              /* Wait for it to take effect */
sleep:a0 = 0x8000          /* Set alfr register in cache loop if running from */
    do 1 {                /* external memory with >1 wait state */
        alfr = a0          /* Stop internal processor clock, interrupt circuits */
        nop                /* active */
    }
    nop                    /* Needed for bedtime execution. Reduced sleep power */
    nop                    /* consumed here.... Interrupt wakes up the device */
cont: . . .               /* User code executes here */
        powerc = 0x00F0    /* Select high-speed clock */
        2*nop              /* Wait for it to take effect */
        powerc = 0x0000    /* Turn peripheral units back on */
```

Note that, in this case, the wake-up latency is determined by the period of the ring oscillator clock.

Sleep with Slow Internal Clock and Small-Signal Disabled. If the target device contains the small-signal clock option, the clock input circuitry can be powered down to further reduce power. In this case, the slow clock must be selected first.

```
        powerc = 0x40F0    /* Turn off peripherals and select slow clock */
        2*nop              /* Wait for it to take effect */
        powerc = 0xC0F0    /* Turn off the small-signal input buffer */
sleep:a0 = 0x8000          /* Set alfr register in cache loop if running from */
    do 1 {                /* external memory with >1 wait state */
        alfr = a0          /* Stop internal processor clock, interrupt circuits */
        nop                /* active */
    }
    nop                    /* Needed for bedtime execution. Reduced sleep power */
    nop                    /* consumed here.... Interrupt wakes up the device */
        powerc = 0x40F0    /* Clear XTLOFF, reenables small-signal */
        call xtlwait       /* Wait until small-signal is stable */
cont: powerc = 0x00F0      /* Select high-speed clock */
        2*nop              /* Wait for it to take effect */
        powerc = 0x0000    /* Turn peripheral units back on */
```

Note that, in this case, the wake-up latency is dominated by the small-signal start-up period.

4 Hardware Architecture (continued)

Software Stop. In this case, all internal clocking is disabled. INT0, INT1, or RSTB may be used to reenable the clocks. The power management must be done in correct sequence.

```

        powerc = 0x4000    /* SLOWCKI asserted */
        2*nop              /* Wait for it to take effect */
        powerc = 0xD000    /* XTLOFF asserted if applicable and INT0EN asserted */
        inc = NOINT0       /* Disable the INT0 interrupt */
sopor: powerc = 0xF000     /* NOCK asserted, all clocks stop */
                               /* Minimum switching power consumed here */
        3*nop              /* Some nops will be needed */
                               /* INT0 pin clears the NOCK field, clocking resumes */
cont:  powerc = 0x4000     /* INT0EN cleared and XTLOFF cleared, if applicable */
        call waitxtl       /* Wait for the small-signal to */
                               /* stabilize, if applicable */
        powerc = 0x0       /* Clear SLOWCKI field, back to high speed */
        2*nop              /* Wait for it to take effect */
        ins = 0x0010       /* Clear the INT0 status bit */

```

In this case also, the wake-up latency is dominated by the small-signal start-up period.

The previous examples do not provide an exhaustive list of options available to the user. Many different clocking possibilities exist for which the target device may be programmed, depending on:

- The clock source to the processor.
- Whether the user chooses to power down the peripheral units.
- The operational state of the small-signal clock input, powered or unpowered.
- Whether the internal processor clock is disabled through hardware or software.
- The combination of power management modes the user chooses.
- Whether or not the PLL is enabled.

An example subroutine for xtlwait follows:

```

xtlwait:  timer0 = 0x2710    /* Load a count of 10,000 into the timer */
          timerc = 0x0010    /* Start the timer with a PRESCALE of two */
          inc = 0x0000       /* Disable the interrupts */
loop1:    a0 = ins           /* Poll the ins register */
          a0 = a0 & 0x0100    /* Check bit 8 (TIME) of the ins register */
          if eq goto loop1    /* Loop if the bit is not set */
          ins = 0x0100       /* Clear the TIME interrupt bit */
          return             /* Return to the main program */

```

4 Hardware Architecture (continued)

Power Management Examples with the PLL

The following examples show the more significant options for reducing power dissipation if operation with the PLL clock synthesizer is desired.

Standard Sleep Mode, PLL Running. This mode would be entered in the same manner as without the PLL. While the input to the clock synthesizer, CKI, remains running, the `alf` register's `AWAIT` bit is set. The PLL will continue to run and dissipate power. Peripheral units may be turned off to further reduce the sleep power.

```
        powerc = 0x00F0    /* Turn off peripherals, core running with PLL */
sleep:a0 = 0x8000          /* Set alf register in cache loop if running from */
    do 1 {                 /* external memory with >1 wait state */
        alf = a0           /* Stop internal processor clock, interrupt circuits */
        nop               /* active */
    }
    nop                   /* Needed for bedtime execution. Only sleep power plus PLL */
    nop                   /* power consumed here.... Interrupt wakes up the device */
cont:   . . .             /* User code executes here */
        powerc = 0x0      /* Turn peripheral units back on */
```

Sleep with Slow Internal Clock, PLL Running. In this case, the ring oscillator is selected to clock the processor before the device is put to sleep. This will reduce power dissipation while waiting for an interrupt to continue program execution.

```
        powerc = 0x40F0    /* Turn off peripherals and select slow clock */
        2*nop              /* Wait for slow clock to take effect */
sleep:a0 = 0x8000          /* Set alf register in cache loop if running from */
    do 1 {                 /* external memory with >1 wait state */
        alf = a0           /* Stop internal processor clock, interrupt circuits */
        nop               /* active */
    }
    nop                   /* Needed for bedtime execution. Reduced sleep power, PLL */
    nop                   /* power, and ring oscillator power consumed here... */
                                /* Interrupt wakes up the device */
cont:   . . .             /* User code executes here */
        powerc = 0x00F0    /* Select high-speed PLL based clock */
        2*nop              /* Wait for it to take effect */
        powerc = 0x0000    /* Turn peripheral units back on */
```

4 Hardware Architecture (continued)

Sleep with Slow Internal Clock and Small-Signal Disabled, PLL Disabled. If the target device contains the small-signal clock option, the clock input circuitry can be powered down to further reduce power. In this case, the slow clock must be selected first, and then the PLL must be disabled, since the PLL cannot run without the clock input circuitry being active.

```

    powerc = 0x40F0    /* Turn off peripherals and select slow clock */
    2*nop              /* Wait for slow clock to take effect */
    pll = 0x29F2       /* Disable PLL (assume N = 1, M = 20, LF = 1001) */
    powerc = 0xC0F0    /* Disable small-signal input buffer */
sleep: a0 = 0x8000     /* Set alf register in cache loop if running from */
    do 1 {             /* external memory with >1 wait state */
        alf = a0        /* Stop internal processor clock, interrupt circuits */
        nop             /* active */
    }
    nop                /* Needed for bedtime execution. Reduced sleep power
    nop                /* consumed here.... Interrupt wakes up device */
    powerc = 0x40F0    /* Clear XTLOFF, leave PLL disabled */
    call xtlwait       /* Wait until small-signal is stable */
    pll = 0xE9F2       /* Enable PLL, continue to run off slow clock */
    call pllwait       /* Loop to check for LOCK flag assertion */
cont: powerc = 0x00F0  /* Select high-speed PLL based clock */
    2*nop              /* Wait for it to take effect */
    powerc = 0x0000    /* Turn peripherals back on */

```

Software Stop, PLL Disabled. In this case, all internal clocking is disabled. INT0, INT1, or RSTB may be used to reenable the clocks. The power management must be done in the correct sequence, with the PLL being disabled before shutting down the clock input buffer.

```

    powerc = 0x4000    /* SLOWCKI asserted */
    2*nop              /* Wait for slow clock to take effect */
    pll = 0x29F2       /* Disable PLL (assume N = 1, M = 20, LF = 1001) */
    powerc = 0xD000    /* XTLOFF asserted, if applicable and INT0EN
                        /* asserted */
sopor: powerc = 0xF000 /* NOCK asserted, all clocks stop */
                        /* Minimum switching power consumed here */
    3*nop              /* Some nops will be needed */
                        /* INT0 pin clears NOCK field, clocking resumes */
cont: powerc = 0x4000  /* INTOEN cleared and XTLOFF cleared, if applicable */
    call xtlwait       /* Wait until small-signal is stable */
                        /* if applicable */
    pll = 0xE9F2       /* Enable PLL, continue to run off slow clock */
    call pllwait       /* Loop to check for LOCK flag assertion */
    powerc = 0x0       /* Select high-speed PLL based clock */
    2*nop              /* Wait for it to take effect */
    ins = 0x0010       /* Clear the INT0 status bit */

```

5 Software Architecture

5.1 Instruction Set

The DSP1629 processor has seven types of instructions: multiply/ALU, special function, control, F3 ALU, BMU, cache, and data move. The multiply/ALU instructions are the primary instructions used to implement signal processing algorithms. Statements from this group can be combined to generate multiply/accumulate, logical, and other ALU functions and to transfer data between memory and registers in the data arithmetic unit. The special function instructions can be conditionally executed based on flags from the previous ALU or BMU operation, the condition of one of the counters, or the value of a pseudorandom bit in the DSP1629 device. Special function instructions perform shift, round, and complement functions. The F3 ALU instructions enrich the operations available on accumulators. The BMU instructions provide high-performance bit manipulation. The control instructions implement the goto and call commands. Control instructions can also be executed conditionally. Cache instructions are used to implement low-overhead loops, conserve program memory, and decrease the execution time of certain multiply/ALU instructions. Data move instructions are used to transfer data between memory and registers or between accumulators and registers. See the *DSP1611/17/18/27/28/29 Digital Signal Processor Information Manual* for a detailed description of the instruction set.

The following operators are used in describing the instruction set:

- * 16 x 16-bit → 32-bit multiplication **or** register-indirect addressing when used as a prefix to an address register **or** denotes direct addressing when used as a prefix to an immediate
- + 36-bit addition[†]
- - 36-bit subtraction[†]
- >> Arithmetic right shift
- >>> Logical right shift
- << Arithmetic left shift
- <<< Logical left shift
- | 36-bit bitwise OR[†]
- & 36-bit bitwise AND[†]
- ^ 36-bit bitwise EXCLUSIVE OR[†]
- : Compound address swapping, accumulator shuffling
- ~ One's complement

[†] These are 36-bit operations. One operand is 36-bit data in an accumulator; the other operand may be 16 bits, 32 bits, or 36 bits.

Multiply/ALU Instructions

Note that the function statements and transfer statements in Table 13, Multiply/ALU Instructions, are chosen independently. Any function statement (F1) can be combined with any transfer statement to form a valid multiply/ALU instruction. If either statement is not required, a single statement from either column also constitutes a valid instruction. The number of cycles to execute the instruction is a function of the transfer column. (An instruction with no transfer statement executes in one instruction cycle.) Whenever PC, pt, or rM is used in the instruction and points to external memory, the programmed number of wait-states must be added to the instruction cycle count. All multiply/ALU instructions require one word of program memory. The no-operation (nop) instruction is a special-case encoding of a multiply/ALU instruction and executes in one cycle. The assembly-language representation of a nop is either nop or a single semicolon.

A single-cycle squaring function is provided in DSP1629. By setting the X = Y = bit in the auc register, any instruction that loads the high half of the y register also loads the x register with the same value. A subsequent instruction to multiply the x register and y register results in the square of the value being placed in the p register. The instruction a0 = p p = x*y y = *r0++ with the X = Y = bit set to one will read the value pointed to by r0, load it to both x and y, multiply the previously fetched value of x and y, and transfer the previous product to a0. A table of values pointed to by r0 can thus be squared in a pipeline with one instruction cycle per each value. Multiply/ALU instructions that use x = X transfer statements (such as a0 = p p = x*y y = *r0++ x = *pt++) are not recommended for squaring because pt will be incremented even though x is not loaded from the value pointed to by pt. Also, the same conflict wait occurs from reading the same bank of internal memory or reading from external memory apply, since the X space fetch occurs (even though its value is not used).

5 Software Architecture (continued)

Table 13. Multiply/ALU Instructions

Function Statement	Transfer Statement [†]	Cycles (Out/In Cache) [‡]
$p = x * y$	$y = Y \quad x = X$	2/1
$aD = p \quad p = x * y$	$y = aT \quad x = X$	2/1
$aD = aS + p \quad p = x * y$	$y[l] = Y$	1/1
$aD = aS - p \quad p = x * y$	$aT[l] = Y$	1/1
$aD = p$	$x = Y$	1/1
$aD = aS + p$	Y	1/1
$aD = aS - p$	$Y = y[l]$	2/2
$aD = y$	$Y = aT[l]$	2/2
$aD = aS + y$	$Z:y \quad x = X$	2/2
$aD = aS - y$	$Z:y[l]$	2/2
$aD = aS \& y$	$Z:aT[l]$	2/2
$aD = aS y$		
$aD = aS \wedge y$		
$aS - y$		
$aS \& y$		

[†] The l in [] is an optional argument that specifies the low 16 bits of **aT** or **y**.

[‡] Add cycles for:

1. When an external memory access is made in X or Y space and wait-states are programmed, add the number of wait-states.
2. If an X-space access and a Y-space access are made to the same bank of DPRAM in one instruction, add one cycle.

Note: For transfer statements when loading the upper half of an accumulator, the lower half is cleared if the corresponding CLR bit in the auc register is zero. auc is cleared by reset.

Table 14. Replacement Table for Multiply/ALU Instructions

Replace	Value	Meaning
aD, aS, aT	a0, a1	One of two DAU accumulators.
X	*pt++, *pt++i	X memory space location pointed to by pt. pt is postmodified by +1 and i, respectively.
Y	*rM, *rM++, *rM--, rM++j	RAM location pointed to by rM (M = 0, 1, 2, 3). rM is postmodified by 0, +1, -1, or j, respectively.
Z	*rMzp, *rMpz, *rMm2, *rMjk	Read/write compound addressing. rM (M = 0, 1, 2, 3) is used twice. First, postmodified by 0, +1, -1, or j, respectively; and, second, postmodified by +1, 0, +2, or k, respectively.

5 Software Architecture (continued)

Special Function Instructions

All forms of the special function require one word of program memory and execute in one instruction cycle. (If PC points to external memory, add programmed wait-states.)

$aD = aS \gg 1$ $aD = aS \gg 4$ $aD = aS \gg 8$ $aD = aS \gg 16$	}	Arithmetic right shift (sign preserved) of 36-bit accumulators
---	---	--

$aD = aS$	Load destination accumulator from source accumulator
$aD = -aS$	2's complement
$aD = \sim aS^*$	1's complement
$aD = \text{rnd}(aS)$	Round upper 20 bits of accumulator
$aDh = aSh + 1$	Increment upper half of accumulator (lower half cleared)
$aD = aS + 1$	Increment accumulator
$aD = y$	Load accumulator with 32-bit y register value with sign extend
$aD = p$	Load accumulator with 32-bit p register value with sign extend

$aD = aS \ll 1$ $aD = aS \ll 4$ $aD = aS \ll 8$ $aD = aS \ll 16$	}	Arithmetic left shift (sign not preserved) of the lower 32 bits of accumulators (upper 4 bits are sign-bit-extended from bit 31 at the completion of the shift)
---	---	---

The above special functions can be conditionally executed, as in:

```
if CON instruction
```

and with an event counter:

```
ifc CON instruction
```

which means:

```
if CON is true then
    c1 = c1 + 1
    instruction
    c2 = c1
else
    c1 = c1 + 1
```

The above special function statements can be executed unconditionally by writing them directly, e.g., $a0 = a1$.

Table 15. Replacement Table for Special Function Instructions

Replace	Value	Meaning
aD aS	a0, a1	One of two DAU accumulators.
CON	mi, pl, eq, ne, gt, le, lvs, lvc, mvs, mvc, c0ge, c0lt, c1ge, c1lt, heads, tails, true, false, allt, allf, somet, somef, oddp, evenp, mns1, nmns1, npint, njint, lock	See Table 17, DSP1629 Conditional Mnemonics, for definitions of mnemonics.

* This function is not available for the DSP16A.

5 Software Architecture (continued)

Control Instructions

All control instructions executed unconditionally execute in two cycles, except `icall`, which takes three cycles. Control instructions executed conditionally execute in three instruction cycles. (If `PC`, `pt`, or `pr` point to external memory, add programmed wait-states.) Control instructions executed unconditionally require one word of program memory, while control instructions executed conditionally require two words. Control instructions cannot be executed from the cache.

```
goto JA†
goto pt
call JA†
call pt
icall‡
return      (goto pr)
ireturn     (goto pi)
```

[†] The **goto JA** and **call JA** instructions should not be placed in the last or next-to-last instruction before the boundary of a 4 Kwords page. If the **goto** or **call** is placed there, the program counter will have incremented to the next page and the jump will be to the next page, rather than to the desired current page.

[‡] The **icall** instruction is reserved for development system use.

The above control instructions, with the exception of `ireturn` and `icall`, can be conditionally executed. For example:

```
if le goto 0x0345
```

Table 16. Replacement Table for Control Instructions

Replace	Value	Meaning
CON	mi, pl, eq, ne, gt, le, nlvs, lvc, mvs, mvc, c0ge, c0lt, c1ge, c1lt, heads, tails, true, false, allt, allf, somet, somef, oddp, evenp, mns1, nmns1, npint, njint, lock	See Table 17, DSP1629 Conditional Mnemonics, for definitions of mnemonics.
JA	12-bit value	Least significant 12 bits of absolute address within the same 4 Kwords memory section.

5 Software Architecture (continued)

Conditional Mnemonics (Flags)

Table 17, DSP1629 Conditional Mnemonics, lists mnemonics used in conditional execution of special function and control instructions.

Table 17. DSP1629 Conditional Mnemonics

Test	Meaning	Test	Meaning
pl	Result is nonnegative (sign bit is bit 35) (≥ 0).	mi	Result is negative (< 0).
eq	Result is equal to 0 ($= 0$).	ne	Result is not equal to 0 ($\neq 0$).
gt	Result is greater than 0 (> 0).	le	Result is less than or equal to 0 (≤ 0).
lvs	Logical overflow set.*	lvc	Logical overflow clear.
mvs	Mathematical overflow set.†	mvc	Mathematical overflow clear.
c0ge	Counter 0 greater than or equal to 0.	c0lt	Counter 0 less than 0.
c1ge	Counter 1 greater than or equal to 0.	c1lt	Counter 1 less than 0.
heads	Pseudorandom sequence bit set.	tails	Pseudorandom sequence bit clear.
true	The condition is always satisfied in an if instruction.	false	The condition is never satisfied in an if instruction.
allt	All true, all BIO input bits tested compared successfully.	allf	All false, no BIO input bits tested compared successfully.
somet	Some true, some BIO input bits tested compared successfully.	somef	Some false, some BIO input bits tested did not compare successfully.
oddp	Odd parity, from BMU operation.	evenp	Even parity, from BMU operation.
mns1	Minus 1, result of BMU operation.	nmns1	Not minus 1, result of BMU operation.
npint	Not PINT, used by hardware development system.	njint	Not JINT, used by hardware development system.
lock	The PLL has achieved lock and is stable.	—	—

* Result is not representable in the 36-bit accumulators (36-bit overflow).

† Bits 35—31 are not the same (32-bit overflow).

Notes:

Testing the state of the counters (c0 or c1) automatically increments the counter by one.

The heads or tails condition is determined by a randomly set or cleared bit, respectively. The bit is randomly set with a probability of 0.5. A random rounding function can be implemented with either heads or tails. The random bit is generated by a ten-stage pseudorandom sequence generator (PSG) that is updated after either a heads or tails test. The pseudorandom sequence may be reset by writing any value to the pi register, except during an interrupt service routine (ISR). While in an ISR, writing to the pi register updates the register and does not reset the PSG. If not in an ISR, writing to the pi register resets the PSG. (The pi register is updated, but will be written with the contents of the PC on the next instruction.) Interrupts must be disabled when writing to the pi register. If an interrupt is taken after the pi write, but before pi is updated with the PC value, the ireturn instruction will not return to the correct location. If the RAND bit in the auc register is set, however, writing the pi register never resets the PSG.

5 Software Architecture (continued)

F3 ALU Instructions

These instructions are implemented in the DSP1600 core. They allow accumulator two-operand operations with either another accumulator, the p register, or a 16-bit immediate operand (IM16). The result is placed in a destination accumulator that can be independently specified. All operations are done with the full 36 bits. For the accumulator with accumulator operations, both inputs are 36 bits. For the accumulator with p register operations, the p register is sign-extended into bits 35—32 before the operation. For the accumulator high with immediate operations, the immediate is sign-extended into bits 35—32 and the lower bits 15—0 are filled with zeros, except for the AND operation, because they are filled with ones. These conventions allow the user to do operations with 32-bit immediates by programming two consecutive 16-bit immediate operations. The F3 ALU instructions are shown in Table 18, F3 ALU Instructions.

Table 18. F3 ALU Instructions

F3 ALU Instructions*	
Cacheable (One-Cycle)	Not Cacheable (Two-Cycle) [†]
aD = aS + aT	aD = aSh + IM16
aD = aS – aT	aD = aSh – IM16
aD = aS & aT	aD = aSh & IM16
aD = aS aT	aD = aSh IM16
aD = aS ^ aT	aD = aSh ^ IM16
aS – aT	aSh – IM16
aS & aT	aSh & IM16
aD = aS + p	aD = aSI + IM16
aD = aS – p	aD = aSI – IM16
aD = aS & p	aD = aSI & IM16
aD = aS p	aD = aSI IM16
aD = aS ^ p	aD = aSI ^ IM16
aS – p	aSI – IM16
aS & p	aSI & IM16

* If PC points to external memory, add programmed wait-states.

[†] The **h** and **I** are required notation in these instructions.

Note: The F3 ALU instructions that do not have a destination accumulator are used to set flags for conditional operations, i.e., bit test operations.

F4 BMU Instructions

The bit manipulation unit in the DSP1629 provides a set of efficient bit manipulation operations on accumulators. It contains four auxiliary registers, ar<0—3> (arM, M = 0, 1, 2, 3), two alternate accumulators (aa0—aa1), which can be shuffled with the working set, and four flags (oddp, evenp, mns1, and nmns1). The flags are testable by conditional instructions and can be read and written via bits 4—7 of the alf register. The BMU also sets the LMI, LEQ, LLV, and LMV flags in the psw register.

LMI = 1 if negative (i.e., bit 35 = 1)

LEQ = 1 if zero (i.e., bits 35—0 are 0)

LLV = 1 if (a) 36-bit overflow, or if (b) illegal shift on field width/offset condition

LMV = 1 if bits 31—35 are not the same (32-bit overflow)

The BMU instructions and cycle times follow. (If PC points to external memory, add programmed wait-states.) All BMU instructions require 1 word of program memory unless otherwise noted. Please refer to the *DSP1611/17/18/27/28/29 Digital Signal Processor Information Manual* for further discussion of the BMU instructions.

5 Software Architecture (continued)

■ Barrel Shifter:

$aD = aS \gg IM16$	Arithmetic right shift by immediate (36-bit, sign filled in); 2-cycle, 2-word.
$aD = aS \gg arM$	Arithmetic right shift by arM (36-bit, sign filled in); 1-cycle.
$aD = \overline{aS} \gg aS$	Arithmetic right shift by aS (36-bit, sign filled in); 2-cycle.
$aD = aS \ggg IM16$	Logical right shift by immediate (32-bit shift, 0s filled in); 2-cycle, 2-word.
$aD = aS \ggg arM$	Logical right shift by arM (32-bit shift, 0s filled in); 1-cycle.
$aD = \overline{aS} \ggg aS$	Logical right shift by aS (32-bit shift, 0s filled in); 2-cycle.
$aD = aS \ll IM16$	Arithmetic left shift [†] by immediate (36-bit shift, 0s filled in); 2-cycle, 2-word.
$aD = aS \ll arM$	Arithmetic left shift [†] by arM (36-bit shift, 0s filled in); 1-cycle.
$aD = \overline{aS} \ll aS$	Arithmetic left shift [†] by aS (36-bit shift, 0s filled in); 2-cycle.
$aD = aS \lll IM16$	Logical left shift by immediate (36-bit shift, 0s filled in); 2-cycle, 2-word.
$aD = aS \lll arM$	Logical left shift by arM (36-bit shift, 0s filled in); 1-cycle.
$aD = \overline{aS} \lll aS$	Logical left shift by aS (36-bit shift, 0s filled in); 2-cycle.

† Not the same as the special function arithmetic left shift. Here, the guard bits in the destination accumulator are shifted into, not sign-extended.

■ Normalization and Exponent Computation:

$aD = \text{exp}(aS)$	Detect the number of redundant sign bits in accumulator; 1-cycle.
$aD = \text{norm}(aS, arM)$	Normalize aS with respect to bit 31, with exponent in arM; 1-cycle.

■ Bit Field Extraction and Insertion:

$aD = \text{extracts}(aS, IM16)$	Extraction with sign extension, field specified as immediate; 2-cycle, 2-word.
$aD = \text{extracts}(aS, arM)$	Extraction with sign extension, field specified in arM; 1-cycle.
$aD = \text{extractz}(aS, IM16)$	Extraction with zero extension, field specified as immediate; 2-cycle, 2-word.
$aD = \text{extractz}(aS, arM)$	Extraction with zero extension, field specified in arM; 1-cycle.
$aD = \text{insert}(aS, IM16)$	Bit field insertion, field specified as immediate; 2-cycle, 2-word.
$aD = \text{insert}(aS, arM)$	Bit field insertion, field specified in arM; 2-cycle.

Note: The bit field to be inserted or extracted is specified as follows. The width (in bits) of the field is the upper byte of the operand (immediate or arM), and the offset from the LSB is in the lower byte.

■ Alternate Accumulator Set:

$aD = aS:aa0$	Shuffle accumulators with alternate accumulator 0 (aa0); 1-cycle.
$aD = aS:aa1$	Shuffle accumulators with alternate accumulator 1 (aa1); 1-cycle.

Note: The alternate accumulator gets what was in aS. aD gets what was in the alternate accumulator.

Table 19. Replacement Table for F3 ALU Instructions and F4 BMU Instructions

Replace	Value	Meaning
aD, aT, aS	a0 or a1	One of the two accumulators.
IM16	immediate	16-bit data, sign-, zero-, or one-extended as appropriate.
arM	ar<0—3>	One of the auxiliary BMU registers.

5 Software Architecture (continued)

Cache Instructions

Cache instructions require one word of program memory. The **do** instruction executes in one instruction cycle, and the **redo** instruction executes in two instruction cycles. (If PC points to external memory, add programmed wait-states.) Control instructions and long immediate values cannot be stored inside the cache. The instruction formats are as follows:

- **do** K {
- instr1
- instr2
- .
- .
- .
- instrN
- }
- **redo** K

Table 20. Replacement Table for Cache Instructions

Replace	Instruction Encoding	Meaning
K	cloop [†]	Number of times the instructions are to be executed taken from bits 0—6 of the cloop register.
	1 to 127	Number of times the instructions to be executed are encoded in the instruction.
N	1 to 15	1 to 15 instructions can be included.

[†] The assembly-language statement, **do cloop** (or **redo cloop**), is used to specify that the number of iterations is to be taken from the **cloop** register. K is encoded as 0 in the instruction encoding to select **cloop**.

When the cache is used to execute a block of instructions, the cycle timings of the instructions are as follows:

1. In the first pass, the instructions are fetched from program memory and the cycle times are the normal out-of-cache values, except for the last instruction in the block of N instructions. This instruction executes in two cycles.
2. During pass two through pass K – 1, each instruction is fetched from cache and the in-cache timings apply.
3. During the last (Kth) pass, the block of instructions is fetched from cache and the in-cache timings apply, except that the timing of the last instruction is the same as if it were out-of-cache.
4. If any of the instructions access external memory, programmed wait-states must be added to the cycle counts.

The **redo** instruction treats the instructions currently in the cache memory as another loop to be executed K times. Using the **redo** instruction, instructions are reexecuted from the cache without reloading the cache.

The number of iterations, K, for a **do** or **redo** can be set at run time by first moving the number of iterations into the **cloop** register (7 bits unsigned), and then issuing the **do cloop** or **redo cloop**. At the completion of the loop, the value of **cloop** is decremented to 0; hence, **cloop** needs to be written before each **do cloop** or **redo cloop**.

5 Software Architecture (continued)

Data Move Instructions

Data move instructions normally execute in two instruction cycles. (If PC or rM point to external memory, any programmed wait-states must be added. In addition, if PC and rM point to the same bank of DPRAM, then one cycle must be added.) Immediate data move instructions require two words of program memory; all other data move instructions require only one word. The only exception to these statements is a special case immediate load (short immediate) instruction. If a YAAU register is loaded with a 9-bit short immediate value, the instruction requires only one word of memory and executes in one instruction cycle. All data move instructions, except those doing long immediate loads, can be executed from within the cache. The data move instructions are as follows:

- R = IM16
- aT[l] = R
- SR = IM9
- Y = R
- R = Y
- Z:R
- R = aS[l]
- DR = *(OFFSET)
- (OFFSET) = DR

Table 21. Replacement Table for Data Move Instructions

Replace	Value	Meaning
R	Any of the registers in Table 51, R Field	—
DR	r<0—3>, a0[l], a1[l], y[l], p, pl, x, pt, pr, psw	Subset of registers accessible with direct addressing.
aS, aT	a0, a1	High half of accumulator.
Y	*rM, *rM++, *rM--, *rM++j	Same as in multiply/ALU instructions.
Z	*rMzp, *rMpz, *rMm2, *rMjk	Same as in multiply/ALU instructions.
IM16	16-bit value	Long immediate data.
IM9	9-bit value	Short immediate data for YAAU registers.
OFFSET	5-bit value from instruction 11-bit value in base register	Value in bits [15:5] of ybase register form the 11 most significant bits of the base address. The 5-bit offset is concatenated to this to form a 16-bit address.
SR	r<0—3>, rb, re, j, k	Subset of registers for short immediate.

Notes:
sioc, sioc2, tdms, tdms2, srta, and srta2 registers are not readable.

When signed registers less than 16 bits wide (c0, c1, c2) are read, their contents are sign-extended to 16 bits. When unsigned registers less than 16 bits wide are read, their contents are zero-extended to 16 bits.

Loading an accumulator with a data move instruction does not affect the flags.

5 Software Architecture (continued)

5.2 Register Settings

Table 22, Serial I/O Control Registers, through Table 38, ioc Register, describe the programmable registers of the DSP1629 device. Table 40, Register Settings After Reset, describes the register settings after reset.

Note that the following abbreviations are used in the tables:

- x = don't care
- R = read only
- W = read/write

The reserved (RSVD) bits in the tables should always be written with zeros to make the program compatible with future chip versions.

Table 22. Serial I/O Control Registers

sioc

Bit	10	9	8	7	6	5	4	3	2	1	0
Field	DODLY	LD	CLK		MSB	OLD	ILD	OCK	ICK	OLEN	ILEN

Field	Value	Description
DODLY	0	DO changes on the rising edge of OCK.
	1	DO changes on the falling edge of OCK. This delay in driving DO increases the hold time on DO by half a cycle of OCK.
LD	0	In active mode, ILD1 and/or OLD1 = ICK1/16, active SYNC1 = ICK1/[128/256*].
	1	In active mode, ILD1 and/or OLD1 = OCK1/16, active SYNC1 = OCK1/[128/256*].
CLK	00	Active clock = CKI/2 (1X).
	01	Active clock = CKI/6 (1X).
	10	Active clock = CKI/8 (1X).
	11	Active clock = CKI/10 (1X).
MSB	0	LSB first.
	1	MSB first.
OLD	0	OLD1 is an input (passive mode).
	1	OLD1 is an output (active mode).
ILD	0	ILD1 is an input (passive mode).
	1	ILD1 is an output (active mode).
OCK	0	OCK1 is an input (passive mode).
	1	OCK1 is an output (active mode).
ICK	0	ICK1 is an input (passive mode).
	1	ICK1 is an output (active mode).
OLEN	0	16-bit output.
	1	8-bit output.
ILEN	0	16-bit input.
	1	8-bit input.

sioc2[†]

Bit	10	9	8	7	6	5	4	3	2	1	0
Field	DODLY2	LD2	CLK2		MSB2	OLD2	ILD2	OCK2	ICK2	OLEN2	ILEN2

* See tdms register, SYNC field.

† The bit definitions of the sioc2 register are identical to the **sioc** register bit definitions.

5 Software Architecture (continued)

Table 23. Time-Division Multiplex Slot Registers

tdms

Bit	9	8	7	6	5	4	3	2	1	0
Field	SYNCSP	MODE	TRANSMIT SLOT							SYNC

Field	Value	Description
SYNCSP*	0† 1	SYNC1 = ICK1/128 if LD = 0*. SYNC1 = OCK1/128 if LD = 1*. SYNC1 = ICK1/256 if LD = 0*. SYNC1 = OCK1/256 if LD = 1*.
MODE	0 1	Multiprocessor mode off; DOEN1 is an input (passive mode). Multiprocessor mode on; DOEN1 is an output (active mode).
TRANSMIT SLOT	1xxxxxx x1xxxxx xx1xxxx xxx1xxx xxxx1xx xxxxx1x xxxxxx1	Transmit slot 7. Transmit slot 6. Transmit slot 5. Transmit slot 4. Transmit slot 3. Transmit slot 2. Transmit slot 1.
SYNC	1 0	Transmit slot 0, SYNC1 is an output (active mode). SYNC1 is an input (passive mode).

tdms2‡

Bit	9	8	7	6	5	4	3	2	1	0
Field	SYNCSP2*	MODE2	TRANSMIT SLOT2							SYNC2

* See sioc register, LD field.

† Select this mode when in multiprocessor mode.

‡ The tdms2 register bit definitions are identical to the tdms register bit definitions.

5 Software Architecture (continued)

Table 24. Serial Receive/Transmit Address Registers

srta

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Field	RECEIVE ADDRESS								TRANSMIT ADDRESS							

Field	Value	Description
RECEIVE ADDRESS	1xxxxxxx	Receive address 7.
	x1xxxxxx	Receive address 6.
	xx1xxxxx	Receive address 5.
	xxx1xxxx	Receive address 4.
	xxxx1xxx	Receive address 3.
	xxxxx1xx	Receive address 2.
	xxxxxx1x	Receive address 1.
	xxxxxxx1	Receive address 0.
TRANSMIT ADDRESS	1xxxxxxx	Transmit address 7.
	x1xxxxxx	Transmit address 6.
	xx1xxxxx	Transmit address 5.
	xxx1xxxx	Transmit address 4.
	xxxx1xxx	Transmit address 3.
	xxxxx1xx	Transmit address 2.
	xxxxxx1x	Transmit address 1.
	xxxxxxx1	Transmit address 0.

srta2*

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Field	RECEIVE ADDRESS2								TRANSMIT ADDRESS2							

* The srta2 field definitions are identical to the **srta** register field definitions.

Table 25. Multiprocessor Protocol Registers

saddx

Bit Field	15—8	7—0
Write	X	Write Protocol Field [7:0]
Read	Read Protocol Field [7:0]	0

saddx2†

Bit Field	15—8	7—0
Write	X	Write Protocol2 Field [7:0]
Read	Read Protocol2 Field [7:0]	0

† The saddx2 field definitions are identical to the saddx register field definitions.

5 Software Architecture (continued)

Table 26. Processor Status Word (psw) Register

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Field	DAU FLAGS				X	X	a1[V]	a1[35:32]				a0[V]	a0[35:32]			

Field	Value	Description
DAU FLAGS*	Wxxx	LMI—logical minus when set (bit 35 = 1).
	xWxx	LEQ—logical equal when set (bit [35:0] = 0).
	xxWx	LLV—logical overflow when set.
	xxxW	LMV—mathematical overflow when set.
a1[V]	W	Accumulator 1 (a1) overflow when set.
a1[35:32]	Wxxx	Accumulator 1 (a1) bit 35.
	xWxx	Accumulator 1 (a1) bit 34.
	xxWx	Accumulator 1 (a1) bit 33.
	xxxW	Accumulator 1 (a1) bit 32.
a0[V]	W	Accumulator 0 (a0) overflow when set.
a0[35:32]	Wxxx	Accumulator 0 (a0) bit 35.
	xWxx	Accumulator 0 (a0) bit 34.
	xxWx	Accumulator 0 (a0) bit 33.
	xxxW	Accumulator 0 (a0) bit 32.

* The DAU flags can be set by either BMU or DAU operations.

Table 27. Arithmetic Unit Control (auc) Register†

Bit	8	7	6	5	4	3	2	1	0
Field	RAND	X=Y=	CLR			SAT		ALIGN	

Field	Value	Description
RAND	0	Pseudorandom sequence generator (PSG) reset by writing the pi register only outside an interrupt service routine.
	1	PSG never reset by writing the pi register.
X=Y=	0	Normal operation.
	1	All instructions which load the high half of the y register also load the x register, allowing single-cycle squaring with $p = x * y$.
CLR	1xx	Clearing yl is disabled (enabled when 0).
	x1x	Clearing a1l is disabled (enabled when 0).
	xx1	Clearing a0l is disabled (enabled when 0).
SAT	1x	a1 saturation on overflow is disabled (enabled when 0).
	x1	a0 saturation on overflow is disabled (enabled when 0).
ALIGN	00	$a0, a1 \leftarrow p$.
	01	$a0, a1 \leftarrow p/4$.
	10	$a0, a1 \leftarrow p \times 4$ (and zeros written to the two LSBs).
	11	$a0, a1 \leftarrow p \times 2$ (and zero written to the LSB).

† The auc is 9 bits [8:0]. The upper 7 bits [15:9] are always zero when read and should always be written with zeros to make the program compatible with future chip versions. The auc register is cleared at reset.

5 Software Architecture (continued)**Table 28. Parallel Host Interface Control (phifc) Register**

Bit	15—7	6	5	4	3	2	1	0
Field	RSVD	PSOBEF	PFLAGSEL	PFLAG	PBSELF	PSTRB	PSTROBE	PMODE

Field	Value	Description
PMODE	0	8-bit data transfers.
	1	16-bit data transfers.
PSTROBE	0	<i>Intel</i> protocol: PIDS and PODS data strobes.
	1	<i>Motorola</i> protocol: PRWN and PDS data strobes.
PSTRB	0	When PSTROBE = 1, PODS pin (PDS) active-low.
	1	When PSTROBE = 1, PODS pin (PDS) active-high.
PBSELF	0	In either mode, PBSEL pin = 0 → pdx0 low byte. See Table 7, PHIF Function (8-bit and 16-bit Modes).
	1	If PMODE = 0, PBSEL pin = 1 → pdx0 low byte.
		If PMODE = 1, PBSEL pin = 0 → pdx0 high byte.
PFLAG	0	PIBF and POBE pins active-high.
	1	PIBF and POBE pins active-low.
PFLAGSEL	0	Normal.
	1	PIBF flag ORed with POBE flag and output on PIBF pin; POBE pin unchanged (output buffer empty).
PSOBEF	0	Normal.
	1	POBE flag as read through PSTAT register is active-low.

Table 29. Interrupt Control (inc) Register

Bit	15	14—11	10	9	8	7—6	5—4	3	2	1	0
Field	JINT*	RSVD	OBE2	IBF2	TIME	RSVD	INT[1:0]	PIBF	POBE	OBE	IBF

* JINT is a JTAG interrupt and is controlled by the HDS. It may be made unmaskable by the Agere Systems development system tools.

Encoding: a 0 disables an interrupt; a 1 enables an interrupt.

Table 30. Interrupt Status (ins) Register

Bit	15	14—11	10	9	8	7—6	5—4	3	2	1	0
Field	JINT	RSVD	OBE2	IBF2	TIME	RSVD	INT[1:0]	PIBF	POBE	OBE	IBF

Encoding: a 0 indicates no interrupt. A 1 indicates an interrupt has been recognized and is pending or being serviced. If a 1 is written to bits 4, 5, or 8 of ins, the corresponding interrupt is cleared.

5 Software Architecture (continued)

Table 31. timerc Register

Bit	15—7	6	5	4	3—0
Field	RSVD	DISABLE	RELOAD	T0EN	PRESCALE
Field	Value	Description			
DISABLE	0	Timer enabled.			
	1	Timer and prescaler disabled. The period register and timer0 are not reset.			
RELOAD	0	Timer stops after counting down to 0.			
	1	Timer automatically reloads and repeats indefinitely.			
T0EN	0	Timer holds current count.			
	1	Timer counts down to 0.			
PRESCALE	—	See the PRESCALE Field table.			

PRESCALE Field

PRESCALE	Frequency of Timer Interrupts	PRESCALE	Frequency of Timer Interrupts
0000	CKO/2	1000	CKO/512
0001	CKO/4	1001	CKO/1024
0010	CKO/8	1010	CKO/2048
0011	CKO/16	1011	CKO/4096
0100	CKO/32	1100	CKO/8192
0101	CKO/64	1101	CKO/16384
0110	CKO/128	1110	CKO/32768
0111	CKO/256	1111	CKO/65536

Table 32. Phase-Locked Loop Control (pllC) Register

Bit	15	14	13	12	11—8	7—5	4—0
Field	PLLEN	PLLSEL	ICP	RSVD	LF[3:0]	Nbits[2:0]	Mbits[4:0]
Field	Value	Description					
PLLEN	0	PLL powered down.					
	1	PLL powered up.					
PLLSEL	0	DSP internal clock taken directly from CKI.					
	1	DSP internal clock taken from PLL.					
ICP	—	Charge pump current selection (see Table 64, PLL Electrical Specifications and pllC Register Settings for proper value).					
RSVD	0	—					
LF[3:0]	—	Loop filter setting (see Table 64, PLL Electrical Specifications and pllC Register Settings for proper value).					
Nbits[2:0]	—	Encodes N, $1 \leq N \leq 8$, where $N = \text{Nbits}[2:0] + 2$, unless $\text{Nbits}[2:0] = 111$, then $N = 1$.					
Mbits[4:0]	—	Encodes M, $2 \leq M \leq 20$, where $M = \text{Mbits}[4:0] + 2$, $f_{\text{INTERNAL CLOCK}} = f_{\text{CKI}} \times (M/(2N))$.					

5 Software Architecture (continued)

Table 33. sbt Register

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Field	DIREC[7:0]								VALUE[7:0]							
Field	Value								Description							
DIREC	1xxxxxxx								IOBIT7 is an output (input when 0).							
	x1xxxxxx								IOBIT6 is an output (input when 0).							
	xx1xxxxx								IOBIT5 is an output (input when 0).							
	xxx1xxxx								IOBIT4 is an output (input when 0).							
	xxxx1xxx								IOBIT3 is an output (input when 0).							
	xxxxx1xx								IOBIT2 is an output (input when 0).							
	xxxxxx1x								IOBIT1 is an output (input when 0).							
	xxxxxxx1								IOBIT0 is an output (input when 0).							
VALUE	Rxxxxxxx								Reads the current value of IOBIT7.							
	xRxxxxxx								Reads the current value of IOBIT6.							
	xxRxxxxx								Reads the current value of IOBIT5.							
	xxxRxxxx								Reads the current value of IOBIT4.							
	xxxxRxxx								Reads the current value of IOBIT3.							
	xxxxxRxx								Reads the current value of IOBIT2.							
	xxxxxxRx								Reads the current value of IOBIT1.							
	xxxxxxxR								Reads the current value of IOBIT0.							

Table 34. cbit Register

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Field	MODE/MASK[7:4]				MODE/MASK[3:0]				DATA/PAT[7:4]				DATA/PAT[3:0]			
DIREC[n]*				MODE/MASK[n]				DATA/PAT[n]				Action				
1 (Output)				0				0				Clear				
1 (Output)				0				1				Set				
1 (Output)				1				0				No Change				
1 (Output)				1				1				Toggle				
0 (Input)				0				0				No Test				
0 (Input)				0				1				No Test				
0 (Input)				1				0				Test for Zero				
0 (Input)				1				1				Test for One				

* $0 \leq n \leq 7$.

5 Software Architecture (continued)**Table 35. alf Register**

Bit	15	14	13—0
Field	AWAIT	LOWPR	FLAGS
Field	Value	Action	
AWAIT	1 0	Power-saving standby mode or standard sleep enabled. Normal operation.	
LOWPR	1 0	The internal DPRAM is addressed beginning at 0x0000 in X space. The internal DPRAM is addressed beginning at 0xc000 in X space.	
FLAGS	—	See the following table.	
Bit	Flag	Use	
13—8	Reserved	—	
7	nmns1	NOT-MINUS-ONE from BMU	
6	mns1	MINUS-ONE from BMU	
5	evenp	EVEN PARITY from BMU	
4	oddp	ODD PARITY from BMU	
3	somef	SOME FALSE from BIO	
2	somet	SOME TRUE from BIO	
1	allf	ALL FALSE from BIO	
0	allt	ALL TRUE from BIO	

Table 36. mwait Register

Bit	15—12	11—8	7—4	3—0
Field	EROM[3:0]	ERAMHI[3:0]	IO[3:0]	ERAMLO[3:0]

If the EXM pin is high and the INT1 is low upon reset, the mwait register is initialized to all 1s (15 wait-states for all external memory). Otherwise, the mwait register is initialized to all 0s (0 wait-states) upon reset.

Table 37. DSP1629 32-Bit JTAG ID Register

Bit	31	30	29—28	27—19	18—12	11—0
Field	RSVD	SECURE	CLOCK	ROMCODE	PART ID	0x03B
Field	Value	Mask-Programmable Features				
RSVD	0	—				
SECURE	0	Nonsecure ROM option.				
	1	Secure ROM option.				
CLOCK	01	Small-signal input clock option.				
	11	CMOS level input clock option.				
ROMCODE	—	Users ROMCODE ID: The ROMCODE ID is the 9-bit binary value of the following expression: (20 x value for first letter) + (value of second letter), where the values of the letters are in the following table. For example, ROMCODE GK is (20 x 6) + (9) = 129 or 0 1000 0001.				
PART ID	0x29	DSP1629.				

ROMCODE Letter	A	B	C	D	E	F	G	H	J	K	L	M	N	P	R	S	T	U	W	Y
Value	0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19

5 Software Architecture (continued)

Table 38. ioc Register*

Bit	15	14	13	12	11	10	9	8—7	6—4	3—0
Field	RSVD	EXTROM	CKO2	EBIOH	WEROM	ESIO2	SIOLBC	CKO[1:0]	RSVD	DENB[3:0]

* The field definitions for the **ioc** register are different from the DSP1610.

ioc Fields

ioc Field	Description
EXTROM	If 1, sets AB15 low during external memory accesses when WEROM = 1.
CKO2	CKO configuration (see the following table).
EBIOH	If 1, enables the high half of BIO, IOBIT[4:7], and disables VEC[3:0] from pins.
WEROM	If 1, allows writing into external program (X) memory.
ESIO2	If 1, enables SIO2 and low half of BIO, and disables PHIF from pins.
SIOLBC	If 1, DO1 and DO2 looped back to DI1 and DI2.
CKO[1:0]	CKO configuration (see the following table).
DENB3	If 1, delay EROM.
DENB2	If 1, delay ERAMHI.
DENB1	If 1, delay IO.
DENB0	If 1, delay ERAMLO.

CKO2	CKO1	CKO0	CKO Output		Description
—	—	—	1X	PLL	—
0	0	0	CKI	$CKI \times M/(2N)$	Free-running clock. [*] , [†]
0	0	1	$CKI/(1 + W)$	$CKI \times (M/(2N))/(1 + W)$	Wait-stated clock. [*] , [†] , [‡]
0	1	0	1	1	Held high.
0	1	1	0	0	Held low.
1	0	0	CKI	CKI	Output of CKI buffer.
1	0	1	$CKI/(1 + W)$	$CKI \times (M/(2N))/(1 + W)$	Sequenced, wait-stated clock. [*] , [†] , [‡] , ^{**}
1	1	0	Reserved.		
1	1	1	Reserved.		

* The phase of CKI is synchronized by the rising edge of RSTB.

† When SLOWCKI is enabled in the powerc register, these options reflect the low-speed internal ring oscillator.

‡ The wait-stated clock reflects the internal instruction cycle and may be stretched based on the mwait register setting (see Table 36, mwait Register). During sequenced external memory accesses, it completes one cycle.

** The sequenced wait-stated clock completes two cycles during a sequenced external memory access and may be stretched based on the mwait register setting (see Table 36, mwait Register).

5 Software Architecture (continued)**Table 39. powerc Register**

The **powerc** register configures various power management modes.

Bit	15	14	13	12	11	10	9—8	7	6	5	4	3—0
Field	XTLOFF	SLOWCKI	NOCK	INT0EN	RSVD	INT1EN	RSVD	SIO1DIS	SIO2DIS	PHIFDIS	TIMERDIS	RSVD

Note: The reserved (RSVD) bits should always be written with zeros to make the program compatible with future chip versions.

powerc fields

Field	Description
XTLOFF	1 = powerdown small-signal clock input.
SLOWCKI	1 = select ring oscillator clock (internal slow clock).
NOCK	1 = disable internal processor clock.
INT0EN	1 = INT0 clears NOCK field.
INT1EN	1 = INT1 clears NOCK field.
SIO1DIS	1 = disable SIO1.
SIO2DIS	1 = disable SIO2.
PHIFDIS	1 = disable PHIF.
TIMERDIS	1 = disable timer.

A • indicates that this bit is unknown on powerup reset and unaffected on subsequent reset. An S indicates that this bit shadows the PC. P indicates the value on an input pin, i.e., the bit in the register reflects the value on the corresponding input pin.

Table 40. Register Settings After Reset

Register	Bits 15—0	Register	Bits 15—0
r0	••••••••••	ybase	••••••••••
r1	••••••••••	inc	0000000000000000
r2	••••••~•••	ins	0000010000000110
r3	••••••~•••	sdx2	••••••~•••
j	••••••~•••	saddx	••••••~•••
k	••••••~•••	cloop	00000000••••••
rb	0000000000000000	mwait	0000000000000000†
re	0000000000000000	saddx2	••••••~•••
pt	••••••~•••	sioc2	••••••0000000000
pr	••••••~•••	cbit	••••••~•••
pi	SSSSSSSSSSSSSSSS	sbit	00000000PPPPPPPP
i	••••••~•••	ioc	0000000000000000
p	••••••~•••	jtag	••••••~•••
pl	••••••~•••	a0	••••••~•••
x	••••••~•••	a0l	••••••~•••
y	••••~•••••	a1	••••~•••••
yl	••••~•••••	a1l	••••~•••••
auc	0000000000000000	timerc	••••••00000000
psw	••••00••••••	timer0	0000000000000000
c0	••••~•••••	tdms2	••••••0000000000
c1	••••~•••••	srta2	••••~•••••
c2	••••~•••••	powerc	0000000000000000
sioc	••••••0000000000	pll	0000000000000000
srta	••••~•••••	ar0	••••~•••••
sdx	••••~•••••	ar1	••••~•••••
tdms	••••••0000000000	ar2	••••~•••••
phifc	0000000000000000	ar3	••••~•••••
pdx0	0000000000000000	alf	00000000••••~•••

† If EXM is high and INT1 is low when RSTB goes high, mwait will contain all ones instead of all zeros.

5 Software Architecture (continued)

5.3 Instruction Set Formats

This section defines the hardware-level encoding of the DSP1629 device instructions.

Multiply/ALU Instructions

Format 1: Multiply/ALU Read/Write Group

Field	T					D	S	F1				X	Y			
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0

Format 1a: Multiply/ALU Read/Write Group

Field	T					aT	S	F1				X	Y			
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0

Format 2: Multiply/ALU Read/Write Group

Field	T					D	S	F1				X	Y			
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0

Format 2a: Multiply/ALU Read/Write Group

Field	T					aT	S	F1				X	Y			
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0

Special Function Instructions

Format 3: F2 ALU Special Functions

Field	T					D	S	F2				CON				
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0

Format 3a: F3 ALU Operations

Field	T					D	S	F3				SRC2		aT	0	1
	Immediate Operand (IM16)															
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0

Format 3b: BMU Operations

Field	T					D	S	F4[3—1]			0	F4[0]	AR			
	Immediate Operand (IM16)															
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0

5 Software Architecture (continued)

Control Instructions

Format 4: Branch Direct Group

Field	T				JA											
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0

Format 5: Branch Indirect Group

Field	T					B			Reserved							0
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0

Format 6: Conditional Branch Qualifier/Software Interrupt (icall)

Note that a branch instruction immediately follows except for a software interrupt (icall).

Field	T					SI	Reserved				CON					
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0

Data Move Instructions

Format 7: Data Move Group

Field	T					aT	R						Y/Z			
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0

Format 8: Data Move (immediate operand—2 words)

Field	T					D	R						Reserved			
	Immediate Operand (IM16)															
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0

Format 9: Short Immediate Group

Field	T					I		Short Immediate Operand (IM9)								
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0

Format 9a: Direct Addressing

Field	T					R/W	DR				1	OFFSET				
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0

Cache Instructions

Format 10: Do/Redo

Field	T					N				K						
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0

5 Software Architecture (continued)**Field Descriptions****Table 41. T Field**

Specifies the type of instruction.

T	Operation	Format
0000x	goto JA	4
00010	Short imm j, k, rb, re	9
00011	Short imm r0, r1, r2, r3	9
00100	Y = a1[l] F1	1
00101	Z:aT[l] F1	2a
00110	Y F1	1
00111	aT[l] = Y F1	1a
01000	Bit 0 = 0, aT = R	7
01000	Bit 0 = 1, aTl = R	7
01001	Bit 10 = 0, R = a0	7
01001	Bit 10 = 1, R = a0l	7
01010	R = IM16	8
01011	Bit 10 = 0, R = a1	7
01011	Bit 10 = 1, R = a1l	7
01100	Y = R	7
01101	Z:R	7
01110	do, redo	10
01111	R = Y	7
1000x	call JA	4
10010	ifc CON F2	3
10011	if CON F2	3
10100	Y = y[l] F1	1
10101	Z:y[l] F1	2
10110	x = Y F1	1
10111	y[l] = Y F1	1
11000	Bit 0 = 0, branch indirect	5
11000	Bit 0 = 1, F3 ALU	3a
11001	y = a0 x = X F1	1
11010	Conditional branch qualifier	6
11011	y = a1 x = X F1	1
11100	Y = a0[l] F1	1
11101	Z:y x = X F1	2
11110	Bit 5 = 0, F4 ALU (BMU)	3b
11110	Bit 5 = 1, direct addressing	9a
11111	y = Y x = X F1	1

Table 42. D Field

Specifies a destination accumulator.

D	Register
0	Accumulator 0
1	Accumulator 1

Table 43. aT Field

Specifies transfer accumulator.

aT	Register
0	Accumulator 1
1	Accumulator 0

Table 44. S Field

Specifies a source accumulator.

S	Register
0	Accumulator 0
1	Accumulator 1

Table 45. F1 Field

Specifies the multiply/ALU function.

F1	Operation
0000	aD = pp = x * y
0001	aD = aS + pp = x * y
0010	p = x * y
0011	aD = aS - pp = x * y
0100	aD = p
0101	aD = aS + p
0110	nop
0111	aD = aS - p
1000	aD = aS y
1001	aD = aS ^ y
1010	aS & y
1011	aS - y
1100	aD = y
1101	aD = aS + y
1110	aD = aS & y
1111	aD = aS - y

Table 46. X Field

Specifies the addressing of ROM data in two-operand multiply/ALU instructions. Specifies the high or low half of an accumulator, or the y register in one-operand multiply/ALU instructions.

X	Operation
Two-Operand Multiply/ALU	
0	*pt++
1	*pt++i
One-Operand Multiply/ALU	
0	aTl, yl
1	aTh, yh

5 Software Architecture (continued)

Table 47. Y Field

Specifies the form of register indirect addressing with postmodification.

Y	Operation
0000	*r0
0001	*r0++
0010	*r0--
0011	*r0++j
0100	*r1
0101	*r1++
0110	*r1--
0111	*r1++j
1000	*r2
1001	*r2++
1010	*r2--
1011	*r2++j
1100	*r3
1101	*r3++
1110	*r3--
1111	*r3++j

Table 48. Z Field

Specifies the form of register indirect compound addressing with postmodification.

Z	Operation
0000	*r0zp
0001	*r0pz
0010	*r0m2
0011	*r0jk
0100	*r1zp
0101	*r1pz
0110	*r1m2
0111	*r1jk
1000	*r2zp
1001	*r2pz
1010	*r2m2
1011	*r2jk
1100	*r3zp
1101	*r3pz
1110	*r3m2
1111	*r3jk

Table 49. F2 Field

Specifies the special function to be performed.

F2	Operation
0000	aD = aS >> 1
0001	aD = aS << 1
0010	aD = aS >> 4
0011	aD = aS << 4
0100	aD = aS >> 8
0101	aD = aS << 8
0110	aD = aS >> 16
0111	aD = aS << 16
1000	aD = p
1001	aDh = aSh + 1
1010	aD = ~aS
1011	aD = rnd(aS)
1100	aD = y
1101	aD = aS + 1
1110	aD = aS
1111	aD = -aS

Table 50. CON Field

Specifies the condition for special functions and conditional control instructions.

CON	Condition	CON	Condition
00000	mi	01110	true
00001	pl	01111	false
00010	eq	10000	gt
00011	ne	10001	le
00100	lvs	10010	allt
00101	lvc	10011	allf
00110	mvs	10100	somet
00111	mvc	10101	somef
01000	heads	10110	oddp
01001	tails	10111	evenp
01010	c0ge	11000	mns1
01011	c0lt	11001	nmns1
01100	c1ge	11010	npint
01101	c1lt	11011	njint
		11100	lock
Other codes	Reserved	—	—

5 Software Architecture (continued)

Table 51. R Field

Specifies the register for data move instructions.

R	Register	R	Register
000000	r0	100000	inc
000001	r1	100001	ins
000010	r2	100010	sdx2
000011	r3	100011	saddx
000100	j	100100	cloop
000101	k	100101	mwait
000110	rb	100110	saddx2
000111	re	100111	sioc2
001000	pt	101000	cbit
001001	pr	101001	sbit
001010	pi	101010	ioc
001011	i	101011	jtag
001100	p	101100	Reserved
001101	pl	101101	Reserved
001110	pllc	101110	Reserved
001111	Reserved	101111	Reserved
010000	x	110000	a0
010001	y	110001	a0l
010010	yl	110010	a1
010011	auc	110011	a1l
010100	psw	110100	timerc
010101	c0	110101	timer0
010110	c1	110110	tdms2
010111	c2	110111	srta2
011000	sioc	111000	powerc
011001	srta	111001	Reserved
011010	sdx	111010	ar0
011011	tdms	111011	ar1
011100	phifc	111100	ar2
011101	pdx0	111101	ar3
011110	Reserved	111110	Reserved
011111	ybase	111111	alf

Table 52. B Field

Specifies the type of branch instruction (except software interrupt).

B	Operation
000	return
001	ireturn
010	goto pt
011	call pt
1xx	Reserved

Table 53. DR Field

DR Value	Register
0000	r0
0001	r1
0010	r2
0011	r3
0100	a0
0101	a0l
0110	a1
0111	a1l
1000	y
1001	yl
1010	p
1011	pl
1100	x
1101	pt
1110	pr
1111	psw

Table 54. I Field

Specifies a register for short immediate data move instructions.

I	Register
00	r0/j
01	r1/k
10	r2/rb
11	r3/re

Table 55. SI Field

Specifies when the conditional branch qualifier instruction should be interpreted as a software interrupt instruction.

SI	Operation
0	Not a software interrupt
1	Software interrupt

5 Software Architecture (continued)

N Field

Number of instructions to be loaded into the cache. Zero implies redo operation.

K Field

Number of times the N instructions in cache are to be executed. Zero specifies use of value in **cloop** register.

JA Field

12-bit jump address.

R/W Field

A zero specifies a write, *(O) = DR.

A one specifies a read, DR = *(O).

Table 56. F3 Field

Specifies the operation in an F3 ALU instruction.

F3	Operation		
1000	$aD = aS[h, l]$		{aT, IM16, p}
1001	$aD = aS[h, l]$	^	{aT, IM16, p}
1010	$aS[h, l]$	&	{aT, IM16, p}
1011	$aS[h, l]$	–	{aT, IM16, p}
1101	$aD = aS[h, l]$	+	{aT, IM16, p}
1110	$aD = aS[h, l]$	&	{aT, IM16, p}
1111	$aD = aS[h, l]$	–	{aT, IM16, p}

Table 57. SRC2 Field

Specifies operands in an F3 ALU instruction.

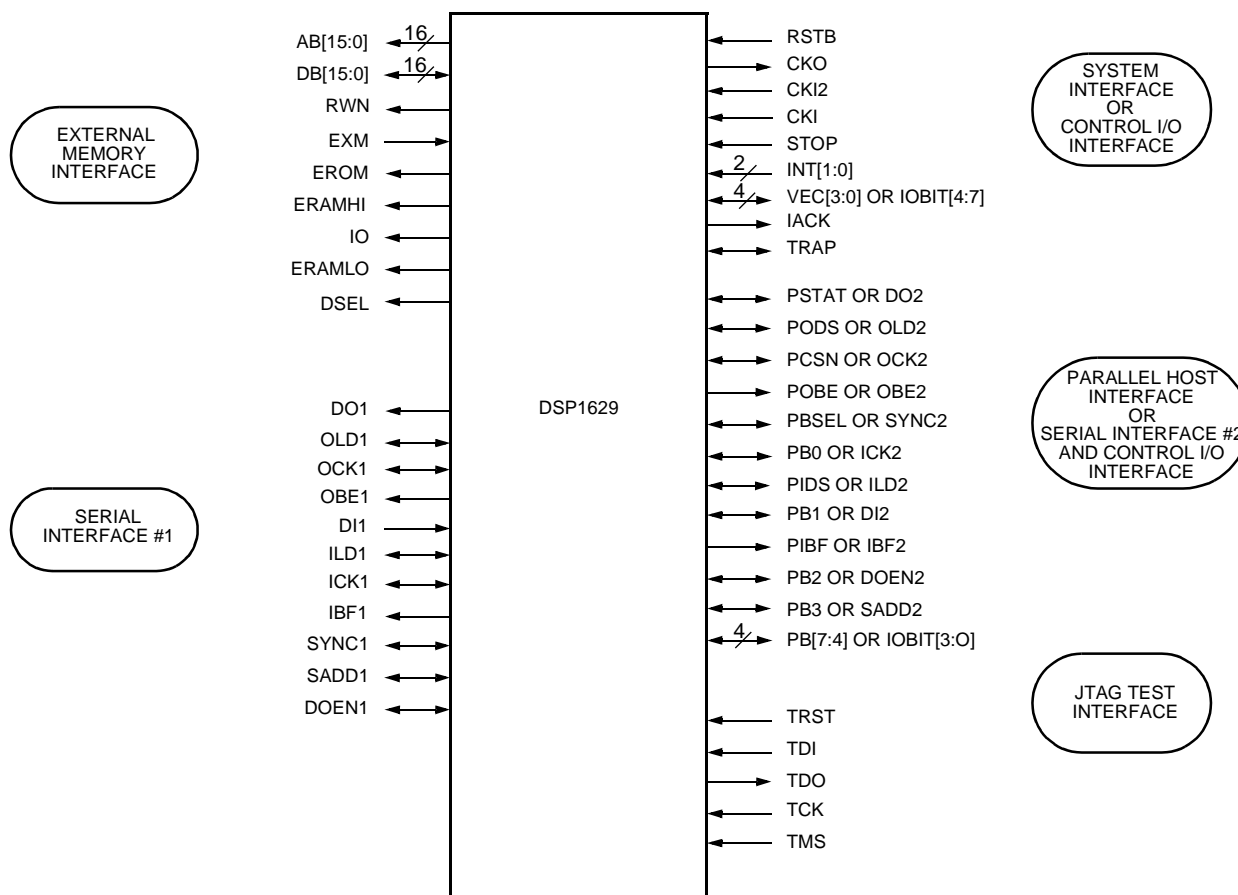
SRC2	Operands
00	aSl, IM16
10	aSh, IM16
01	aS, aT
11	aS, p

Table 58. BMU Encodings

F4	AR	Operation
0000	00xx	$aD = aS \gg arM$
0001	00xx	$aD = aS \ll arM$
0000	10xx	$aD = aS \ggg arM$
0001	10xx	$aD = aS \lll arM$
1000	0000	$aD = \overline{aS} \gg aS$
1001	0000	$aD = \overline{aS} \ll aS$
1000	1000	$aD = \overline{aS} \ggg aS$
1001	1000	$aD = \overline{aS} \lll aS$
1100	0000	$aD = aS \gg IM16$
1101	0000	$aD = aS \ll IM16$
1100	1000	$aD = aS \ggg IM16$
1101	1000	$aD = aS \lll IM16$
0000	1100	$aD = \exp(aS)$
0001	11xx	$aD = \text{norm}(aS, arM)$
1110	0000	$aD = \text{extracts}(aS, IM16)$
0010	00xx	$aD = \text{extracts}(aS, arM)$
1110	0100	$aD = \text{extractz}(aS, IM16)$
0010	01xx	$aD = \text{extractz}(aS, arM)$
1110	1000	$aD = \text{insert}(aS, IM16)$
1010	10xx	$aD = \text{insert}(aS, arM)$
0111	0000	$aD = aS:aa0$
0111	0001	$aD = aS:aa1$

Note: xx encodes the auxiliary register to be used; 00 (ar0), 01 (ar1), 10 (ar2), or 11 (ar3).

6 Signal Descriptions



5-4006 (F).i

Figure 9. DSP1629 Pinout by Interface

Figure 9, DSP1629 Pinout by Interface, shows the pinout for the DSP1629. The signals can be separated into five interfaces, as shown. These interfaces and the signals that comprise them are described in Section 6.1, System Interface.

6.1 System Interface

The system interface consists of the clock, interrupt, and reset signals for the processor.

RSTB

Reset: Negative assertion. A high-to-low transition causes the processor to enter the reset state. The auc, powerc, sioc, sioc2, phifc, pdx0, tdms, tdms2, timerc, timer0, sbit (upper byte), inc, ins (except OBE, OBE2,

and PODS status bits set), alf (upper 2 bits, AWAIT and LOWPR), ioc, rb, and re registers are cleared. The mwait register is initialized to all 0s (zero wait-states) unless the EXM pin is high and the INT1 pin is low. In that case, the mwait register is initialized to all 1s (15 wait-states).

Reset clears IACK, VEC[3:0]/IOBIT[4:7], IBF, and IBF2. The DAU condition flags are not affected by reset. IOBIT[7:0] are initialized as inputs. If any of the IOBIT pins are switched to outputs (by writing sbit), their initial value will be logic zero (see Table 40, Register Settings After Reset).

Upon negation of the signal, the processor begins execution at location 0x0000 in the active memory map (see Section 4.4, Memory Maps and Wait-States).

6 Signal Descriptions (continued)

CKI

Input Clock: A mask-programmable option selects one of three possible input buffers for the CKI pin (see Section 7, Mask-Programmable Options, and Table 1, Pin Descriptions). The internal CKI from the output of the selected input buffer can then drive the internal processor clock directly (1X) or drive the on-chip PLL (see Section 4.13, Power Management). The PLL allows the CKI input clock to be at a lower frequency than the internal processor clock.

CKI2

Input Clock 2: Used with mask-programmable input clock options which require an external small signal differential across CKI and CKI2 (see Table 1, Pin Descriptions). When the CMOS option is selected, this pin should be tied to VSSA.

STOP

Stop Input Clock: Negative assertion. A high-to-low transition synchronously stops all of the internal processor clocks, leaving the processor in a defined state. Returning the pin high will synchronously restart the processor clocks to continue program execution from where it left off, without any loss of state. This hardware feature has the same effect as setting the NOCK bit in the powerc register (see Table 39, powerc Register).

CKO

Clock Out: Buffered output clock with options programmable via the ioc register (see Table 38, ioc Register). The selectable CKO options (see Table 38, ioc Register and Table 29, Interrupt Control (inc) Register) are as follows:

- A free-running output clock at the frequency of the internal processor clock; runs at the internal ring oscillator frequency when SLOWCKI is enabled.
- A wait-stated clock based on the internal instruction cycle; runs at the internal ring oscillator frequency when SLOWCKI is enabled.
- A sequenced, wait-stated clock based on the EMI sequencer cycle; runs at the internal ring oscillator frequency when SLOWCKI is enabled.
- A free-running output clock that runs at the CKI rate, independent of the powerc register setting. This option is only available with the small-signal clock options. When the PLL is selected, the CKO frequency equals the input CKI frequency, regardless of how the

PLL is programmed.

- A logic 0.
- A logic 1.

INT[1:0]

Processor Interrupts 0 and 1: Positive assertion. Hardware interrupt inputs to the DSP1629. Each is enabled via the inc register. When enabled and asserted, each cause the processor to vector to the memory location described in Table 4, Interrupt Vector Table. INT1 is used in conjunction with EXM to select the desired reset initialization of the mwait register (see Table 36, mwait Register). When both INT0 and RSTB are asserted, all output and bidirectional pins (except TDO, which 3-states by JTAG control) are put in a 3-state condition.

VEC[3:0]

Interrupt Output Vector: These four pins indicate which interrupt is currently being serviced by the device. Table 4, Interrupt Vector Table, shows the code associated with each interrupt condition. VEC[3:0] are multiplexed with IOBIT[4:7].

IACK

Interrupt Acknowledge: Positive assertion. IACK signals when an interrupt is being serviced by the DSP1629. IACK remains asserted while in an interrupt service routine, and is cleared when the ireturn instruction is executed.

TRAP

Trap Signal: Positive assertion. When asserted, the processor is put into the trap condition, which normally causes a branch to the location 0x0046. The hardware development system (HDS) can configure the trap pin to cause an HDS trap, which causes a branch to location 0x0003. Although normally an input, the pin can be configured as an output by the HDS. As an output, the pin can be used to signal an HDS breakpoint in a multiple processor environment.

6 Signal Descriptions (continued)

6.2 External Memory Interface

The external memory interface is used to interface the DSP1629 to external memory and I/O devices. It supports read/write operations from/to program and data memory spaces. The interface supports four external memory segments. Each external memory segment can have an independent number of software-programmable wait-states. One hardware address is decoded, and an enable line is provided, to allow glueless I/O interfacing.

AB[15:0]

External Memory Address Bus: Output only. This 16-bit bus supplies the address for read or write operations to the external memory or I/O. During external memory accesses, AB[15:0] retain the value of the last valid external access.

DB[15:0]

External Memory Data Bus: This 16-bit bidirectional data bus is used for read or write operations to the external memory or I/O.

RWN

Read/Write Not: When a logic 1, the pin indicates that the memory access is a read operation. When a logic 0, the memory access is a write operation.

EXM

External Memory Select: Input only. This signal is latched into the device on the rising edge of RSTB. The value of EXM latched in determines whether the internal ROM is addressable in the instruction/coefficient memory map. If EXM is low, internal ROM is addressable. If EXM is high, only external ROM is addressable in the instruction/coefficient memory map (see Table 5, Instruction/Coefficient Memory Maps). EXM chooses between MAP1 or MAP2 and between MAP3 or MAP4.

EROM

External ROM Enable Signal: Negative assertion. When asserted, the signal indicates an access to external program memory (see Table 5, Instruction/Coefficient Memory Maps). This signal's leading edge can be delayed via the ioc register (see Table 38, ioc Register).

ERAMHI

External RAM High Enable Signal: Negative assertion. When asserted, the signal indicates an access to external data memory addresses 0x8000 through 0xFFFF (see Table 6, Data Memory Maps). This signal's leading edge can be delayed via the ioc register (see Table 38, ioc Register).

ERAMLO

External RAM Low Enable Signal: Negative assertion. When asserted, the signal indicates an access to external data memory addresses 0x4100 through 0x7FFF (see Table 6, Data Memory Maps). This signal's leading edge can be delayed via the ioc register (see Table 38, ioc Register).

I/O

External I/O Enable Signal: Negative assertion. When asserted, the signal indicates an access to external data memory addresses 0x4000 through 0x40FF (see Table 6, Data Memory Maps). This memory segment is intended for memory-mapped I/O. This signal's leading edge can be delayed via the ioc register (see Table 38, ioc Register).

6 Signal Descriptions (continued)

6.3 Serial Interface #1

The serial interface pins implement a full-featured synchronous/asynchronous serial I/O channel. In addition, several pins offer a glueless TDM interface for multiprocessor communication applications (see Figure 6, Multiprocessor Communication and Connections).

DI1

Data Input: Serial data is latched on the rising edge of ICK1, either LSB or MSB first, according to the sioc register MSB field (see Table 22, Serial I/O Control Registers).

ICK1

Input Clock: The clock for serial input data. In active mode, ICK1 is an output; in passive mode, ICK1 is an input, according to the sioc register ICK field (see Table 22, Serial I/O Control Registers). Input typically has 0.7 V hysteresis.

ILD1

Input Load: The clock for loading the input buffer, sdx[in], from the input shift register isr. A falling edge of ILD1 indicates the beginning of a serial input word. In active mode, ILD1 is an output; in passive mode, ILD1 is an input, according to the sioc register ILD field (see Table 22, Serial I/O Control Registers). Input typically has 0.7 V hysteresis.

IBF1

Input Buffer Full: Positive assertion. IBF1 is asserted when the input buffer, sdx[in], is filled. IBF1 is negated by a read of the buffer, as in a0 = sdx. IBF1 is also negated by asserting RSTB.

DO1

Data Output: The serial data output from the output shift register (osr), either LSB or MSB first (according to the sioc register MSB field). DO1 changes on the rising edges of OCK1. DO1 is 3-stated when DOEN1 is high.

DOEN1

Data Output Enable: Negative assertion. An input when not in the multiprocessor mode. DO1 and SADD1 are enabled only if DOEN1 is low. DOEN1 is bidirectional when in the multiprocessor mode (tdms register MODE field set). In the multiprocessor mode, DOEN1 indicates a valid time slot for a serial output.

OCK1

Output Clock: The clock for serial output data. In active mode, OCK1 is an output; in passive mode, OCK1 is an input, according to the sioc register OCK field (see Table 22, Serial I/O Control Registers). Input typically has 0.7 V hysteresis.

OLD1

Output Load: The clock for loading the output shift register, osr, from the output buffer sdx[out]. A falling edge of OLD1 indicates the beginning of a serial output word. In active mode, OLD1 is an output; in passive, OLD1 is an input, according to the sioc register OLD field (see Table 22, Serial I/O Control Registers). Input typically has 0.7 V hysteresis.

OBE1

Output Buffer Empty: Positive assertion. OBE1 is asserted when the output buffer, sdx[out], is emptied (moved to the output shift register for transmission). It is cleared with a write to the buffer, as in sdx = a0. OBE1 is also set by asserting RSTB.

SADD1

Serial Address: Negative assertion. A 16-bit serial bit stream typically used for addressing during multiprocessor communication between multiple DSP16xx devices. In multiprocessor mode, SADD1 is an output when the tdms time slot dictates a serial transmission; otherwise, it is an input. Both the source and destination DSP can be identified in the transmission. SADD1 is always an output when not in multiprocessor mode and can be used as a second 16-bit serial output. See the *DSP1611/17/18/27/28/29 Digital Signal Processor Information Manual* for additional information. SADD1 is 3-stated when DOEN1 is high. When used on a bus, SADD1 should be pulled high through a 5 k Ω resistor.

SYNC1

Multiprocessor Synchronization: Typically used in the multiprocessor mode, a falling edge of SYNC1 indicates the first word (time slot 0) of a TDM I/O stream and causes the resynchronization of the active ILD1 and OLD1 generators. SYNC1 is an output when the tdms register SYNC field is set (i.e., selects the master DSP and uses time slot 0 for transmit). As an input, SYNC1 must be tied low unless part of a TDM interface. When used as an output, SYNC1 = [ILD1/OLD1]/8 or 16, depending on the setting of the SYNCSP field of the tdms register. When configured as described above, SYNC1 can be used to generate a slow clock for SIO operations. Input typically has 0.7 V hysteresis.

6 Signal Descriptions (continued)

6.4 Parallel Host Interface or Serial Interface #2 and Control I/O Interface

This interface pin multiplexes a parallel host interface with a second serial I/O interface and a 4-bit I/O interface. The interface selection is made by writing the ESIO2 bit in the ioc register (see Table 38, ioc Register and Section 4.1, DSP1629 Architectural Overview). The functions and signals for the second SIO correspond exactly with those in SIO #1. Therefore, the following pin descriptions discuss only PHIF and BIO pin functionality.

PB[7:0]

Parallel I/O Data Bus: This 8-bit bidirectional bus is used to input data to, or output data from, the PHIF.

Note that PB[3:0] are pin multiplexed with SIO2 functionality, and PB[7:4] are pin multiplexed with BIO unit pins IOBIT[3:0] (see Section 4.1, DSP1629 Architectural Overview).

PCSN

Peripheral Chip Select Not: Negative assertion. PCSN is an input. While PCSN is low, the data strobes PIDS and PODS are enabled. While PCSN is high, the DSP1629 ignores any activity on PIDS and PODS.

PBSEL

Peripheral Byte Select: An input pin, configurable in software. Selects the high or low byte of pdx0 available for host accesses.

PSTAT

Peripheral Status Select: PSTAT is an input. When a logic 0, the PHIF will output the pdx0[out] register on the PB bus. When a logic 1, the PHIF will output the contents of the PSTAT register on PB[7:0].

PIDS

Parallel Input Data Strobe: An input pin, software configurable to support both *Intel* and *Motorola* protocols.

In *Intel* mode: negative assertion. PIDS is pulled low by an external device to indicate that data is available on the PB bus. The DSP latches data on the PB bus on the rising edge (low-to-high transition) of PIDS or PCSN, whichever comes first.

In *Motorola* mode: PIDS/PRWN functions as a read/write strobe. The external device sets PIDS/PRWN to a logic 0 to indicate that data is available on the PB bus (write operation by the external device). A logic 1 on

PIDS/PRWN indicates an external read operation by the external device.

PODS

Parallel Output Data Strobe: An input pin, software configurable to support both *Intel* and *Motorola* protocols.

In *Intel* mode: negative assertion. When PODS is pulled low by an external device, the DSP1629 places the contents of the parallel output register, pdx0, onto the PB bus.

In *Motorola* mode: software-configurable assertion level. The external device uses PODS/PDS as its data strobe for both read and write operations.

PIBF

Parallel Input Buffer Full: An output pin with positive assertion; configurable in software. This flag is cleared after reset, indicating an empty input buffer pdx0[in].

PIBF is set immediately after the rising edge of PIDS or PCSN, indicating that data has been latched into the pdx0[in] register. When the DSP1629 reads the contents of this register, emptying the buffer, the flag is cleared.

Configured in software, PIBF may become the logical OR of the PIBF and POBE flags.

POBE

Parallel Output Buffer Empty: An output pin with positive assertion; configurable in software. This flag is set after reset, indicating an empty output buffer pdx0[out].

POBE is set immediately after the rising edge of PODS or PCSN, indicating that the data in pdx0[out] has been driven onto the PB bus. When the DSP1629 writes to pdx0[out], filling the buffer, this flag is cleared.

6.5 Control I/O Interface

This interface is used for status and control operations provided by the bit I/O unit of the DSP1629. It is pin multiplexed with the PHIF and VEC[3:0] pins (see Section 4.1, DSP1629 Architectural Overview). Setting the ESIO2 and EBIOH bits in the ioc register provides a full 8-bit BIO interface at the associated pins.

IOBIT[7:0]

I/O Bits [7:0]: Each of these bits can be independently configured as either an input or an output. As outputs, they can be independently set, toggled, or cleared. As inputs, they can be tested independently or in combinations for various data patterns.

6 Signal Descriptions (continued)

6.6 JTAG Test Interface

The JTAG test interface has features that allow programs and data to be downloaded into the DSP via four pins. This provides extensive test and diagnostic capability. In addition, internal circuitry allows the device to be controlled through the JTAG port to provide on-chip in-circuit emulation. Agere Systems provides hardware and software tools to interface to the on-chip HDS via the JTAG port.

Note: The DSP1629 provides all JTAG/*IEEE* 1149.1 standard test capabilities, including boundary scan. See the *DSP1611/17/18/27/28/29 Digital Signal Processor* Information Manual for additional information on the JTAG test interface.

TDI

Test Data Input: JTAG serial input signal. All serial-scanned data and instructions are input on this pin. This pin has an internal pull-up resistor.

TDO

Test Data Output: JTAG serial output signal. Serial-scanned data and status bits are output on this pin.

TMS

Test Mode Select: JTAG mode control signal that, when combined with TCK, controls the scan operations. This pin has an internal pull-up resistor.

TCK

Test Clock: JTAG serial shift clock. This signal clocks all data into the port through TDI, and out of the port through TDO, and controls the port by latching the TMS signal inside the state-machine controller.

TRST

Test Reset: Negative assertion. JTAG test reset. When asserted low, asynchronously resets JTAG TAP controller. In an application environment, this pin must be asserted prior to or concurrent with RSTB. This pin has an internal pull-up resistor.

7 Mask-Programmable Options

The DSP1629 contains a ROM that is mask-programmable. The selection of several programmable features is made when a custom ROM is encoded. These features select the input clock options, the instruction/coefficient memory map option, and the hardware emulation or ROM security option, as summarized in Table 59, DSP1629 ROM Options.

Table 59. DSP1629 ROM Options

Features	Options	Comments
Input Clock	CMOS Level Small Signal	2.7 V and 3 V. 2.7 V and 3 V.
Memory Map	DSP1629x16 DSP1629x10	16 Kwords DPRAM. 10 Kwords DPRAM.
ROM Security	Nonsecure Secure	Specify and link 1629hds.v# [*] , allows emulation. Specify and link crc16.v# [†] , no emulation capability.

* 1629hds.v# (# indicates the current version number) is the relocatable HDS object code. It uses approximately 140 words and must reside in the first 4 Kwords of ROM.

† crc16.v# is the cyclic redundancy check object code. It uses approximately 75 words and must reside in the first 4 Kwords of ROM. See the *DSP1600 Support Tools Manual* for detailed information.

7.1 Input Clock Options

For all input options, the input clock CKI can run at some fraction of the internal clock frequency by setting the PLL multiplication factors appropriately (see Section 4.12, Clock Synthesis). When the PLL is bypassed, the input clock CKI frequency is the internal clock frequency.

7.2 Memory Map Options

The DSP1629 offers a DSP1629x16 or a DSP1629x10, where the difference is in the memory maps. The DSP1629x16 contains 16 Kwords of internal RAM (DPRAM). The DSP1629x10 supports the use of only 10 Kwords of DPRAM. See Section 4.4, Memory Maps and Wait-States, for further description.

7.3 ROM Security Options

The DSP1600 hardware development system (HDS) provides on-chip in-circuit emulation and requires that the relocatable HDS code be linked to the application code. This code's object file is called 1629hds.v#, where # is a unique version identifier. Refer to the DSP1629-ST software tools release for more specific information. If on-chip, in-circuit emulation is desired, a nonsecure ROM must be chosen. If ROM security is desired with the DSP1629, the HDS cannot be used. To provide testing of the internal ROM contents on a secure ROM device, a cyclic redundancy check (CRC) program is called by and linked with the user's source code. The CRC code resides in the first 4 Kwords of ROM.

See the *DSP1600 Support Tools Manual* for more detailed information.

8 Device Characteristics

8.1 Absolute Maximum Ratings

Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. These are absolute stress ratings only. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of the data sheet. Exposure to absolute maximum ratings for extended periods can adversely affect device reliability.

External leads can be bonded and soldered safely at temperatures of up to 300 °C. (TBD for 144-pin PBGA.)

Voltage Range on VDD with Respect to Ground Using Devices Designed

for 3 V Operation -0.5 V to +4.6 V

Voltage Range on Any Pin VSS - 0.5 V to VDD + 0.5 V

Power Dissipation 1 W

Ambient Temperature Range -40 °C to +85 °C

Storage Temperature Range -65 °C to +150 °C

8.2 Handling Precautions

All MOS devices must be handled with certain precautions to avoid damage due to the accumulation of static charge. Although input protection circuitry has been incorporated into the devices to minimize the effect of this static buildup, proper precautions should be taken to avoid exposure to electrostatic discharge during handling and mounting. Agere Systems employs a human-body model for ESD-susceptibility testing. Since the failure voltage of electronic devices is dependent on the current, voltage, and hence, the resistance and capacitance, it is important that standard values be employed to establish a reference by which to compare test data. Values of 100 pF and 1500 Ω are the most common and are the values used in the Agere Systems human-body model test circuit. The breakdown voltage for the DSP1629 is greater than 2000 V.

8.3 Recommended Operating Conditions

Table 60. Recommended Operating Conditions

Maximum Instruction Rate (MIPS)	Device Speed	Input Clock	Package	Supply Voltage VDD (V)		Ambient Temperature TA (°C)	
				Min	Max	Min	Max
52	19.2 ns	CMOS, Small-signal	PBGA BQFP or TQFP	2.7	3.3	-40	85
80	12.5 ns	CMOS, Small-signal	PBGA BQFP or TQFP	2.7	3.3	-40	85
60	16.7 ns	CMOS, Small-signal	PBGA BQFP or TQFP	3.0	3.6	-40	85
100	10 ns	CMOS, Small-signal	PBGA BQFP or TQFP	3.0	3.6	-40	85

The ratio of the instruction cycle rate to the input clock frequency is 1:1 without the PLL (referred to as 1X operation), and M/(2N) with the PLL selected (see Section 4.12, Clock Synthesis). Device speeds greater than 50 MIPS do not support 1X operation; use the PLL.

8 Device Characteristics (continued)

8.4 Package Thermal Considerations

The recommended operating temperature specified in Section 8.3, Recommended Operating Conditions, is based on the maximum power, package type, and maximum junction temperature. The following equations describe the relationship between these parameters. If the applications' maximum power is less than the worst-case value, this relationship determines a higher maximum ambient temperature or the maximum temperature measured at top dead center of the package.

$$T_A = T_J - P \times \Theta_{JA}$$

$$T_{TDC} = T_J - P \times \Theta_{J-TDC}$$

where T_A is the still-air ambient temperature and T_{TDC} is the temperature measured by a thermocouple at the top dead center of the package.

Maximum Junction Temperature (T_J) in 100-Pin BQFP	100 °C
100-pin BQFP Maximum Thermal Resistance in Still-Air-Ambient (Θ_{JA})	55 °C/W
100-pin BQFP Maximum Thermal Resistance, Junction to Top Dead Center (Θ_{J-TDC})	12 °C/W
Maximum Junction Temperature (T_J) in 100-Pin TQFP	100 °C
100-pin TQFP Maximum Thermal Resistance in Still-Air-Ambient (Θ_{JA})	30 °C/W
100-pin TQFP Maximum Thermal Resistance, Junction to Top Dead Center (Θ_{J-TDC})	6 °C/W
Maximum Junction Temperature (T_J) in 144-Pin PBGA	100 °C
144-pin PBGA Maximum Thermal Resistance in Still-Air-Ambient (Θ_{JA})	TBD (estimated 30 °C/W)
144-pin PBGA Maximum Thermal Resistance, Junction to Top Dead Center (Θ_{J-TDC})	TBD

WARNING: Due to package thermal constraints, proper precautions in the user's application should be taken to avoid exceeding the maximum junction temperature of 100 °C. Otherwise, the device will be affected adversely.

9 Electrical Characteristics and Requirements

The following electrical characteristics are preliminary and are subject to change. Electrical characteristics refer to the behavior of the device under specified conditions. Electrical requirements refer to conditions imposed on the user for proper operation of the device. The parameters in Table 61, Electrical Characteristics and Requirements, are valid for the conditions described in Section 8.3, Recommended Operating Conditions.

Table 61. Electrical Characteristics and Requirements

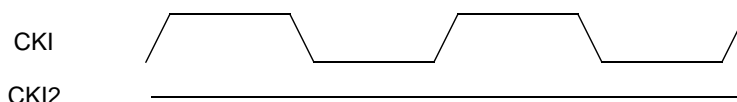
Parameter	Symbol	Min	Max	Unit
Input Voltage:				
Low	V_{IL}	-0.3	$0.3 * V_{DD}$	V
High	V_{IH}	$0.7 * V_{DD}$	$V_{DD} + 0.3$	V
Input Current (except TMS, TDI):				
Low ($V_{IL} = 0$ V, $V_{DD} = 5.25$ V)	I_{IL}	-5	—	μ A
High ($V_{IH} = 5.25$ V, $V_{DD} = 5.25$ V)	I_{IH}	—	5	μ A
Input Current (TMS, TDI):				
Low ($V_{IL} = 0$ V, $V_{DD} = 5.25$ V)	I_{IL}	-100	—	μ A
High ($V_{IH} = 5.25$ V, $V_{DD} = 5.25$ V)	I_{IH}	—	5	μ A
Output Low Voltage:				
Low ($I_{OL} = 2.0$ mA)	V_{OL}	—	0.4	V
Low ($I_{OL} = 50$ μ A)	V_{OL}	—	0.2	V
Output High Voltage:				
High ($I_{OH} = -2.0$ mA)	V_{OH}	$V_{DD} - 0.7$	—	V
High ($I_{OH} = -50$ μ A)	V_{OH}	$V_{DD} - 0.2$	—	V
Output 3-State Current:				
Low ($V_{DD} = 5.25$ V, $V_{IL} = 0$ V)	I_{OZL}	-10	—	μ A
High ($V_{DD} = 5.25$ V, $V_{IH} = 5.25$ V)	I_{OZH}	—	10	μ A
Input Capacitance	C_I	—	5	pF

Table 62. Electrical Requirements for Mask-Programmable Input Clock Options

Parameter	Symbol	Min	Max	Unit
CKI CMOS Level Input Voltage:				
Low	V_{IL}	-0.3	$0.3 * V_{DD}$	V
High	V_{IH}	$0.7 * V_{DD}$	$V_{DD} + 0.3$	V
Small-signal Peak-to-peak Voltage (on CKI) [†]	V_{pp}	0.6	—	V
Small-signal Input Duty Cycle [‡]	DCyc	45	55	%
Small-signal Input Voltage Range (pins: CKI, CKI2)	V_{in}	$0.2 * V_{DD}$	$0.6 * V_{DD}$	V
Small-signal Buffer Frequency Range	fss	—	35	MHz

[†] The small-signal buffer must be used in single-ended mode where an ac waveform (sine or square) is applied to CKI and a dc voltage approximately equal to the average value of CKI is applied to CKI2, as shown in the following figure. The maximum allowable ripple on CKI2 is 100 mV.

[‡] Duty cycle for a sine wave is defined as the percentage of time during each clock cycle that the voltage on CKI exceeds the voltage on CKI2.



9 Electrical Characteristics and Requirements (continued)

Table 63. PLL Electrical Specifications, VCO Frequency Ranges

Parameter	Symbol	Min	Max	Unit
VCO Frequency Range ($V_{DD} = 3\text{ V} \pm 10\%$) [*]	f _{VCO}	50	160	MHz
VCO Frequency Range ($V_{DD} = 3.0\text{ V} - 3.6\text{ V}$)	f _{VCO}	50	200	MHz
Input Jitter at CKI	—	—	200	ps-rms

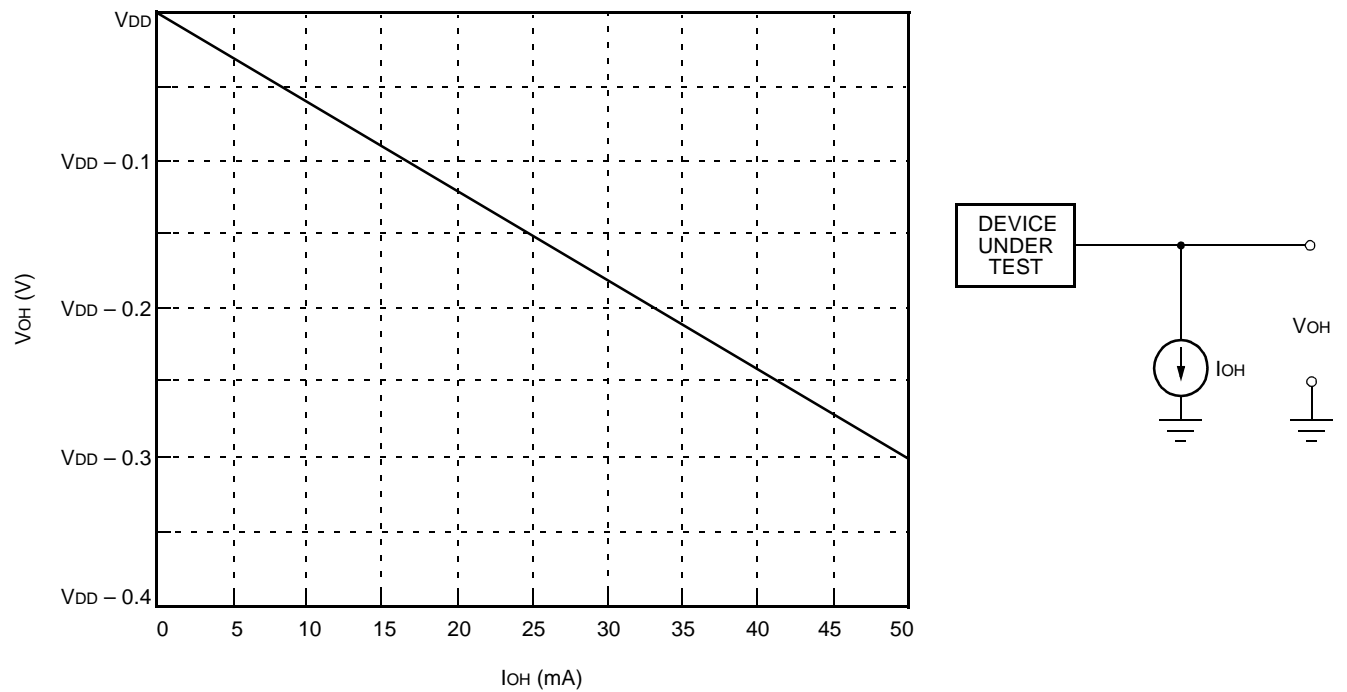
^{*} The M and N counter values in the **pllc** register must be set so that the VCO will operate in the appropriate range (see Table 63, PLL Electrical Specifications, VCO Frequency Ranges). Choose the lowest value of N and then the appropriate value of M for $f_{\text{INTERNAL CLOCK}} = f_{\text{CKI}} \times (M/(2N)) = f_{\text{VCO}}/2$.

Table 64. PLL Electrical Specifications and pllc Register Settings

M	V _{DD}	pllc13 (ICP)	pllc12 Reserved	pllc[11:8] (LF[3:0])	Typical Lock-in Time (μs) [*]
23—24	2.7 V – 3.6 V	1	0	1011	30
21—22	2.7 V – 3.6 V	1	0	1010	30
19—20	2.7 V – 3.6 V	1	0	1001	30
16—18	2.7 V – 3.6 V	1	0	1000	30
12—15	2.7 V – 3.6 V	1	0	0111	30
8—11	2.7 V – 3.6 V	1	0	0110	30
2—7	2.7 V – 3.6 V	1	0	0100	30

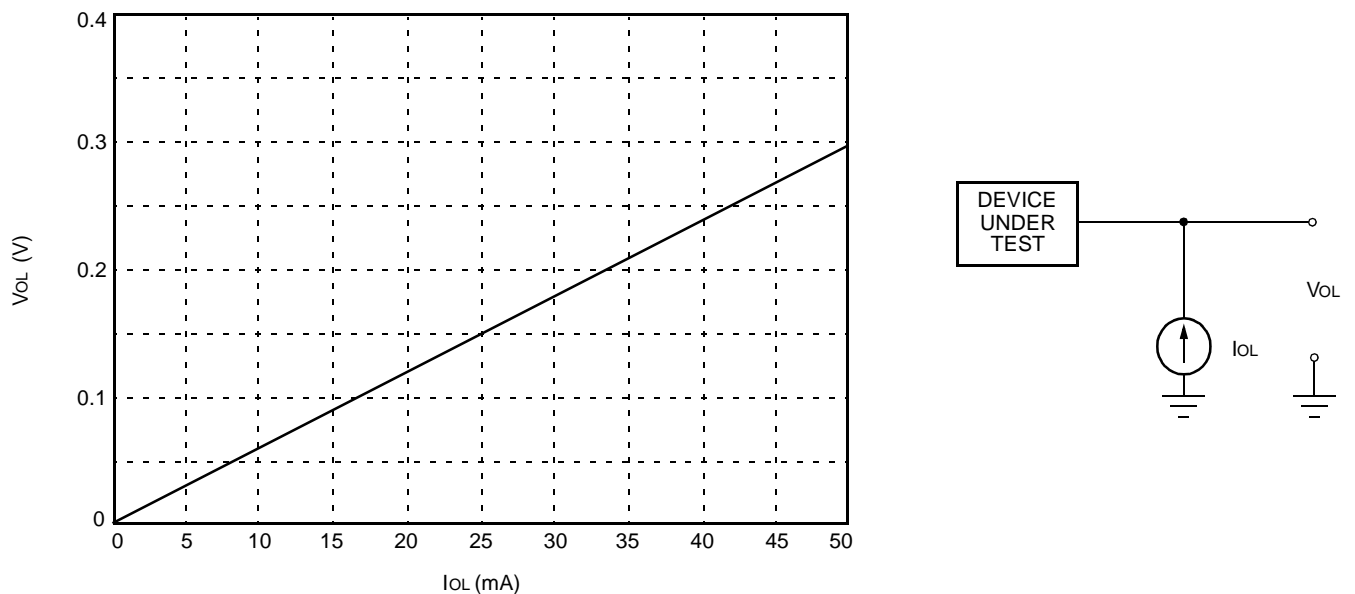
^{*} Lock-in time represents the time following assertion of the PLLEN bit of the **pllc** register during which the PLL output clock is unstable. The DSP must operate from the 1X CKI input clock or from the slow ring oscillator while the PLL is locking. Completion of the lock-in interval is indicated by assertion of the LOCK flag.

9 Electrical Characteristics and Requirements (continued)



5-4007 (F).a

Figure 10. Plot of V_{OH} vs. I_{OH} Under Typical Operating Conditions



5-4008 (F).b

Figure 11. Plot of V_{OL} vs. I_{OL} Under Typical Operating Conditions

9 Electrical Characteristics and Requirements (continued)

9.1 Power Dissipation

Power dissipation is highly dependent on DSP program activity and the frequency of operation. The typical power dissipation listed is for a selected application. The following electrical characteristics are preliminary and are subject to change.

Table 65. Power Dissipation and Wake-Up Latency

Operating Mode (Unused inputs at V _{DD} or V _{SS}) V _{DD} =	Typical Power Dissipation (mW)		Wake-Up Latency	
	I/O Units ON powerc[7:4] = 0x0	I/O Units OFF powerc[7:4] = 0xf	(PLL Not Used During Wake State)	(PLL Used During Wake State)
	3 V	3 V	3 V	3 V
Normal Operation ioc = 0x0180 PLL Disabled				
CKI and CKO = 40 MHz:				
CMOS	93.7	91.2	—	—
Small Signal	96.3	93.7	—	—
CKI and CKO = 0 MHz:				
CMOS	0.17	0.17	—	—
Small Signal	2.75	2.75	—	—
Normal Operation ioc = 0x0180 PLL Enabled pllcc = 0xFC0E CKI = 10 MHz CKO = 40 MHz				
CMOS	96.7	94.2	—	—
Small Signal	99.3	96.7	—	—
Power Management Modes CKO = 40 MHz				
Standard Sleep, External Interrupt alf[15] = 1, ioc = 0x0180 PLL Disabled During Sleep				
CMOS	14.0	9.3	3T*	3T* + tL [†]
Small Signal	16.3	12.0	3T*	3T* + tL [†]
Standard Sleep, External Interrupt alf[15] = 1, ioc = 0x0180 PLL Enabled During Sleep				
CMOS	16.5	11.2	—	3T*
Small Signal	18.9	14.0	—	3T*
Sleep with Slow Internal Clock Small Signal Enabled powerc[15:14] = 01, alf[15] = 1, ioc = 0x0180 PLL Disabled During Sleep				
CMOS	0.7	0.5	5.0 μs	5.0 μs + tL [†]
Small Signal	3.7	3.5	5.0 μs	5.0 μs + tL [†]
Sleep with Slow Internal Clock Small Signal Enabled powerc[15:14] = 01, alf[15] = 1, ioc = 0x0180 PLL Enabled During Sleep				
CMOS	3.3	2.9	—	5.0 μs
Small Signal	6.1	5.5	—	5.0 μs

* T = CKI clock cycle for 1X input clock option or T = CKI clock cycle divided by M/(2N) for PLL clock option (see Section 4.12, Clock Synthesis).

† tL = PLL lock time (see Table 64, PLL Electrical Specifications and pllcc Register Settings).

9 Electrical Characteristics and Requirements (continued)

Table 65. Power Dissipation and Wake-Up Latency (continued)

Operating Mode (Unused inputs at VDD or VSS) VDD=	Typical Power Dissipation (mW)		Wake-Up Latency	
	I/O Units ON powerc[7:4] = 0x0	I/O Units OFF powerc[7:4] = 0xf	(PLL Not Used During Wake State)	(PLL Used During Wake State)
	3 V	3 V	3 V	3 V
Sleep with Slow Internal Clock Small Signal Disabled powerc[15:14] = 11, alf[15] = 1, ioc = 0x0180 PLL Disabled During Sleep				
Small Signal	0.40	0.30	20 μ s	20 μ s + tL [†]
Software Stop powerc[15:12] = 0011 PLL Disabled During STOP				
CMOS	0.060	0.060	3T*	3T* + tL [†]
Software Stop powerc[15:12] = 1111 PLL Disabled During STOP				
Small Signal	0.060	0.060	20 μ s	20 μ s + tL [†]
Hardware Stop (STOP = VSS) powerc[15:12] = 0000 PLL Disabled During STOP				
CMOS	0.060	0.060	3T*	—
Small Signal	1.20	1.20	3T*	—
Hardware Stop (STOP = VSS) powerc[15:12] = 0000 PLL Enabled During STOP				
CMOS	2.5	2.5	3T*	3T*
Small Signal	3.6	3.6	3T*	3T*

* T = CKI clock cycle for 1X input clock option or T = CKI clock cycle divided by M/(2N) for PLL clock option (see Section 4.12, Clock Synthesis).

† tL = PLL lock time (see Table 64, PLL Electrical Specifications and pll Register Settings).

The power dissipation listed is for internal power dissipation only. Total power dissipation can be calculated on the basis of the application by adding $C \times V_{DD}/2 \times f$ for each output, where C is the additional load capacitance and f is the output frequency.

Power dissipation due to the input buffers is highly dependent on the input voltage level. At full CMOS levels, essentially no dc current is drawn. However, for levels between the power supply rails, especially at or near the threshold of $V_{DD}/2$, high currents can flow. Although input and I/O buffers may be left untied (since the input voltage levels of the input and I/O buffers are designed to remain at full CMOS levels when not driven by the DSP), it is still recommended that unused input and I/O pins be tied to VSS or VDD through a 10 k Ω resistor to avoid application ambiguities. Further, if I/O pins are tied high or low, they should be pulled fully to VSS or VDD.

WARNING: The device needs to be clocked for at least six CKI cycles during reset after powerup. Otherwise, high currents may flow.

10 Timing Characteristics for 3.0 V Operation

The following timing characteristics and requirements are preliminary information and are subject to change. Timing characteristics refer to the behavior of the device under specified conditions. Timing requirements refer to conditions imposed on the user for proper operation of the device. All timing data is valid for the following conditions:

$T_A = -40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$ (See Section 8.3, Recommended Operating Conditions.)

$V_{DD} = 3.0\text{ V}$ to 3.6 V , $V_{SS} = 0\text{ V}$ (See Section 8.3, Recommended Operating Conditions.)

Capacitance load on outputs (C_L) = 50 pF , except for CKO, where $C_L = 20\text{ pF}$.

Output characteristics can be derated as a function of load capacitance (C_L).

All outputs: $0.03\text{ ns/pF} \leq dt/dC_L \leq 0.07\text{ ns/pF}$ for $10 \leq C_L \leq 100\text{ pF}$ at V_{IH} for rising edge and at V_{IL} for falling edge.

For example, if the actual load capacitance is 30 pF instead of 50 pF , the derating for a rising edge is $(30 - 50)\text{ pF} \times 0.06\text{ ns/pF} = 1.2\text{ ns}$ **less** than the specified rise time or delay that includes a rise time.

Test conditions for inputs:

- Rise and fall times of 4 ns or less
- Timing reference levels for delays = V_{IH} , V_{IL}

Test conditions for outputs (unless noted otherwise):

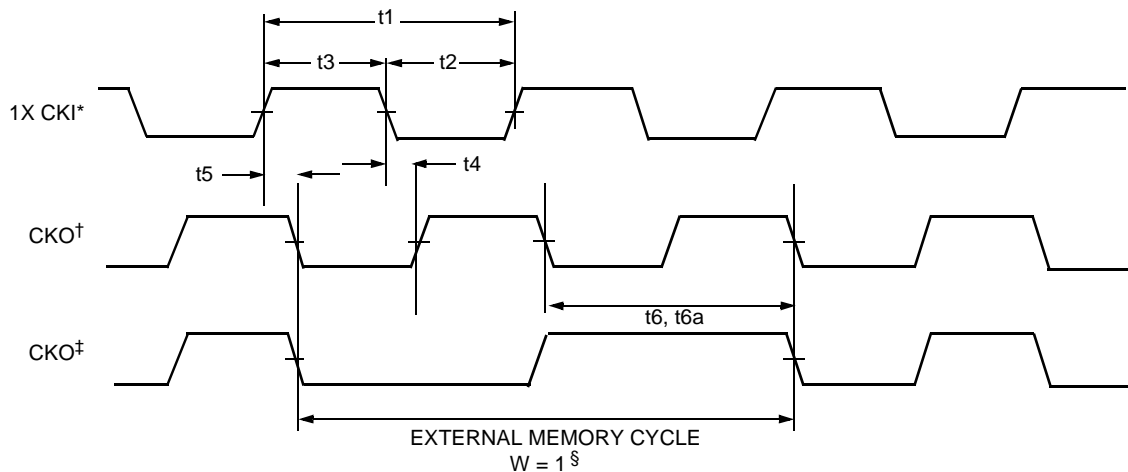
- $C_{LOAD} = 50\text{ pF}$; except for CKO, where $C_{LOAD} = 20\text{ pF}$
- Timing reference levels for delays = V_{IH} , V_{IL}
- 3-state delays measured to the high-impedance state of the output driver

For the timing diagrams, see Table 62, Electrical Requirements for Mask-Programmable Input Clock Options, for input clock requirements.

Unless otherwise noted, CKO in the timing diagrams is the free-running CKO.

10 Timing Characteristics for 3.0 V Operation (continued)

10.1 DSP Clock Generation (3.0 V Operation)



5-4009 (F).a

* See Table 62, Electrical Requirements for Mask-Programmable Input Clock Options, for input clock electrical requirements.

† Free-running clock.

‡ Wait-stated clock (see Table 38, ioc Register).

§ W = number of wait-states.

Figure 12. I/O Clock Timing Diagram (3.0 V Operation)

Table 66. Timing Requirements for Input Clock (3.0 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t1	Clock In Period (high to high)	20†	—‡	ns
t2	Clock In Low Time (low to high)	10	—	ns
t3	Clock In High Time (high to low)	10	—	ns

† Device speeds greater than 50 MIPS do not support 1X operation. Use the PLL.

‡ Device is fully static, t1 is tested at 100 ns for 1X input clock option, and memory hold time is tested at 0.1 s.

Table 67. Timing Characteristics for Input Clock and Output Clock (3.0 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t4	Clock Out High Delay	—	10	ns
t5	Clock Out Low Delay (high to low)	—	10	ns
t6	Clock Out Period (low to low)	T†	—	ns
t6a	Clock Out Period with SLOWCKI Bit Set in powerc Register (low to low)	0.74	3.8	μs

† T = internal clock period, set by CKI or by CKI and the PLL parameters.

10 Timing Characteristics for 3.0 V Operation (continued)

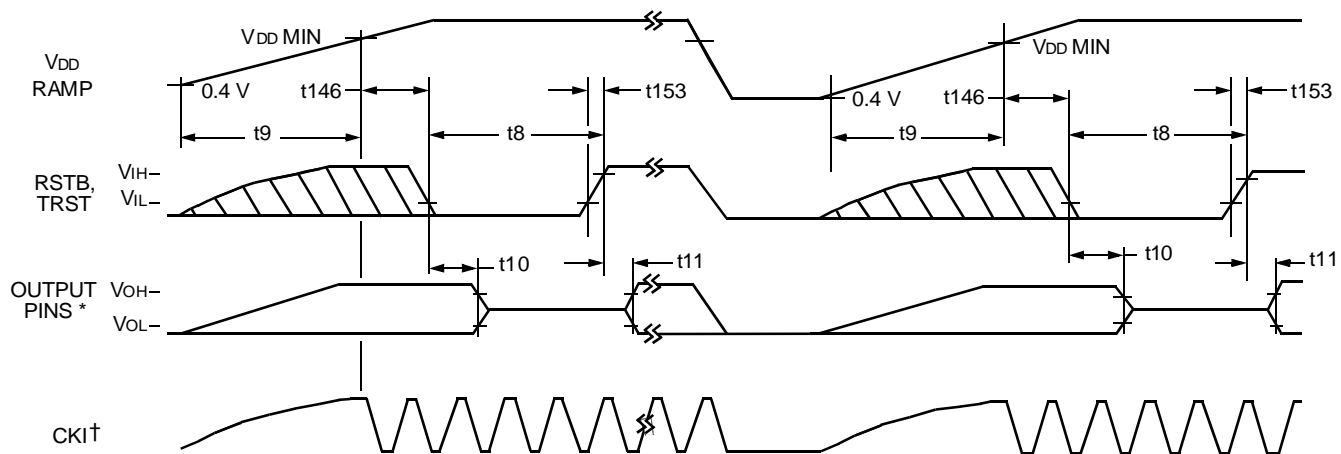
10.2 Reset Circuit (3.0 V Operation)

The DSP1629 has two external reset pins: RSTB and TRST. At initial powerup, or if the supply voltage falls below $V_{DD\ MIN}^*$ and a device reset is required, both TRST and RSTB must be asserted to initialize the device. Figure 13, Powerup Reset and Chip Reset Timing Diagram (3.0 V Operation), shows two separate events:

- Chip reset at initial powerup.
- Chip reset following a drop in power supply.

Note: The TRST pin must be asserted even if the JTAG controller is not used by the application.

* See Table 60, Recommended Operating Conditions.



5-4010 (F).a

* When both INT0 and RSTB are asserted, all output and bidirectional pins (except TDO, which 3-states by JTAG control) are put in a 3-state condition. With RSTB asserted and INT0 not asserted, EROM, ERAMHI, ERAMLO, IO, and RWN outputs remain high, and CKO remains a free-running clock.

† See Table 62, Electrical Requirements for Mask-Programmable Input Clock Options, for input clock electrical requirements.

Figure 13. Powerup Reset and Chip Reset Timing Diagram (3.0 V Operation)

Table 68. Timing Requirements for Powerup Reset and Chip Reset (3.0 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t8	RSTB and TRST Reset Pulse (low to high)	6T	—	ns
t9	VDD Ramp	—	10	ms
t146	VDD MIN to RSTB Low: CMOS Small-signal	2T 20	—	ns μs
t153	RSTB (low to high)	—	54	ns

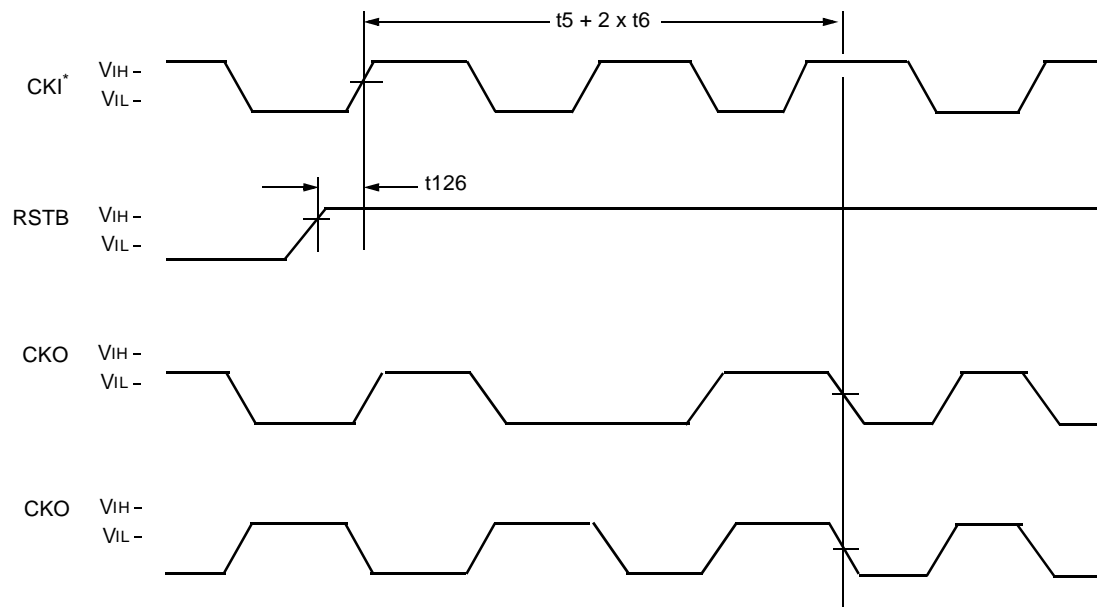
Table 69. Timing Characteristics for Powerup Reset and Chip Reset (3.0 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t10	RSTB Disable Time (low to 3-state)	—	100	ns
t11	RSTB Enable Time (high to valid)	—	100	ns

Note: The device needs to be clocked for at least six CKI cycles during reset after powerup. Otherwise, high currents may flow.

10 Timing Characteristics for 3.0 V Operation (continued)

10.3 Reset Synchronization (3.0 V Operation)



5-4011 (F).a

* See Table 62, Electrical Requirements for Mask-Programmable Input Clock Options, for input clock electrical requirements.

Notes:

CKO1 and CKO2 are two possible CKO states before reset. CKO is free-running.

If the rising edge of RSTB (low to high) is captured instead by the falling edge of CKO (high to low), CKO and CKI will be in-phase at $t_5 + 2 \times t_6$.

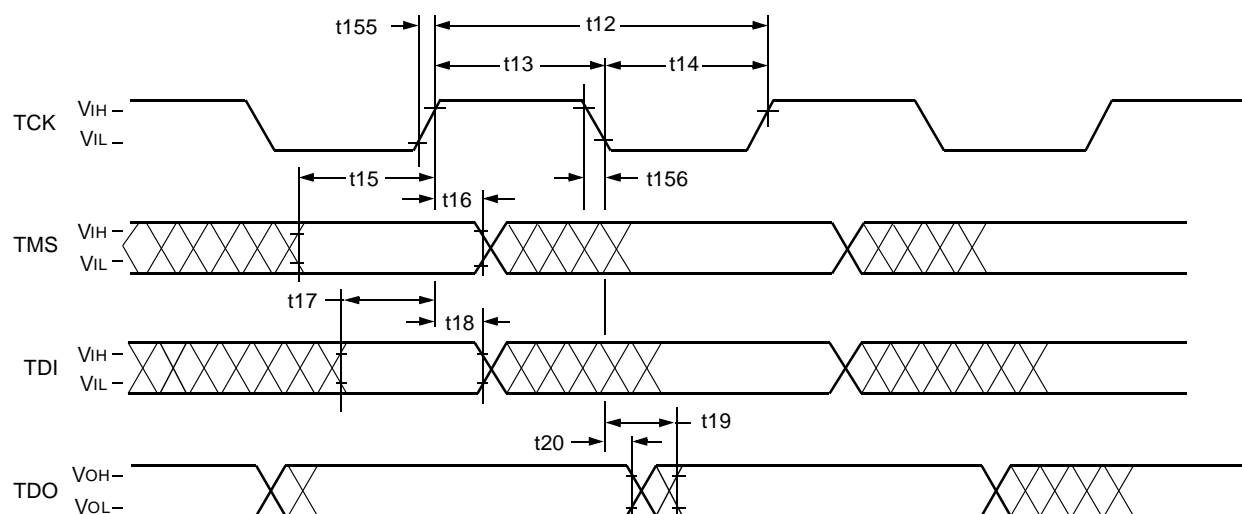
Figure 14. Reset Synchronization Timing (3.0 V Operation)

Table 70. Timing Requirements for Reset Synchronization Timing (3.0 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t126	Reset Setup (high to high)	3	$T/2 - 1$	ns

10 Timing Characteristics for 3.0 V Operation (continued)

10.4 JTAG I/O Specifications (3.0 V Operation)



5-4017 (F)

Figure 15. JTAG Timing Diagram (3.0 V Operation)

Table 71. Timing Requirements for JTAG Input/Output (3.0 V Operation)

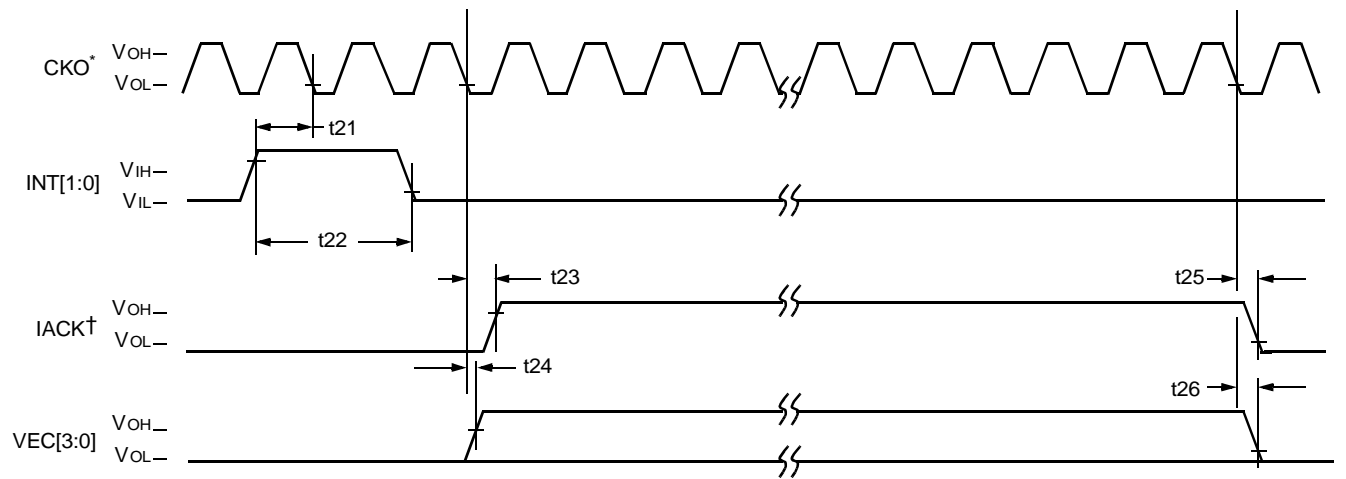
Abbreviated Reference	Parameter	Min	Max	Unit
t12	TCK Period (high to high)	50	—	ns
t13	TCK High Time (high to low)	22.5	—	ns
t14	TCK Low Time (low to high)	22.5	—	ns
t155	TCK Rise Transition Time (low to high)	0.6	—	V/ns
t156	TCK Fall Transition Time (high to low)	0.6	—	V/ns
t15	TMS Setup Time (valid to high)	7.5	—	ns
t16	TMS Hold Time (high to invalid)	2	—	ns
t17	TDI Setup Time (valid to high)	7.5	—	ns
t18	TDI Hold Time (high to invalid)	2	—	ns

Table 72. Timing Characteristics for JTAG Input/Output (3.0 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t19	TDO Delay (low to valid)	—	19	ns
t20	TDO Hold (low to invalid)	0	—	ns

10 Timing Characteristics for 3.0 V Operation (continued)

10.5 Interrupt (3.0 V Operation)



5-4018 (F)

* CKO is free-running.

† IACK assertion is guaranteed to be enclosed by VEC[3:0] assertion.

Figure 16. Interrupt Timing Diagram (3.0 V Operation)

Table 73. Timing Requirements for Interrupt (3.0 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t21	Interrupt Setup (high to low)	19	—	ns
t22	INT Assertion Time (high to low)	2T	—	ns

Note: Interrupt is asserted during an interruptible instruction and no other pending interrupts.

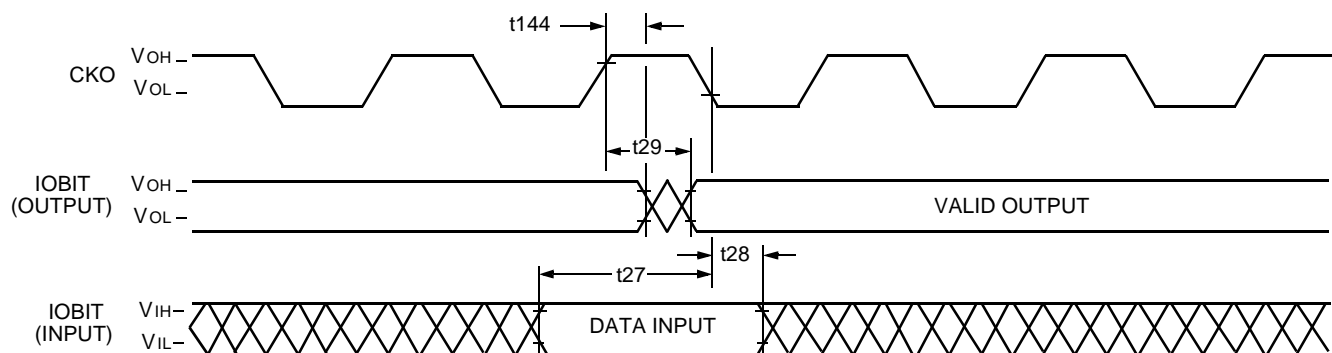
Table 74. Timing Characteristics for Interrupt (3.0 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t23	IACK Assertion Time (low to high)	—	T/2 + 10	ns
t24	VEC Assertion Time (low to high)	—	12.5	ns
t25	IACK Invalid Time (low to low)	—	10	ns
t26	VEC Invalid Time (low to low)	—	12.5	ns

Note: Interrupt is asserted during an interruptible instruction and no other pending interrupts.

10 Timing Characteristics for 3.0 V Operation (continued)

10.6 Bit Input/Output (BIO) (3.0 V Operation)



5-4019 (F).a

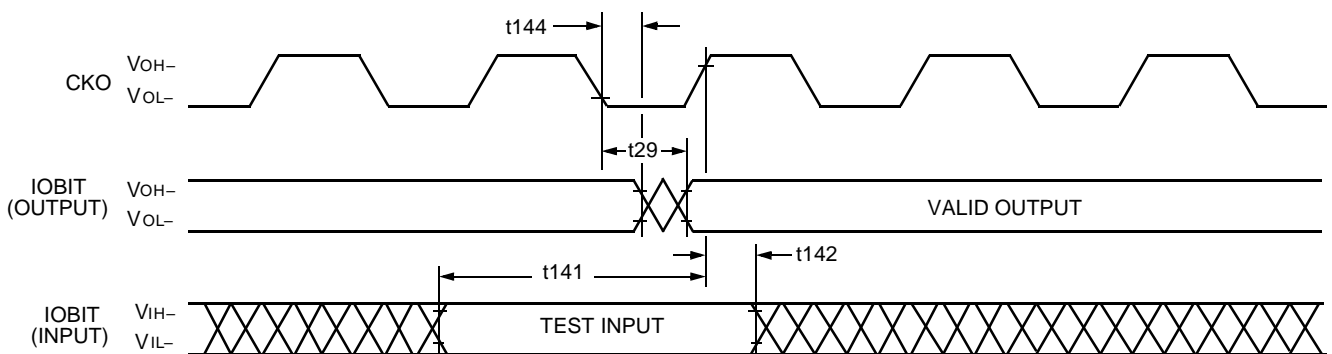
Figure 17. Write Outputs Followed by Read Inputs (cbit = Immediate; a1 = sbits) (3.0 V Operation)

Table 75. Timing Requirements for BIO Input Read (3.0 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t27	IOBIT Input Setup Time (valid to high)	15	—	ns
t28	IOBIT Input Hold Time (high to invalid)	0	—	ns

Table 76. Timing Characteristics for BIO Output (3.0 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t29	IOBIT Output Valid Time (low to valid)	—	9	ns
t144	IOBIT Output Hold Time (low to invalid)	1	—	ns



5-4019 (F).b

Figure 18. Write Outputs and Test Inputs (cbit = Immediate) (3.0 V Operation)

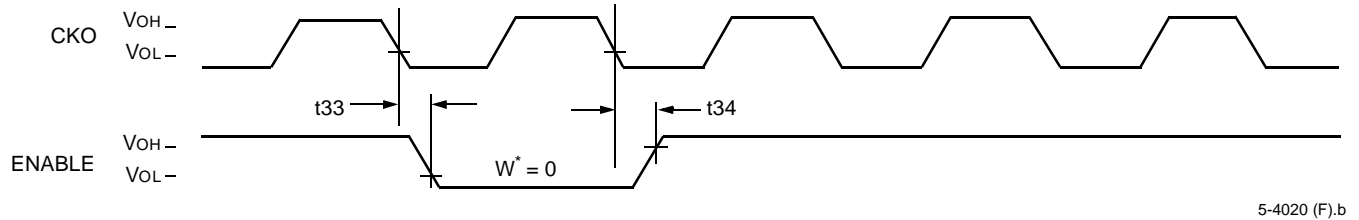
Table 77. Timing Requirements for BIO Input Test (3.0 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t141	IOBIT Input Setup Time (valid to low)	15	—	ns
t142	IOBIT Input Hold Time (low to invalid)	0	—	ns

10 Timing Characteristics for 3.0 V Operation (continued)

10.7 External Memory Interface (3.0 V Operation)

The following timing diagrams, characteristics, and requirements do not apply to interactions with delayed external memory enables unless so stated. See the *DSP1611/17/18/27/28/29 Digital Signal Processor Information Manual* for a detailed description of the external memory interface, including other functional diagrams.



* W = number of wait-states.

Figure 19. Enable Transition Timing (3.0 V Operation)

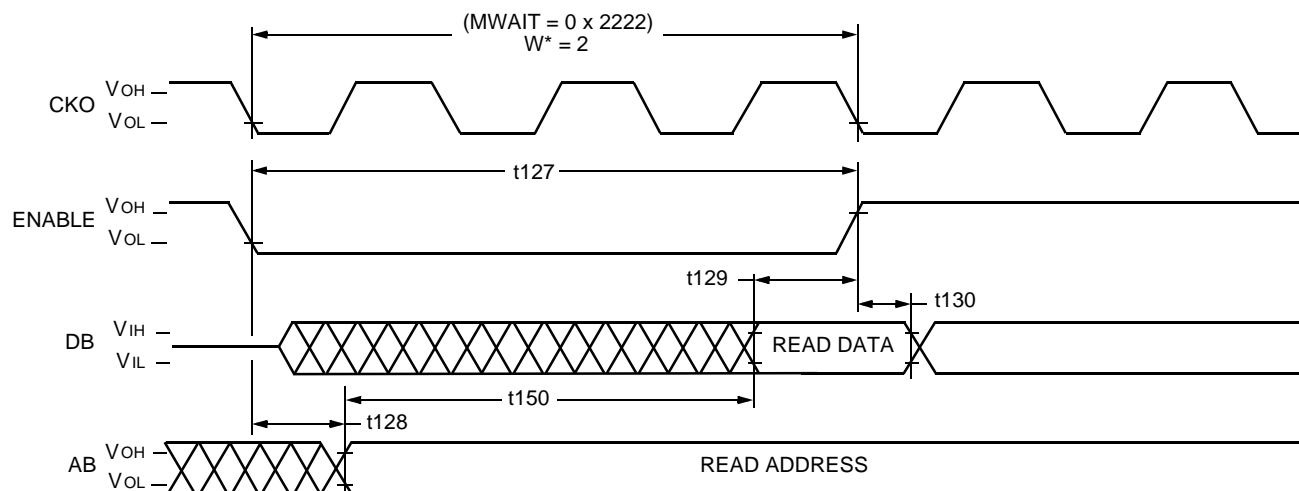
Table 78. Timing Characteristics for External Memory Enables (EROM, ERAMHI, IO, ERAMLO) (3.0 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t33	CKO to ENABLE Active (low to low)	0	4.5	ns
t34	CKO to ENABLE Inactive (low to high)	-1	4	ns

Table 79. Timing Characteristics for Delayed External Memory Enables (ioc = 0x000F) (3.0 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t33	CKO to Delayed ENABLE Active (low to low)	T/2	T/2 + 7	ns

10 Timing Characteristics for 3.0 V Operation (continued)



5-4021 (F).a

* W = number of wait-states.

Figure 20. External Memory Data Read Timing Diagram (3.0 V Operation)

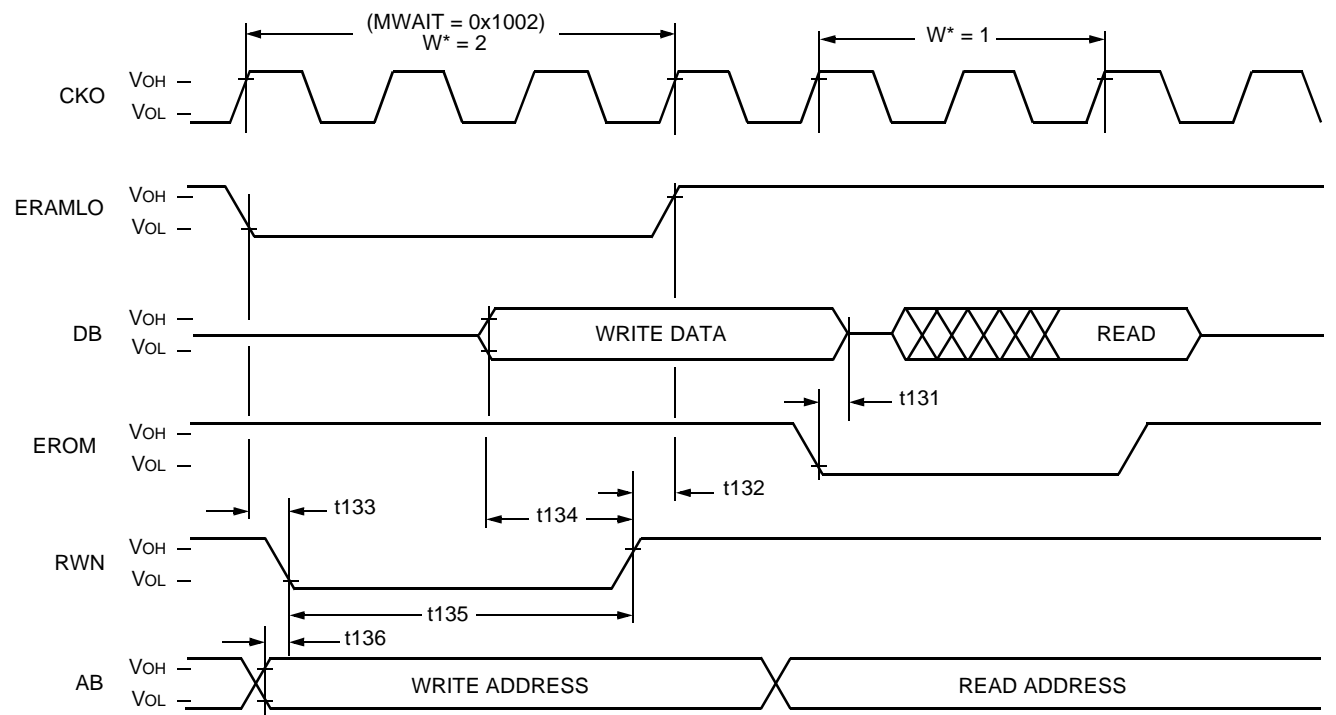
Table 80. Timing Characteristics for External Memory Access (3.0 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t127	Enable Width (low to high)	$T(1 + W) - 1.5$	—	ns
t128	Address Valid (enable low to valid)	—	2	ns

Table 81. Timing Requirements for External Memory Read (EROM, ERAMHI, IO, ERAMLO) (3.0 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t129	Read Data Setup (valid to enable high)	12	—	ns
t130	Read Data Hold (enable high to hold)	0	—	ns
t150	External Memory Access Time (valid to valid)	—	$T(1 + W) - 13$	ns

10 Timing Characteristics for 3.0 V Operation (continued)



5-4022 (F).a

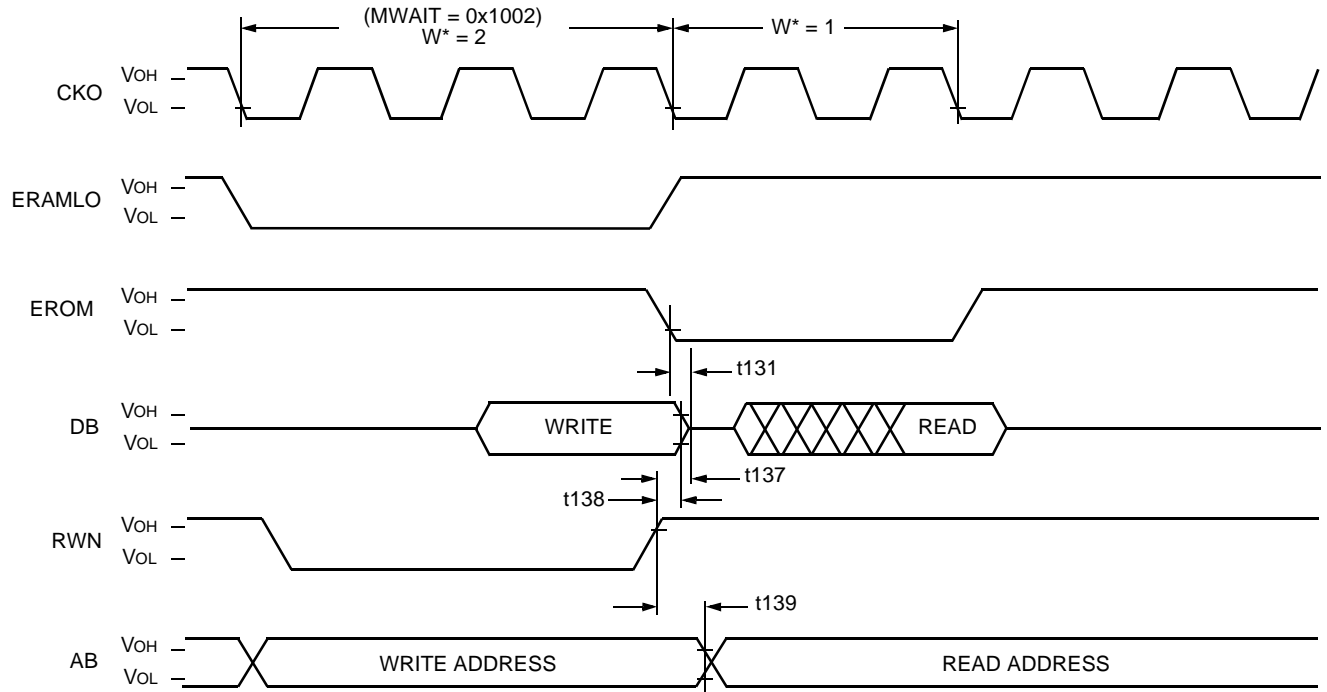
* W = number of wait-states.

Figure 21. External Memory Data Write Timing Diagram (3.0 V Operation)

Table 82. Timing Characteristics for External Memory Data Write (All Enables) (3.0 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t131	Write Overlap (enable low to 3-state)	—	0	ns
t132	RWN Advance (RWN high to enable high)	0	—	ns
t133	RWN Delay (enable low to RWN low)	0	—	ns
t134	Write Data Setup (data valid to RWN high)	$T(1 + W)/2 - 3$	—	ns
t135	RWN Width (low to high)	$T(1 + W) - 4$	—	ns
t136	Write Address Setup (address valid to RWN low)	0	—	ns

10 Timing Characteristics for 3.0 V Operation (continued)



5-4023 (F).a

* W = number of wait-states.

Figure 22. Write Cycle Followed by Read Cycle (3.0 V Operation)

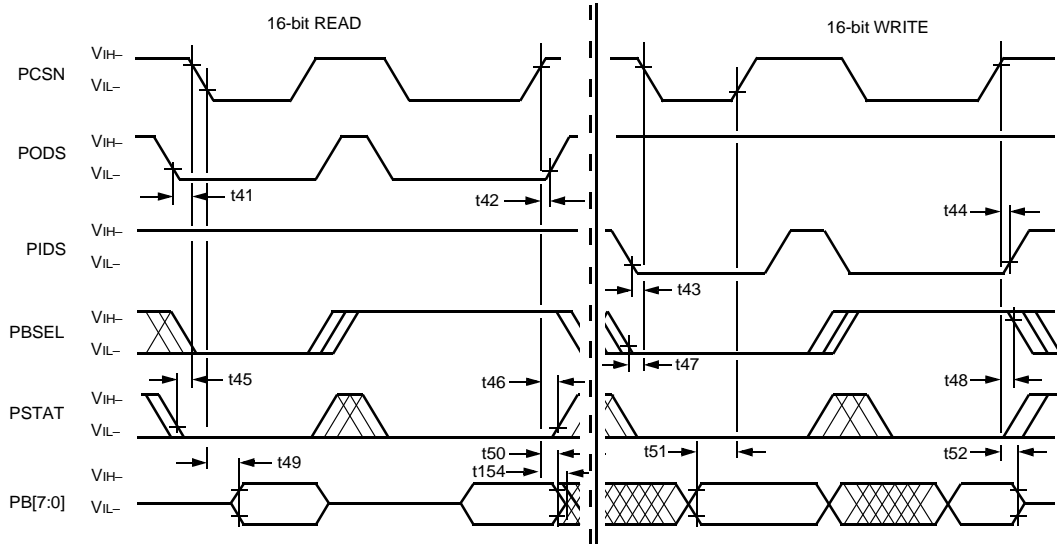
Table 83. Timing Characteristics for Write Cycle Followed by Read Cycle (3.0 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t131	Write Overlap (enable low to 3-state)	—	0	ns
t137	Write Data 3-state (RWN high to 3-state)	—	2	ns
t138	Write Data Hold (RWN high to data hold)	0	—	ns
t139	Write Address Hold (RWN high to address hold)	0	—	ns

10 Timing Characteristics for 3.0 V Operation (continued)

10.8 PHIF Specifications (3.0 V Operation)

For the PHIF, read means read by the external user (output by the DSP); write is similarly defined. The 8-bit reads/writes are identical to one-half of a 16-bit access.



5-4036 (F)

Figure 23. PHIF *Intel* Mode Signaling (Read and Write) Timing Diagram (3.0 V Operation)

Table 84. Timing Requirements for PHIF *Intel* Mode Signaling (3.0 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t41	PODS to PCSN Setup (low to low)	0	—	ns
t42	PCSN to PODS Hold (high to high)	0	—	ns
t43	PIDS to PCSN Setup (low to low)	0	—	ns
t44	PCSN to PIDS Hold (high to high)	0	—	ns
t45*	PSTAT to PCSN Setup (valid to low)	4	—	ns
t46*	PCSN to PSTAT Hold (high to invalid)	0	—	ns
t47*	PBSEL to PCSN Setup (valid to low)	6	—	ns
t48*	PCSN to PBSEL Hold (high to invalid)	0	—	ns
t51*	PB Write to PCSN Setup (valid to high)	10	—	ns
t52*	PCSN to PB Write Hold (high to invalid)	4	—	ns

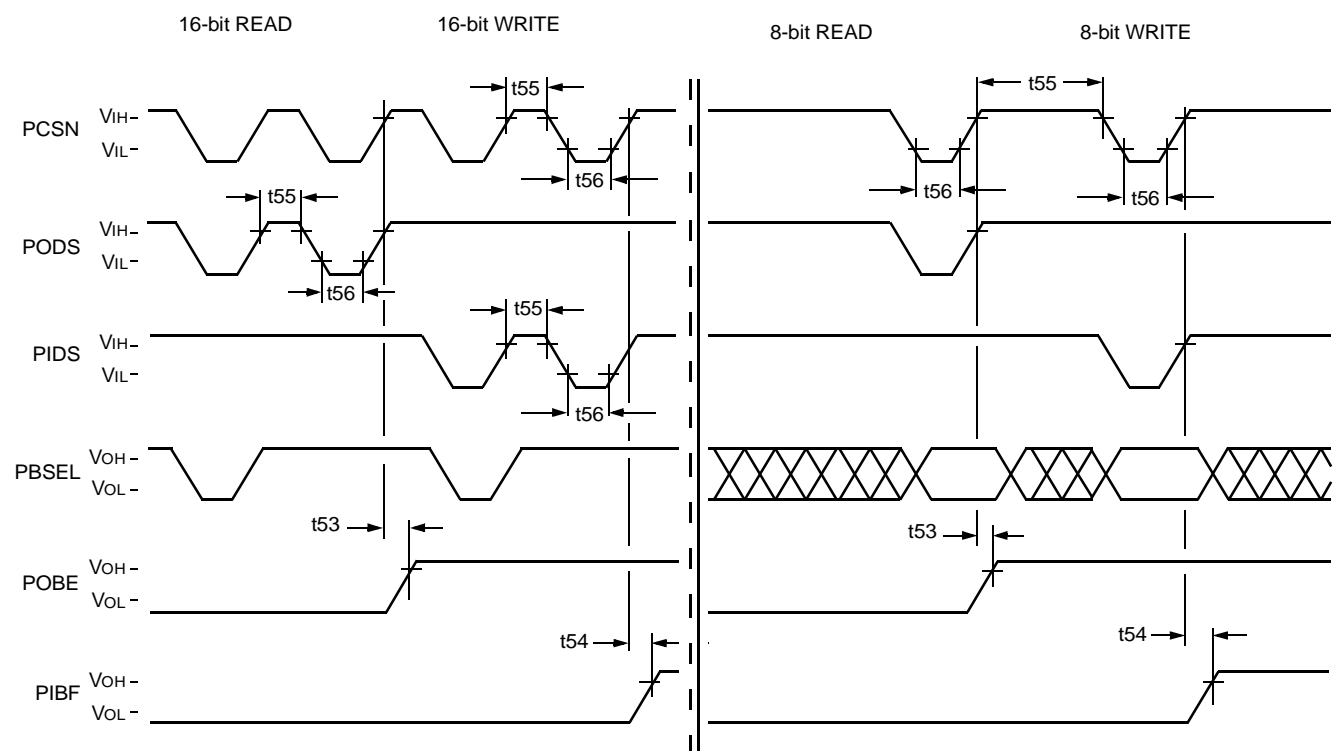
* This timing diagram for the PHIF port shows accesses using the PCSN signal to initiate and complete a transaction. The transactions can also be initiated and completed with the PIDS and PODS signals. An output transaction (read) is initiated by PCSN or PODS going low, whichever comes last. For example, the timing requirements referenced to PCSN going low, t45 and t49, should be referenced to PODS going low, if PODS goes low after PCSN. An output transaction is completed by PCSN or PODS going high, whichever comes first. An input transaction is initiated by PCSN or PIDS going low, whichever comes last. An input transaction is completed by PCSN or PIDS going high, whichever comes first. All requirements referenced to PCSN apply to PIDS or PODS, if PIDS or PODS is the controlling signal.

Table 85. Timing Characteristics for PHIF *Intel* Mode Signaling (3.0 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t49*	PCSN to PB Read (low to valid)	—	12	ns
t50*	PCSN to PB Read Hold (high to invalid)	0	—	ns
t154	PCSN to PB Read 3-state (high to 3-state)	—	8	ns

* This timing diagram for the PHIF port shows accesses using the PCSN signal to initiate and complete a transaction. The transactions can also be initiated and completed with the PIDS and PODS signals. An output transaction (read) is initiated by PCSN or PODS going low, whichever comes last. For example, the timing requirements referenced to PCSN going low, t45 and t49, should be referenced to PODS going low, if PODS goes low after PCSN. An output transaction is completed by PCSN or PODS going high, whichever comes first. An input transaction is initiated by PCSN or PIDS going low, whichever comes last. An input transaction is completed by PCSN or PIDS going high, whichever comes first. All requirements referenced to PCSN apply to PIDS or PODS, if PIDS or PODS is the controlling signal.

10 Timing Characteristics for 3.0 V Operation (continued)



5-4037 (F).a

Figure 24. PHIF *Intel* Mode Signaling (Pulse Period and Flags) Timing Diagram (3.0 V Operation)

Table 86. Timing Requirements for PHIF *Intel* Mode Signaling (3.0 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t55	PCSN/PODS/PIDS Pulse Width (high to low)	20.5	—	ns
t56	PCSN/PODS/PIDS Pulse Width (low to high)	20.5	—	ns

Table 87. Timing Characteristics for PHIF *Intel* Mode Signaling (3.0 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t53*	PCSN/PODS to POBE [†] (high to high)	—	17	ns
t54*	PCSN/PIDS to PIBF [†] (high to high)	—	17	ns

* t53 should be referenced to the rising edge of PCSN or PODS, whichever comes first. t54 should be referenced to the rising edge of PCSN or PIDS, whichever comes first.

† POBE and PIBF may be programmed to be the opposite logic levels shown in the diagram (positive assertion levels shown). t53 and t54 apply to the inverted levels as well as those shown.

10 Timing Characteristics for 3.0 V Operation (continued)

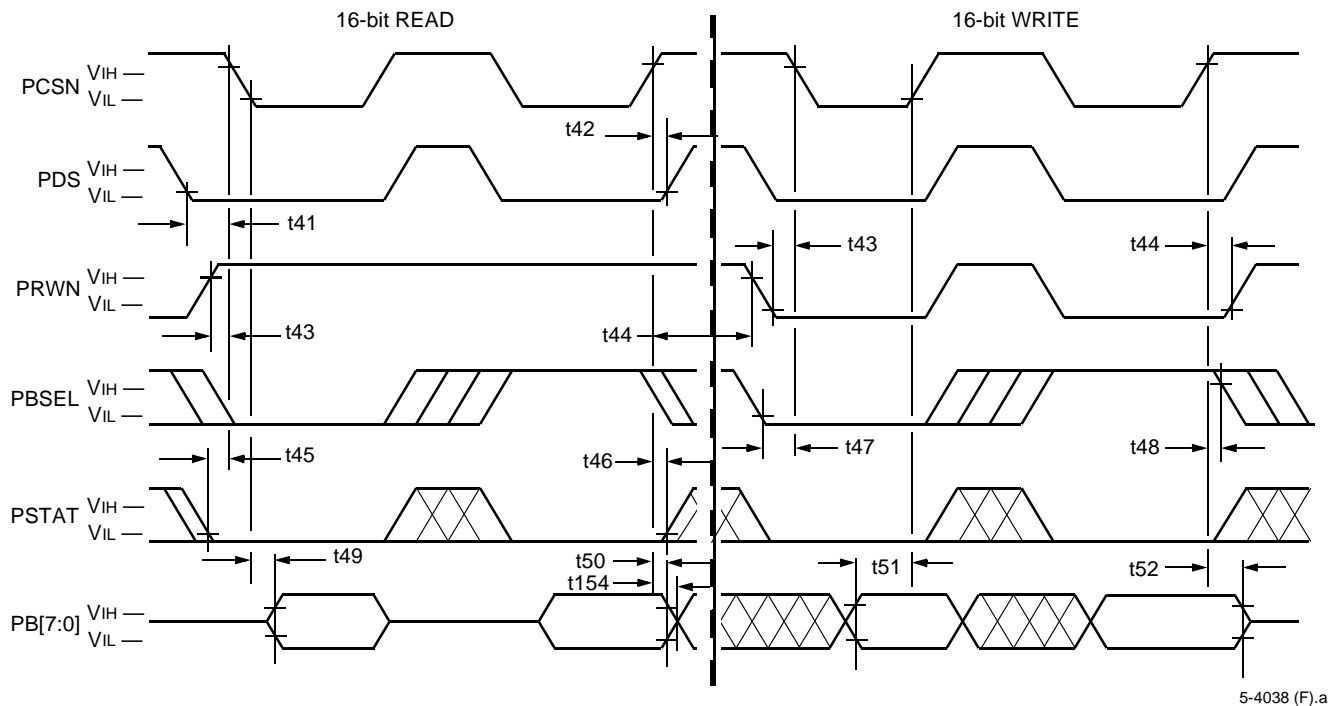


Figure 25. PHIF *Motorola* Mode Signaling (Read and Write) Timing Diagram (3.0 V Operation)

Table 88. Timing Requirements for PHIF *Motorola* Mode Signaling (3.0 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t41	PDS [†] to PCSN Setup (valid to low)	0	—	ns
t42	PCSN to PDS [†] Hold (high to invalid)	0	—	ns
t43	PRWN to PCSN Setup (valid to low)	4	—	ns
t44	PCSN to PRWN Hold (high to invalid)	0	—	ns
t45*	PSTAT to PCSN Setup (valid to low)	4	—	ns
t46*	PCSN to PSTAT Hold (high to invalid)	0	—	ns
t47*	PBSEL to PCSN Setup (valid to low)	6	—	ns
t48*	PCSN to PBSEL Hold (high to invalid)	0	—	ns
t51*	PB Write to PCSN Setup (valid to high)	10	—	ns
t52*	PCSN to PB Write Hold (high to invalid)	4	—	ns

* This timing diagram for the PHIF port shows accesses using the PCSN signal to initiate and complete a transaction. The transactions can also be initiated and completed with the PDS signal. An input/output transaction is initiated by PCSN or PDS going low, whichever comes last. For example, the timing requirements referenced to PCSN going low, t45 and t49, should be referenced to PDS going low, if PDS goes low after PCSN. An input/output transaction is completed by PCSN or PDS going high, whichever comes first. All requirements referenced to PCSN should be referenced to PDS, if PDS is the controlling signal. PRWN should never be used to initiate or complete a transaction.

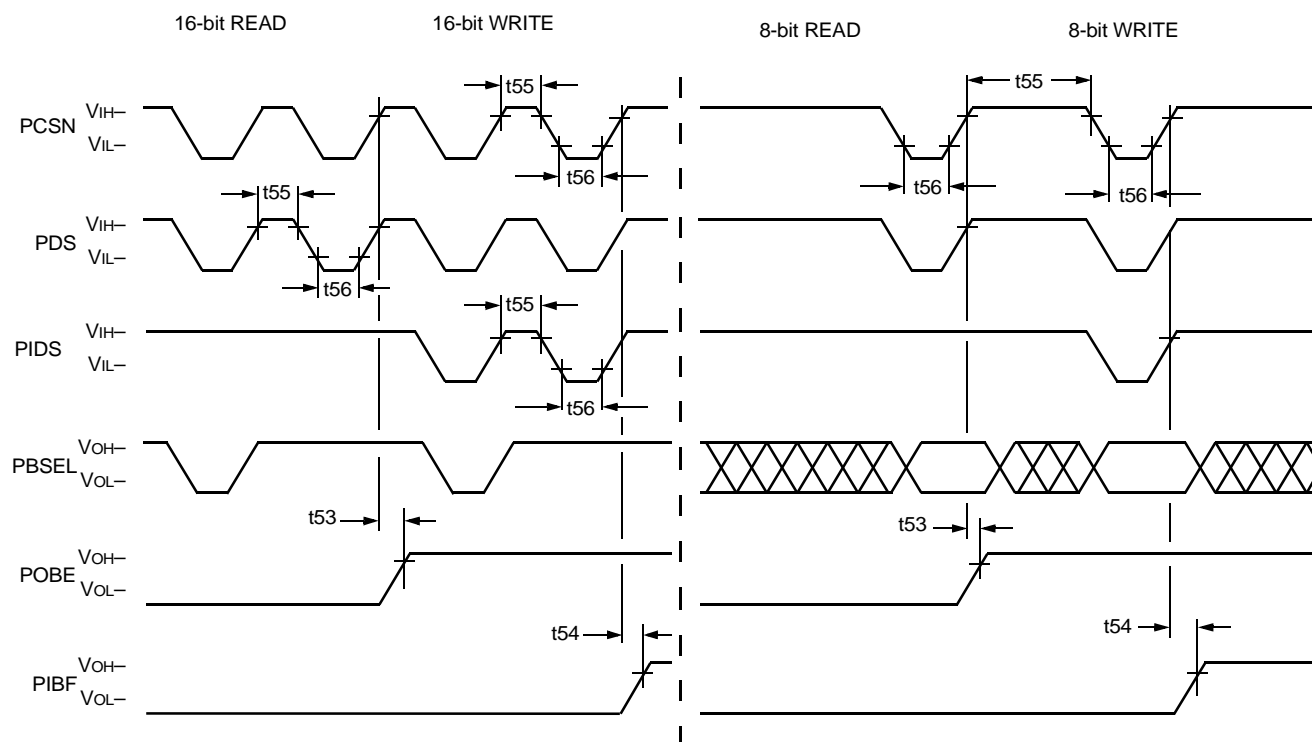
† PDS is programmable to be active-high or active-low. It is shown active-low in Figures 49 and 50. POBE and PIBF may be programmed to be the opposite logic levels shown in the diagram. t53 and t54 apply to the inverted levels as well as those shown.

Table 89. Timing Characteristics for PHIF *Motorola* Mode Signaling (3.0 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t49*	PCSN to PB Read (low to valid)	—	12	ns
t50*	PCSN to PB Read Hold (high to invalid)	0	—	ns
t154	PCSN to PB Read 3-state (high to 3-state)	—	8	ns

* This timing diagram for the PHIF port shows accesses using the PCSN signal to initiate and complete a transaction. The transactions can also be initiated and completed with the PDS signal. An input/output transaction is initiated by PCSN or PDS going low, whichever comes last. For example, the timing requirements referenced to PCSN going low, t45 and t49, should be referenced to PDS going low, if PDS goes low after PCSN. An input/output transaction is completed by PCSN or PDS going high, whichever comes first. All requirements referenced to PCSN should be referenced to PDS, if PDS is the controlling signal. PRWN should never be used to initiate or complete a transaction.

10 Timing Characteristics for 3.0 V Operation (continued)



5-4039 (F).a

Figure 26. PHIF Motorola Mode Signaling (Pulse Period and Flags) Timing Diagram (3.0 V Operation)

Table 90. Timing Characteristics for PHIF Motorola Mode Signaling (3.0 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t53*	PCSN/PDS [†] to POBE [†] (high to high)	—	17	ns
t54*	PCSN/PDS [†] to PIBF [†] (high to high)	—	17	ns

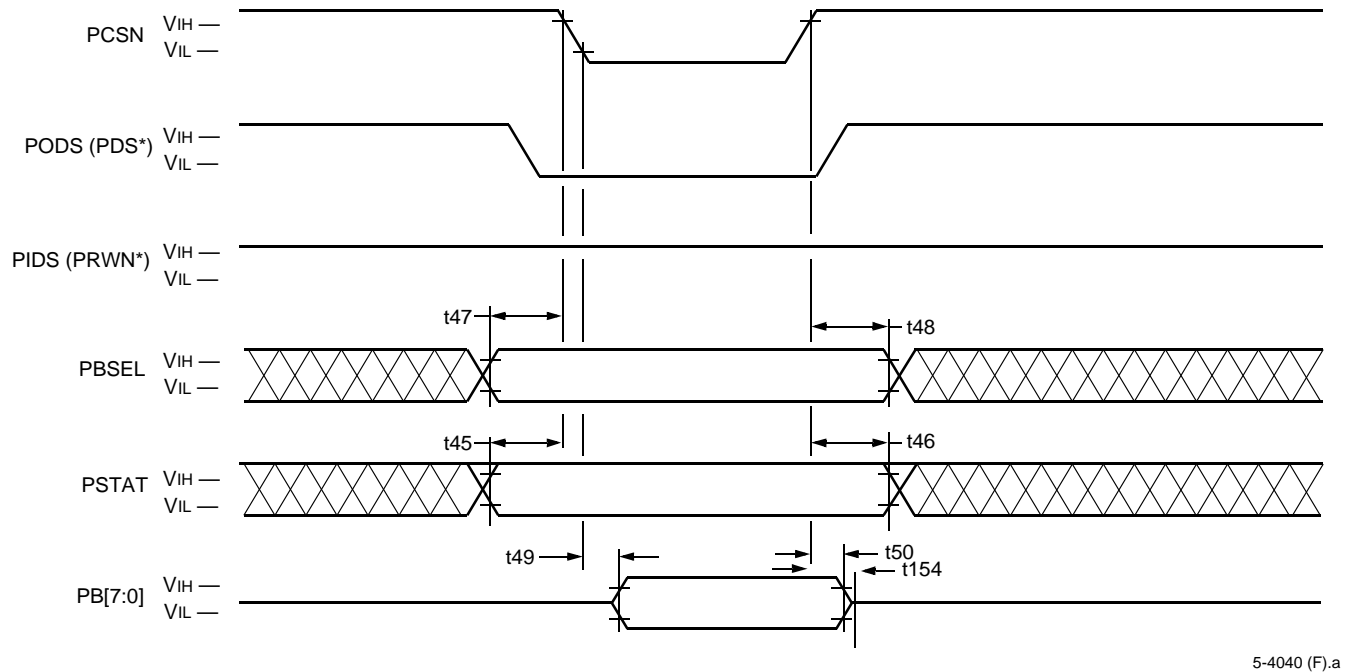
* An input/output transaction is initiated by PCSN or PDS going low, whichever comes last. For example, t53 and t54 should be referenced to PDS going low, if PDS goes low after PCSN. An input/output transaction is completed by PCSN or PDS going high, whichever comes first. All requirements referenced to PCSN should be referenced to PDS, if PDS is the controlling signal. PRWN should never be used to initiate or complete a transaction.

† PDS is programmable to be active-high or active-low. It is shown active-low in Figures 49 and 50. POBE and PIBF may be programmed to be the opposite logic levels shown in the diagram. t53 and t54 apply to the inverted levels as well as those shown.

Table 91. Timing Requirements for PHIF Motorola Mode Signaling (3.0 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t55	PCSN/PDS/PRWN Pulse Width (high to low)	20	—	ns
t56	PCSN/PDS/PRWN Pulse Width (low to high)	20	—	ns

10 Timing Characteristics for 3.0 V Operation (continued)



* Motorola mode signal name.

Figure 27. PHIF *Intel* or *Motorola* Mode Signaling (Status Register Read) Timing Diagram (3.0 V Operation)

Table 92. Timing Requirements for *Intel* and *Motorola* Mode Signaling (Status Register Read) (3.0 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t45†	PSTAT to PCSN Setup (valid to low)	4	—	ns
t46‡	PCSN to PSTAT Hold (high to invalid)	0	—	ns
t47†	PBSEL to PCSN Setup (valid to low)	6	—	ns
t48‡	PCSN to PBSEL Hold (high to invalid)	0	—	ns

† t45, t47, and t49 are referenced to the falling edge of PCSN or PODS(PDS), whichever occurs last.

‡ t46, t48, and t50 are referenced to the rising edge of PCSN or PODS(PDS), whichever occurs first.

Table 93. Timing Characteristics for *Intel* and *Motorola* Mode Signaling (Status Register Read) (3.0 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t49†	PCSN to PB Read (low to valid)	—	12	ns
t50‡	PCSN to PB Read Hold (high to invalid)	0	—	ns
t154	PCSN to PB Read 3-state (high to 3-state)	—	8	ns

† t45, t47, and t49 are referenced to the falling edge of PCSN or PODS(PDS), whichever occurs last.

‡ t46, t48, t154, and t50 are referenced to the rising edge of PCSN or PODS(PDS), whichever occurs first.

10 Timing Characteristics for 3.0 V Operation (continued)

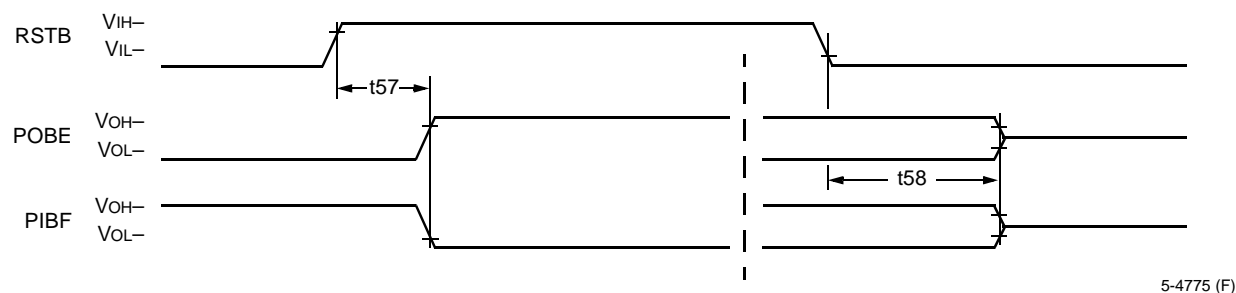
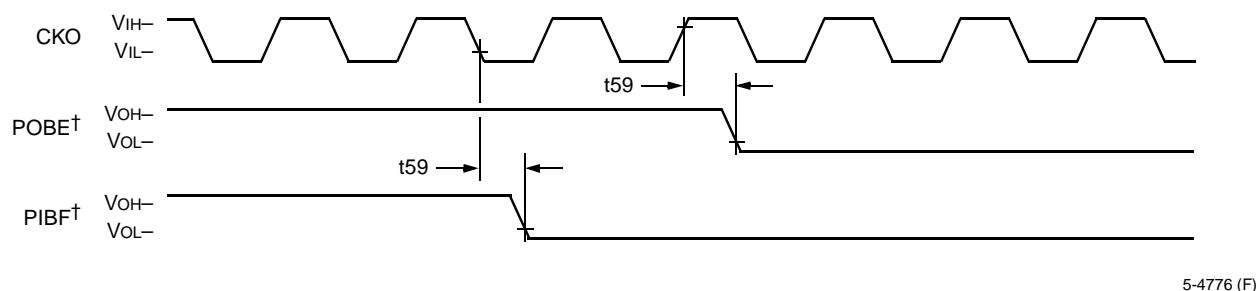


Figure 28. PHIF, PIBF, and POBE Reset Timing Diagram (3.0 V Operation)

Table 94. PHIF Timing Characteristics for PHIF, PIBF, and POBE Reset (3.0 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t57	RSTB Disable to POBE/PIBF* (high to valid)	—	25	ns
t58	RSTB Enable to POBE/PIBF* (low to invalid)	3	25	ns

* After reset, POBE and PIBF always go to the levels shown, indicating output buffer empty and input buffer empty. The DSP program, however, may later invert the definition of the logic levels for POBE and PIBF. t57 and t58 continue to apply.



† POBE and PIBF can be programmed to be active-high or active-low. They are shown active-high. The timing characteristic for active-low is the same as for active-high.

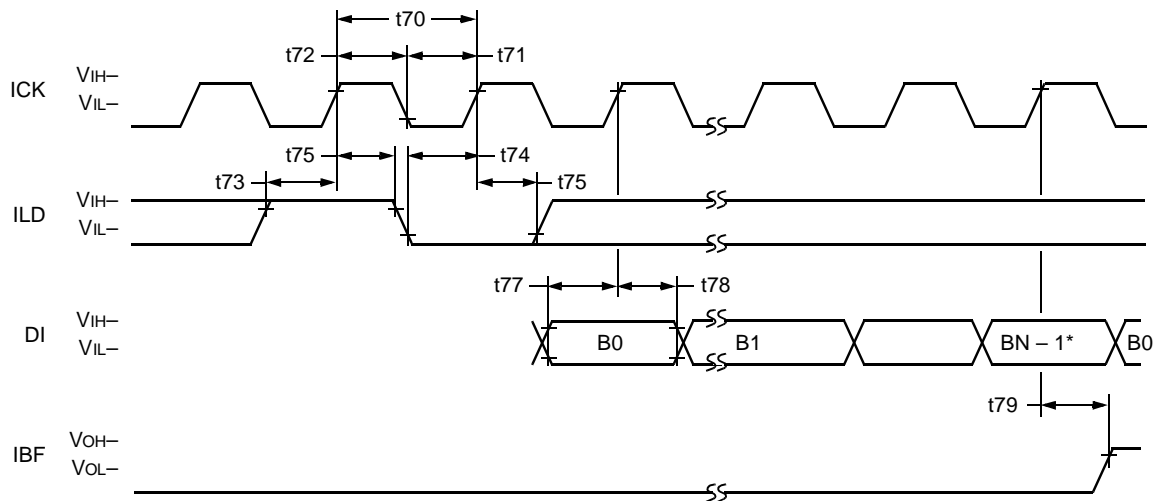
Figure 29. PHIF, PIBF, and POBE Disable Timing Diagram (3.0 V Operation)

Table 95. PHIF Timing Characteristics for POBE and PIBF Disable (3.0 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t59	CKO to POBE/PIBF Disable (high/low to disable)	—	20	ns

10 Timing Characteristics for 3.0 V Operation (continued)

10.9 Serial I/O Specifications (3.0 V Operation)



5-4777 (F)

* N = 16 bits or 8 bits.

Figure 30. SIO Passive Mode Input Timing Diagram (3.0 V Operation)

Table 96. Timing Requirements for Serial Inputs (3.0 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t70	Clock Period (high to high) [†]	40	— [‡]	ns
t71	Clock Low Time (low to high)	18	—	ns
t72	Clock High Time (high to low)	18	—	ns
t73	Load High Setup (high to high)	8	—	ns
t74	Load Low Setup (low to high)	8	—	ns
t75	Load High Hold (high to invalid)	0	—	ns
t77	Data Setup (valid to high)	7	—	ns
t78	Data Hold (high to invalid)	0	—	ns

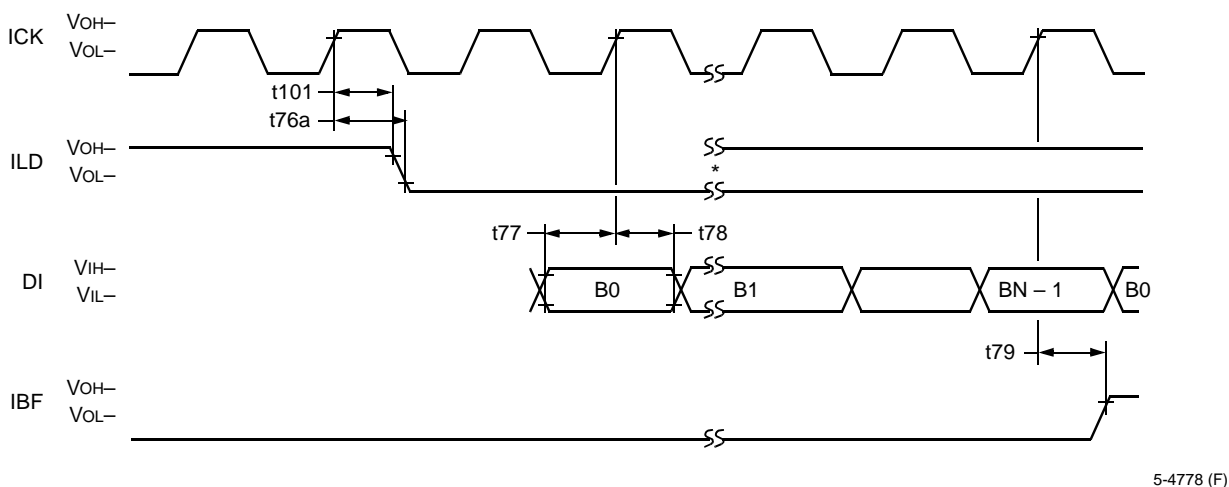
[†] For multiprocessor mode, see note in Section 11.10, Multiprocessor Communication (2.7 V Operation).

[‡] Device is fully static; t70 is tested at 200 ns.

Table 97. Timing Characteristics for Serial Outputs (3.0 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t79	IBF Delay (high to high)	—	35	ns

10 Timing Characteristics for 3.0 V Operation (continued)



* ILD goes high during bit 6 (of 0:15); N = 8 or 16.

Figure 31. SIO Active Mode Input Timing Diagram (3.0 V Operation)

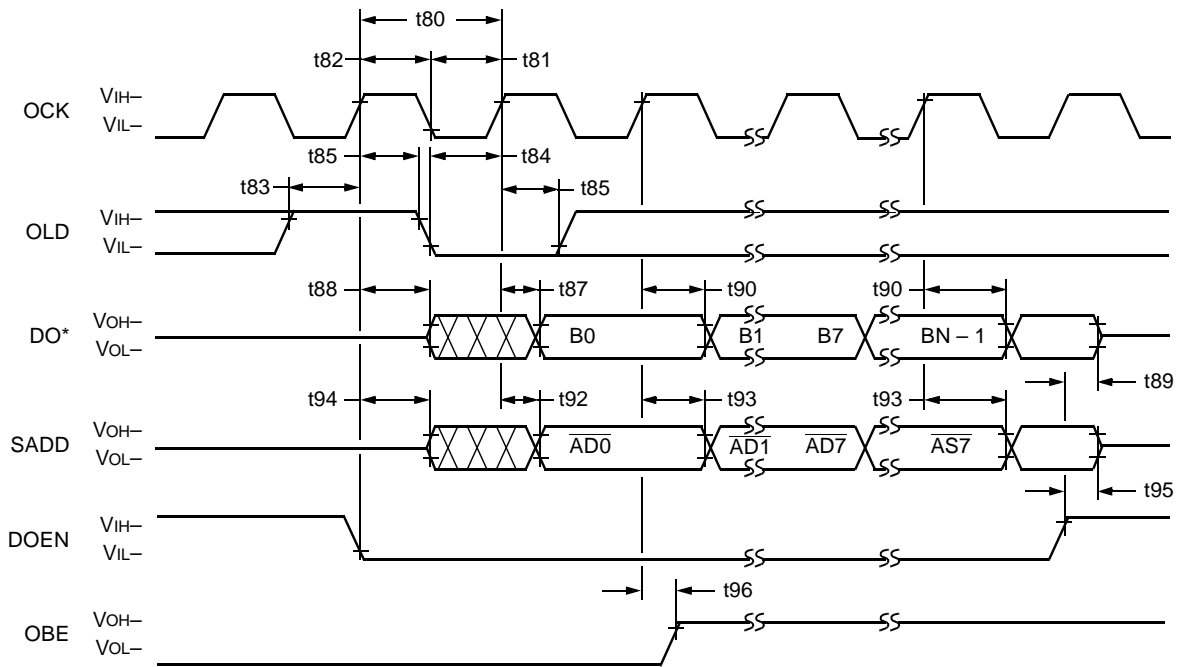
Table 98. Timing Requirements for Serial Inputs (3.0 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t77	Data Setup (valid to high)	7	—	ns
t78	Data Hold (high to invalid)	0	—	ns

Table 99. Timing Characteristics for Serial Outputs (3.0 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t76a	ILD Delay (high to low)	—	35	ns
t101	ILD Hold (high to invalid)	3	—	ns
t79	IBF Delay (high to high)	—	35	ns

10 Timing Characteristics for 3.0 V Operation (continued)



5-4796 (F)

* See **sioc** register, MSB field, to determine if B0 is the MSB or LSB. See **sioc** register, ILEN field, to determine if the DO word length is 8 bits or 16 bits.

Figure 32. SIO Passive Mode Output Timing Diagram (3.0 V Operation)

Table 100. Timing Requirements for Serial Inputs (3.0 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t80	Clock Period (high to high) [†]	40	— [‡]	ns
t81	Clock Low Time (low to high)	18	—	ns
t82	Clock High Time (high to low)	18	—	ns
t83	Load High Setup (high to high)	8	—	ns
t84	Load Low Setup (low to high)	8	—	ns
t85	Load Hold (high to invalid)	0	—	ns

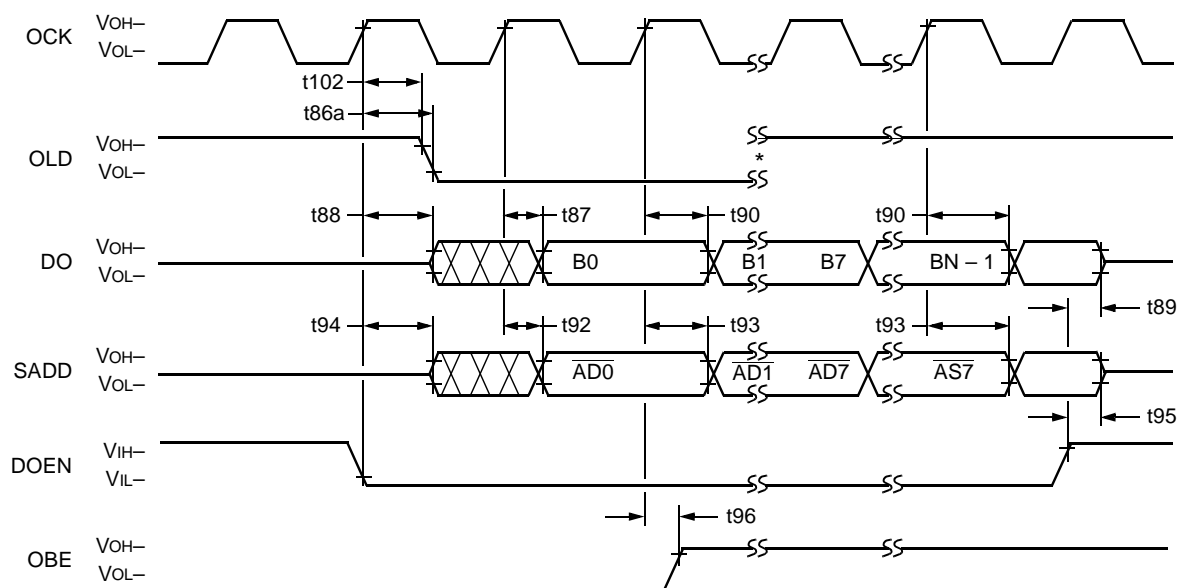
[†] For multiprocessor mode, see note in Section 11.10, Multiprocessor Communication (2.7 V Operation).

[‡] Device is fully static; t80 is tested at 200 ns.

Table 101. Timing Characteristics for Serial Outputs (3.0 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t87	Data Delay (high to valid)	—	35	ns
t88	Enable Data Delay (low to active)	—	35	ns
t89	Disable Data Delay (high to 3-state)	—	35	ns
t90	Data Hold (high to invalid)	3	—	ns
t92	Address Delay (high to valid)	—	35	ns
t93	Address Hold (high to invalid)	3	—	ns
t94	Enable Delay (low to active)	—	35	ns
t95	Disable Delay (high to 3-state)	—	35	ns
t96	OBE Delay (high to high)	—	35	ns

10 Timing Characteristics for 3.0 V Operation (continued)



5-4797 (F)

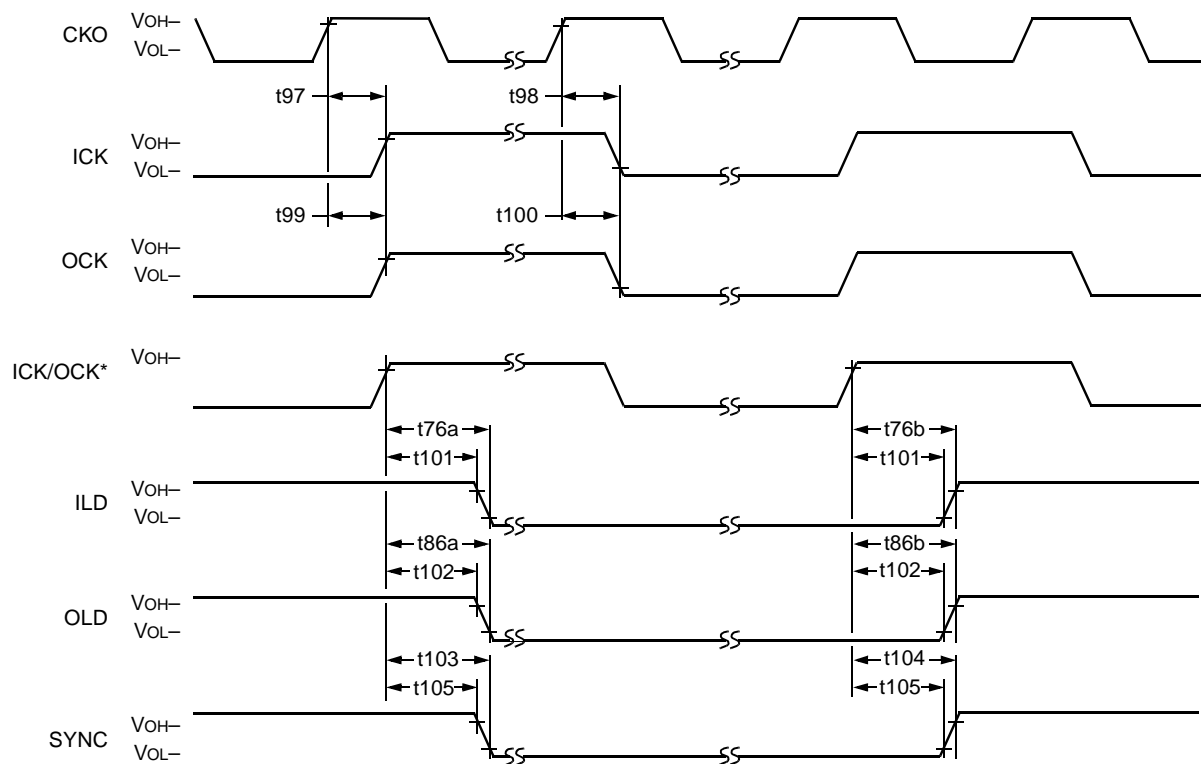
* OLD goes high at the end of bit 6 of 0:15.

Figure 33. SIO Active Mode Output Timing Diagram (3.0 V Operation)

Table 102. Timing Characteristics for Serial Output (3.0 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t86a	OLD Delay (high to low)	—	35	ns
t102	OLD Hold (high to invalid)	3	—	ns
t87	Data Delay (high to valid)	—	35	ns
t88	Enable Data Delay (low to active)	—	35	ns
t89	Disable Data Delay (high to 3-state)	—	35	ns
t90	Data Hold (high to invalid)	3	—	ns
t92	Address Delay (high to valid)	—	35	ns
t93	Address Hold (high to invalid)	3	—	ns
t94	Enable Delay (low to active)	—	35	ns
t95	Disable Delay (high to 3-state)	—	35	ns
t96	OBE Delay (high to high)	—	35	ns

10 Timing Characteristics for 3.0 V Operation (continued)



5-4798 (F)

* See **sioc** register, LD field.

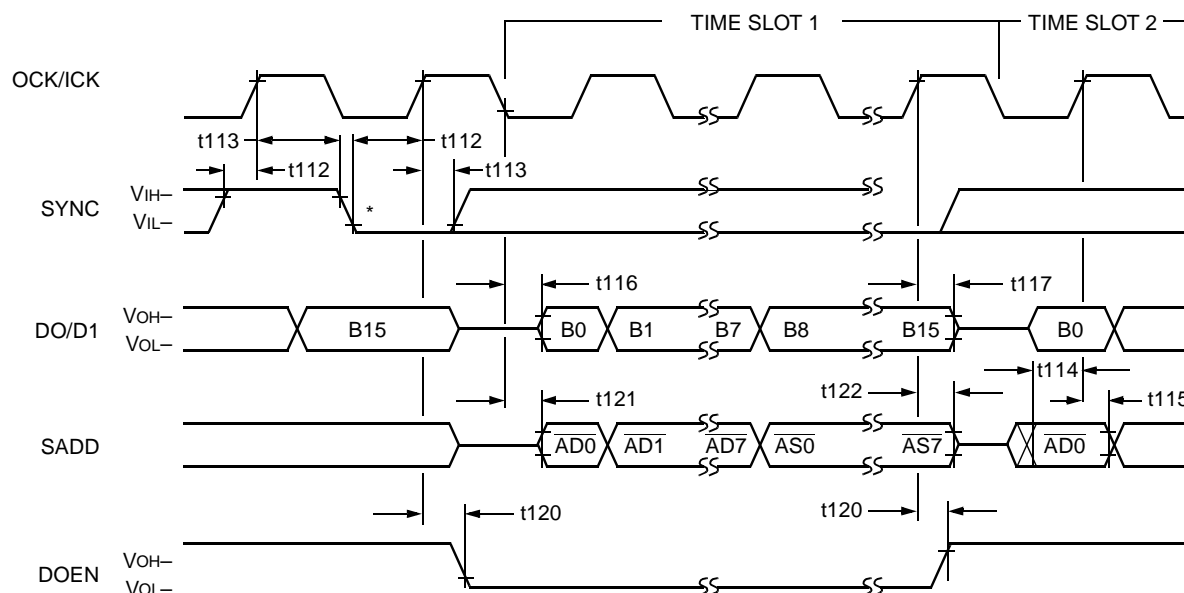
Figure 34. Serial I/O Active Mode Clock Timing (3.0 V Operation)

Table 103. Timing Characteristics for Signal Generation (3.0 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t97	ICK Delay (high to high)	—	18	ns
t98	ICK Delay (high to low)	—	18	ns
t99	OCK Delay (high to high)	—	18	ns
t100	OCK Delay (high to low)	—	18	ns
t76a	ILD Delay (high to low)	—	35	ns
t76b	ILD Delay (high to high)	—	35	ns
t101	ILD Hold (high to invalid)	3	—	ns
t86a	OLD Delay (high to low)	—	35	ns
t86b	OLD Delay (high to high)	—	35	ns
t102	OLD Hold (high to invalid)	3	—	ns
t103	SYNC Delay (high to low)	—	35	ns
t104	SYNC Delay (high to high)	—	35	ns
t105	SYNC Hold (high to invalid)	3	—	ns

10 Timing Characteristics for 3.0 V Operation (continued)

10.10 Multiprocessor Communication (3.0 V Operation)



5-4799 (F)

* Negative edge initiates time slot 0.

Figure 35. SIO Multiprocessor Timing Diagram (3.0 V Operation)

Note: All serial I/O timing requirements and characteristics still apply, but the minimum clock period in passive multiprocessor mode, assuming 50% duty cycle, is calculated as $(t_{77} + t_{116}) * 2$.

Table 104. Timing Requirements for SIO Multiprocessor Communication (3.0 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t112	Sync Setup (high/low to high)	35	—	ns
t113	Sync Hold (high to high/low)	0	—	ns
t114	Address Setup (valid to high)	12	—	ns
t115	Address Hold (high to invalid)	0	—	ns

Table 105. Timing Characteristics for SIO Multiprocessor Communication (3.0 V Operation)

Abbreviated Reference [†]	Parameter	Min	Max	Unit
t116	Data Delay (bit 0 only) (low to valid)	—	35	ns
t117	Data Disable Delay (high to 3-state)	—	30	ns
t120	DOEN Valid Delay (high to valid)	—	25	ns
t121	Address Delay (bit 0 only) (low to valid)	—	35	ns
t122	Address Disable Delay (high to 3-state)	—	30	ns

[†] With capacitance load on ICK, OCK, DO, SYNC, and SADD = 100 pF, add 4 ns to t116—t122.

11 Timing Characteristics for 2.7 V Operation

The following timing characteristics and requirements are preliminary information and are subject to change. Timing characteristics refer to the behavior of the device under specified conditions. Timing requirements refer to conditions imposed on the user for proper operation of the device. All timing data is valid for the following conditions:

$T_A = -40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$ (See Section 8.3, Recommended Operating Conditions.)

$V_{DD} = 3\text{ V} \pm 10\%$, $V_{SS} = 0\text{ V}$ (See Section 8.3, Recommended Operating Conditions.)

Capacitance load on outputs (C_L) = 50 pF, except for CKO, where $C_L = 20\text{ pF}$.

Output characteristics can be derated as a function of load capacitance (C_L).

All outputs: $0.03\text{ ns/pF} \leq dt/dC_L \leq 0.07\text{ ns/pF}$ for $10 \leq C_L \leq 100\text{ pF}$ at V_{IH} for rising edge and at V_{IL} for falling edge.

For example, if the actual load capacitance is 30 pF instead of 50 pF, the derating for a rising edge is $(30 - 50)\text{ pF} \times 0.06\text{ ns/pF} = 1.2\text{ ns}$ **less** than the specified rise time or delay that includes a rise time.

Test conditions for inputs:

- Rise and fall times of 4 ns or less
- Timing reference levels for delays = V_{IH} , V_{IL}

Test conditions for outputs (unless noted otherwise):

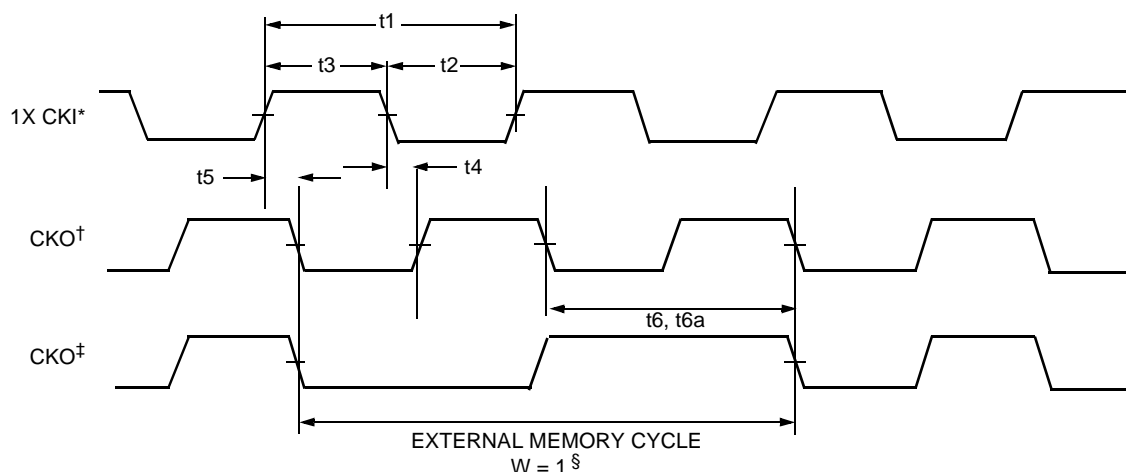
- $C_{LOAD} = 50\text{ pF}$; except for CKO, where $C_{LOAD} = 20\text{ pF}$
- Timing reference levels for delays = V_{IH} , V_{IL}
- 3-state delays measured to the high-impedance state of the output driver

For the timing diagrams, see Table 62, Electrical Requirements for Mask-Programmable Input Clock Options, for input clock requirements.

Unless otherwise noted, CKO in the timing diagrams is the free-running CKO.

11 Timing Characteristics for 2.7 V Operation (continued)

11.1 DSP Clock Generation (2.7 V Operation)



5-4009 (F).a

* See Table 62, Electrical Requirements for Mask-Programmable Input Clock Options, for input clock electrical requirements.

† Free-running clock.

‡ Wait-stated clock (see Table 38, ioc Register).

§ W = number of wait-states.

Figure 36. I/O Clock Timing Diagram (2.7 V Operation)

Table 106. Timing Requirements for Input Clock (2.7 V Operation)

Abbreviated Reference	Parameter	19.2 ns and 12.5 ns†		
		Min	Max	Unit
t1	Clock In Period (high to high)	20	—‡	ns
t2	Clock In Low Time (low to high)	10	—	ns
t3	Clock In High Time (high to low)	10	—	ns

† Device speeds greater than 50 MIPS do not support 1X operation. Use the PLL.

‡ Device is fully static, t1 is tested at 100 ns for 1X input clock option, and memory hold time is tested at 0.1 s.

Table 107. Timing Characteristics for Input Clock and Output Clock (2.7 V Operation)

Abbreviated Reference	Parameter	19.2 ns		12.5 ns		Unit
		Min	Max	Min	Max	
t4	Clock Out High Delay	—	14	—	10	ns
t5	Clock Out Low Delay (high to low)	—	14	—	10	ns
t6	Clock Out Period (low to low)	T†	—	T†	—	ns
t6a	Clock Out Period with SLOWCKI Bit Set in powerc Register (low to low)	0.74	3.8	0.74	3.8	μs

† T = internal clock period, set by CKI or by CKI and the PLL parameters.

11 Timing Characteristics for 2.7 V Operation (continued)

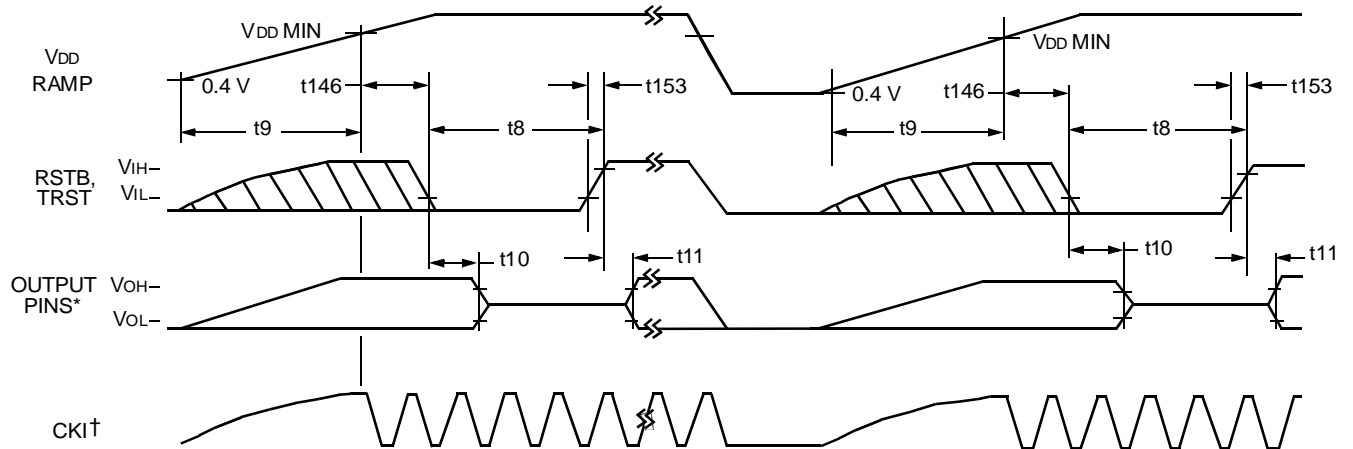
11.2 Reset Circuit (2.7 V Operation)

The DSP1629 has two external reset pins: RSTB and TRST. At initial powerup, or if the supply voltage falls below $V_{DD\ MIN}^*$ and a device reset is required, both TRST and RSTB must be asserted to initialize the device. Figure 37, Powerup Reset and Chip Reset Timing Diagram (2.7 V Operation), shows two separate events:

- Chip reset at initial powerup.
- Chip reset following a drop in power supply.

Note: The TRST pin must be asserted even if the JTAG controller is not used by the application.

* See Table 60, Recommended Operating Conditions.



5-4010 (F).a

* When both INT0 and RSTB are asserted, all output and bidirectional pins (except TDO, which 3-states by JTAG control) are put in a 3-state condition. With RSTB asserted and INT0 not asserted, EROM, ERAMHI, ERAMLO, IO, and RWN outputs remain high, and CKO remains a free-running clock.

† See Table 62, Electrical Requirements for Mask-Programmable Input Clock Options, for input clock electrical requirements.

Figure 37. Powerup Reset and Chip Reset Timing Diagram (2.7 V Operation)

Table 108. Timing Requirements for Powerup Reset and Chip Reset (2.7 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t8	RSTB and TRST Reset Pulse (low to high)	6T	—	ns
t9	VDD Ramp	—	10	ms
t146	VDD MIN to RSTB Low: CMOS	2T	—	ns
		20	—	μs
t153	RSTB (low to high)	—	54	ns

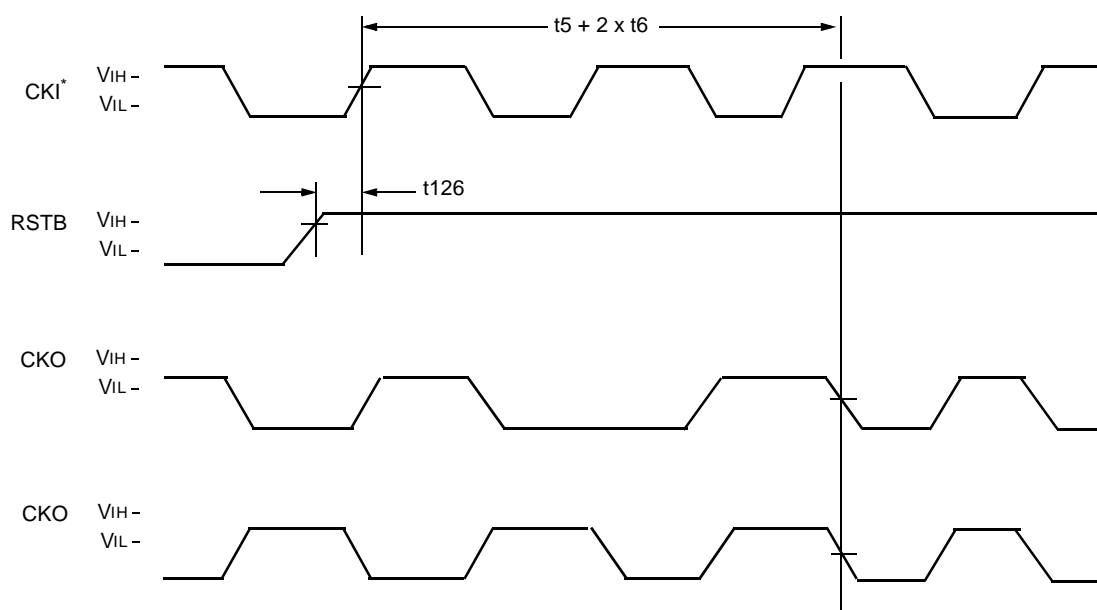
Table 109. Timing Characteristics for Powerup Reset and Chip Reset (2.7 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t10	RSTB Disable Time (low to 3-state)	—	100	ns
t11	RSTB Enable Time (high to valid)	—	100	ns

Note: The device needs to be clocked for at least six CKI cycles during reset after powerup. Otherwise, high currents may flow.

11 Timing Characteristics for 2.7 V Operation (continued)

11.3 Reset Synchronization (2.7 V Operation)



5-4011 (F).a

* See Table 62, Electrical Requirements for Mask-Programmable Input Clock Options, for input clock electrical requirements.

Notes:

CKO1 and CKO2 are two possible CKO states before reset. CKO is free-running.

If the rising edge of RSTB (low to high) is captured instead by the falling edge of CKO (high to low), CKO and CKI will be in-phase at $t_5 + 2 \times t_6$.

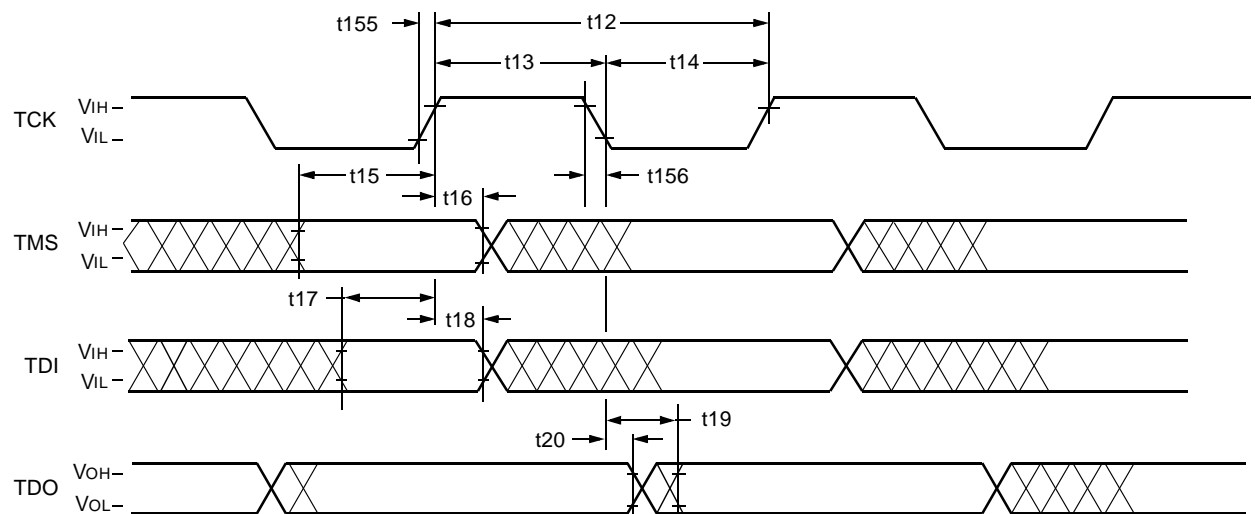
Figure 38. Reset Synchronization Timing (2.7 V Operation)

Table 110. Timing Requirements for Reset Synchronization Timing (2.7 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t_{126}	Reset Setup (high to high)	3	$T/2 - 1$	ns

11 Timing Characteristics for 2.7 V Operation (continued)

11.4 JTAG I/O Specifications (2.7 V Operation)



5-4017 (F)

Figure 39. JTAG Timing Diagram (2.7 V Operation)

Table 111. Timing Requirements for JTAG Input/Output (2.7 V Operation)

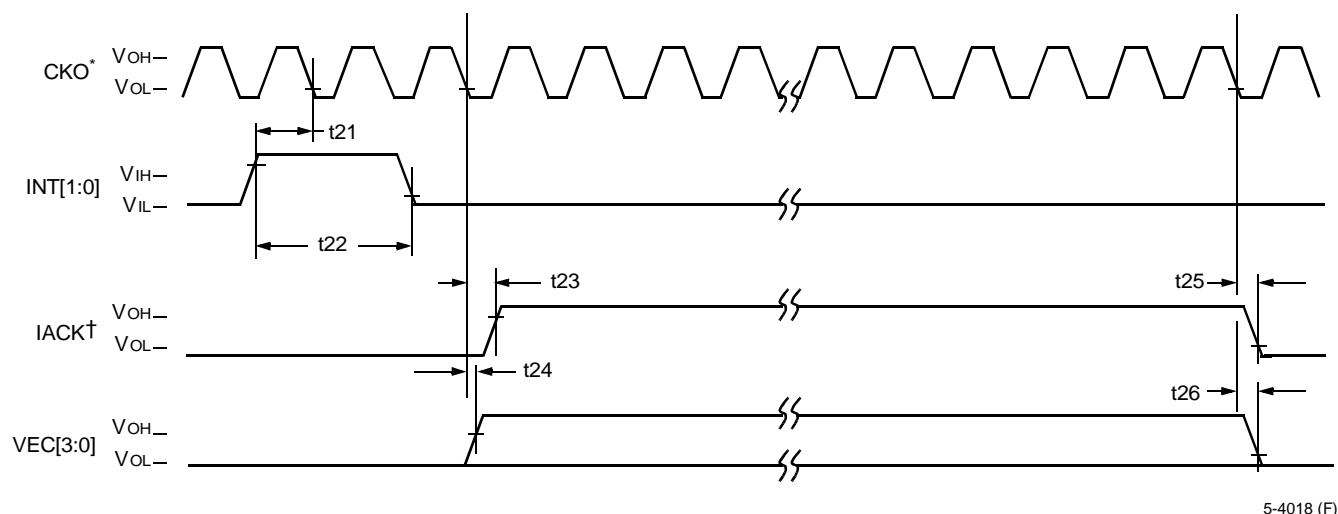
Abbreviated Reference	Parameter	Min	Max	Unit
t12	TCK Period (high to high)	50	—	ns
t13	TCK High Time (high to low)	22.5	—	ns
t14	TCK Low Transition Time (low to high)	22.5	—	ns
t155	TCK Rise Transition Time (low to high)	0.6	—	V/ns
t156	TCK Fall Transition Time (high to low)	0.6	—	V/ns
t15	TMS Setup Time (valid to high)	7.5	—	ns
t16	TMS Hold Time (high to invalid)	2	—	ns
t17	TDI Setup Time (valid to high)	7.5	—	ns
t18	TDI Hold Time (high to invalid)	2	—	ns

Table 112. Timing Characteristics for JTAG Input/Output (2.7 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t19	TDO Delay (low to valid)	—	19	ns
t20	TDO Hold (low to invalid)	0	—	ns

11 Timing Characteristics for 2.7 V Operation (continued)

11.5 Interrupt (2.7 V Operation)



* CKO is free-running.

† IACK assertion is guaranteed to be enclosed by VEC[3:0] assertion.

Figure 40. Interrupt Timing Diagram (2.7 V Operation)

Table 113. Timing Requirements for Interrupt (2.7 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t21	Interrupt Setup (high to low)	19	—	ns
t22	INT Assertion Time (high to low)	2T	—	ns

Note: Interrupt is asserted during an interruptible instruction and no other pending interrupts.

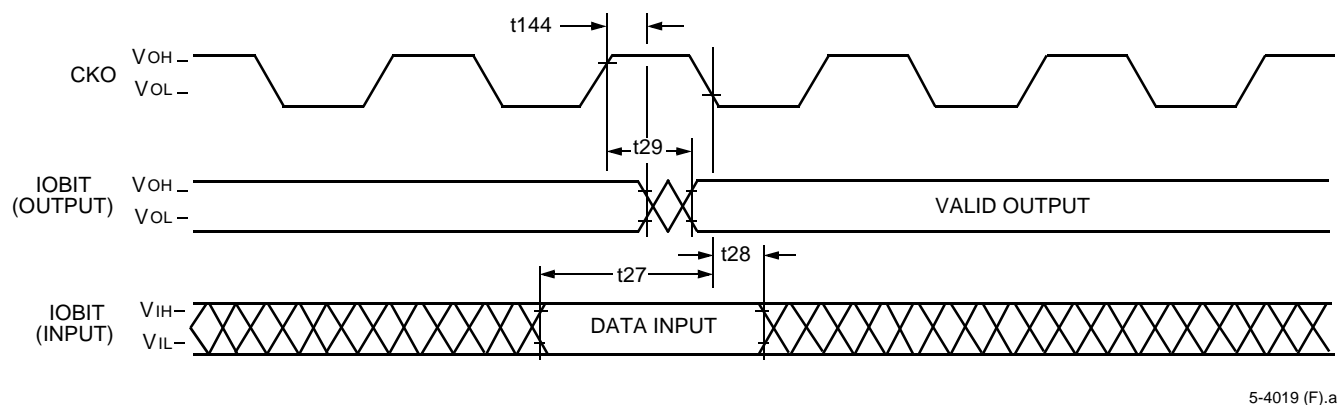
Table 114. Timing Characteristics for Interrupt (2.7 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t23	IACK Assertion Time (low to high)	—	T/2 + 10	ns
t24	VEC Assertion Time (low to high)	—	12.5	ns
t25	IACK Invalid Time (low to low)	—	10	ns
t26	VEC Invalid Time (low to low)	—	12.5	ns

Note: Interrupt is asserted during an interruptible instruction and no other pending interrupts.

11 Timing Characteristics for 2.7 V Operation (continued)

11.6 Bit Input/Output (BIO) (2.7 V Operation)



5-4019 (F).a

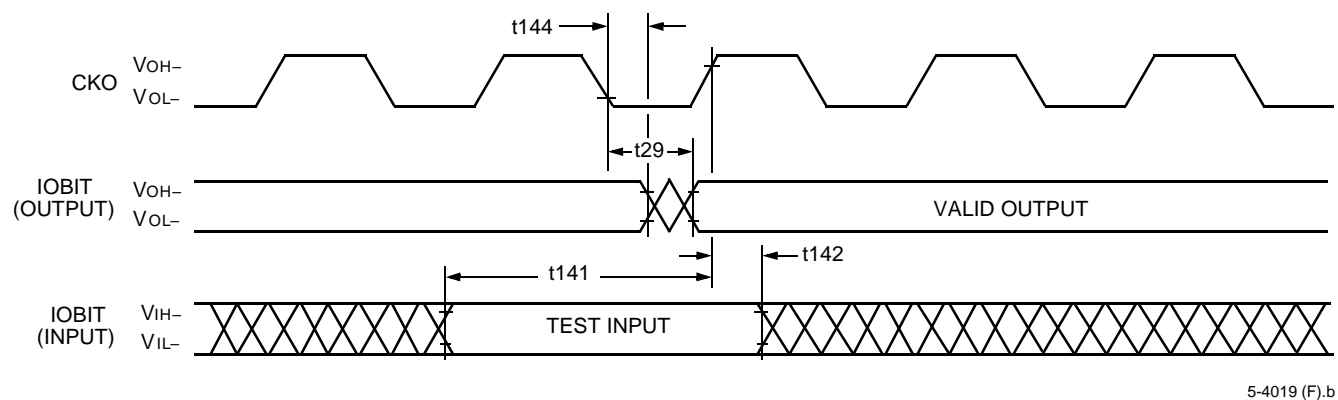
Figure 41. Write Outputs Followed by Read Inputs (cbit = Immediate; a1 = sbit) (2.7 V Operation)

Table 115. Timing Requirements for BIO Input Read (2.7 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t27	IOBIT Input Setup Time (valid to high)	15	—	ns
t28	IOBIT Input Hold Time (high to invalid)	0	—	ns

Table 116. Timing Characteristics for BIO Output (2.7 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t29	IOBIT Output Valid Time (low to valid)	—	9	ns
t144	IOBIT Output Hold Time (low to invalid)	1	—	ns



5-4019 (F).b

Figure 42. Write Outputs and Test Inputs (cbit = Immediate) (2.7 V Operation)

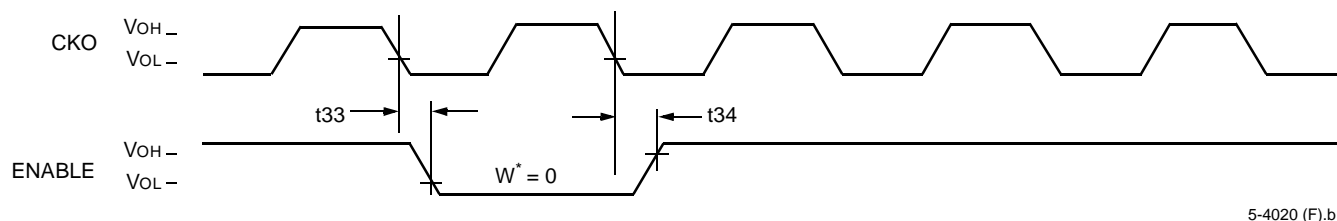
Table 117. Timing Requirements for BIO Input Test (2.7 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t141	IOBIT Input Setup Time (valid to low)	15	—	ns
t142	IOBIT Input Hold Time (low to invalid)	0	—	ns

11 Timing Characteristics for 2.7 V Operation (continued)

11.7 External Memory Interface (2.7 V Operation)

The following timing diagrams, characteristics, and requirements do not apply to interactions with delayed external memory enables unless so stated. See the *DSP1611/17/18/27/28/29 Digital Signal Processor Information Manual* for a detailed description of the external memory interface, including other functional diagrams.



* W = number of wait-states.

Figure 43. Enable Transition Timing (2.7 V Operation)

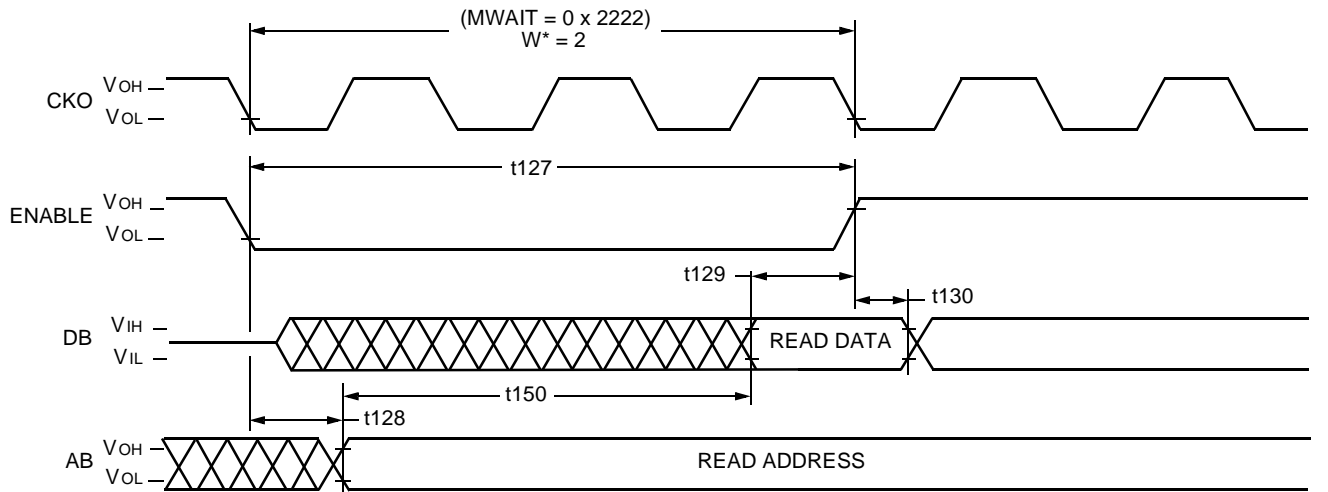
Table 118. Timing Characteristics for External Memory Enables (EROM, ERAMHI, IO, ERAMLO) (2.7 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t33	CKO to ENABLE Active (low to low)	0	5	ns
t34	CKO to ENABLE Inactive (low to high)	-1	4.5	ns

Table 119. Timing Characteristics for Delayed External Memory Enables (ioc = 0x000F) (2.7 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t33	CKO to Delayed ENABLE Active (low to low)	T/2	T/2 + 7	ns

11 Timing Characteristics for 2.7 V Operation (continued)



5-4021 (F).a

* W = number of wait-states.

Figure 44. External Memory Data Read Timing Diagram (2.7 V Operation)

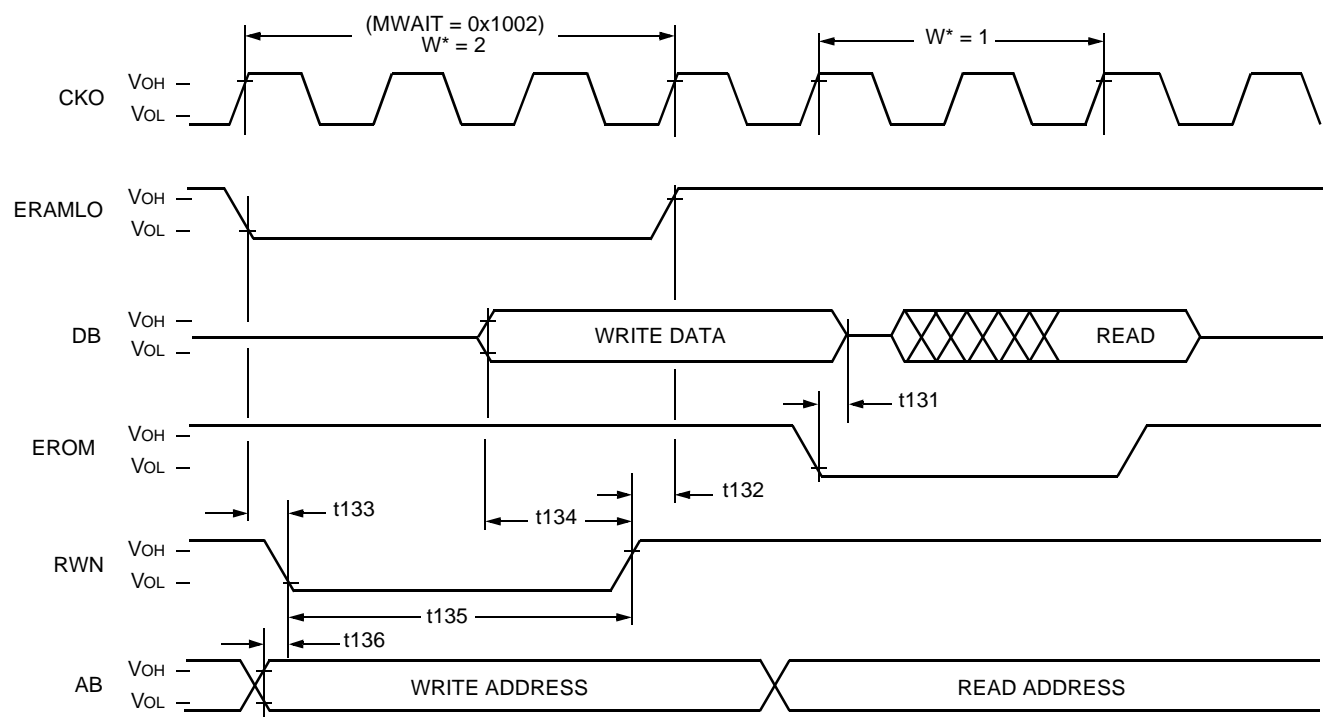
Table 120. Timing Characteristics for External Memory Access (2.7 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t127	Enable Width (low to high)	$T(1 + W) - 1.5$	—	ns
t128	Address Valid (enable low to valid)	—	2.5	ns

Table 121. Timing Requirements for External Memory Read (EROM, ERAMHI, IO, ERAMLO) (2.7 V Operation)

Abbreviated Reference	Parameter	19.2 ns		12.5 ns		Unit
		Min	Max	Min	Max	
t129	Read Data Setup (valid to enable high)	15	—	13	—	ns
t130	Read Data Hold (enable high to hold)	0	—	0	—	ns
t150	External Memory Access Time (valid to valid)	—	$T(1 + W) - 15$	—	$T(1 + W) - 14$	ns

11 Timing Characteristics for 2.7 V Operation (continued)



5-4022 (F).a

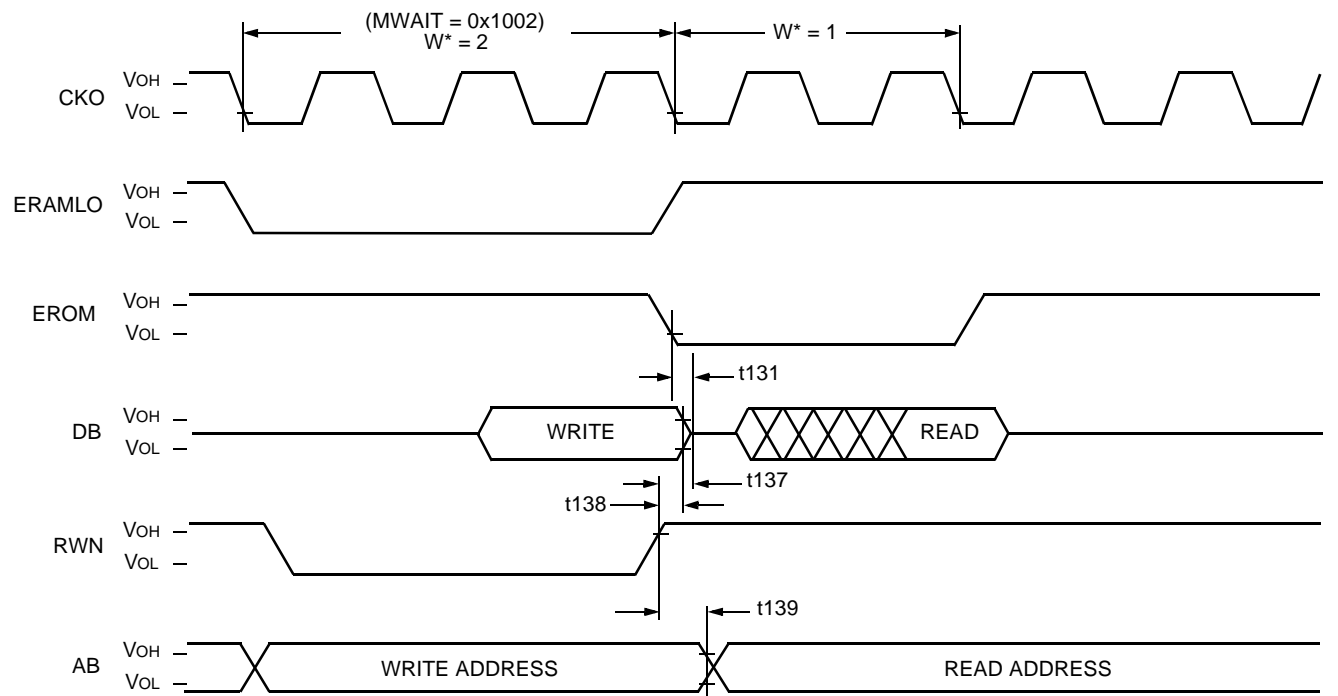
* W = number of wait-states.

Figure 45. External Memory Data Write Timing Diagram (2.7 V Operation)

Table 122. Timing Characteristics for External Memory Data Write (All Enables) (2.7 V Operation)

Abbreviated Reference	Parameter	19.2 ns		12.5 ns		Unit
		Min	Max	Min	Max	
t131	Write Overlap (enable low to 3-state)	—	0	—	0	ns
t132	RWN Advance (RWN high to enable high)	0	—	0	—	ns
t133	RWN Delay (enable low to RWN low)	0	—	0	—	ns
t134	Write Data Setup (data valid to RWN high)	$T(1 + W)/2 - 4$	—	$T(1 + W)/2 - 3$	—	ns
t135	RWN Width (low to high)	$T(1 + W) - 5$	—	$T(1 + W) - 4$	—	ns
t136	Write Address Setup (address valid to RWN low)	0	—	0	—	ns

11 Timing Characteristics for 2.7 V Operation (continued)



5-4023 (F).a

* W = number of wait-states.

Figure 46. Write Cycle Followed by Read Cycle (2.7 V Operation)

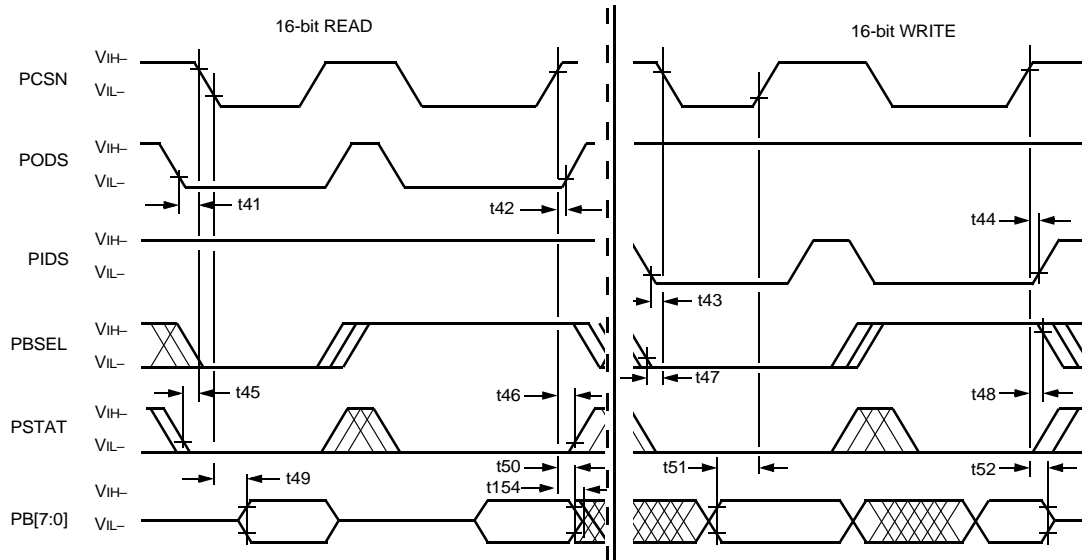
Table 123. Timing Characteristics for Write Cycle Followed by Read Cycle (2.7 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t131	Write Overlap (enable low to 3-state)	—	0	ns
t137	Write Data 3-state (RWN high to 3-state)	—	2	ns
t138	Write Data Hold (RWN high to data hold)	0	—	ns
t139	Write Address Hold (RWN high to address hold)	0	—	ns

11 Timing Characteristics for 2.7 V Operation (continued)

11.8 PHIF Specifications (2.7 V Operation)

For the PHIF, read means read by the external user (output by the DSP); write is similarly defined. The 8-bit reads/writes are identical to one-half of a 16-bit access.



5-4036 (F)

Figure 47. PHIF *Intel* Mode Signaling (Read and Write) Timing Diagram (2.7 V Operation)

Table 124. Timing Requirements for PHIF *Intel* Mode Signaling (2.7 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t41	PODS to PCSN Setup (low to low)	0	—	ns
t42	PCSN to PODS Hold (high to high)	0	—	ns
t43	PIDS to PCSN Setup (low to low)	0	—	ns
t44	PCSN to PIDS Hold (high to high)	0	—	ns
t45*	PSTAT to PCSN Setup (valid to low)	4	—	ns
t46*	PCSN to PSTAT Hold (high to invalid)	0	—	ns
t47*	PBSEL to PCSN Setup (valid to low)	6	—	ns
t48*	PCSN to PBSEL Hold (high to invalid)	0	—	ns
t51*	PB Write to PCSN Setup (valid to high)	10	—	ns
t52*	PCSN to PB Write Hold (high to invalid)	4	—	ns

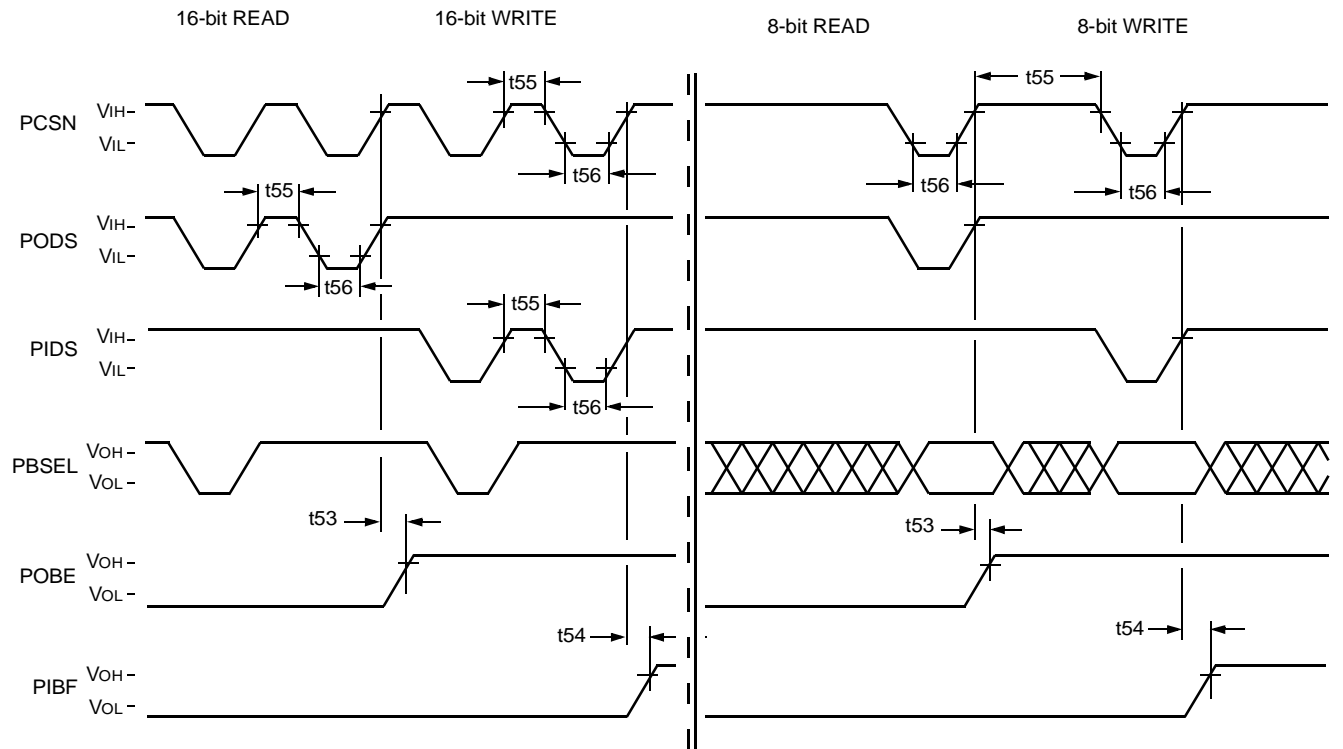
* This timing diagram for the PHIF port shows accesses using the PCSN signal to initiate and complete a transaction. The transactions can also be initiated and completed with the PIDS and PODS signals. An output transaction (read) is initiated by PCSN or PODS going low, whichever comes last. For example, the timing requirements referenced to PCSN going low, t45 and t49, should be referenced to PODS going low, if PODS goes low after PCSN. An output transaction is completed by PCSN or PODS going high, whichever comes first. An input transaction is initiated by PCSN or PIDS going low, whichever comes last. An input transaction is completed by PCSN or PIDS going high, whichever comes first. All requirements referenced to PCSN apply to PIDS or PODS, if PIDS or PODS is the controlling signal.

Table 125. Timing Characteristics for PHIF *Intel* Mode Signaling (2.7 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t49*	PCSN to PB Read (low to valid)	—	12	ns
t50*	PCSN to PB Read Hold (high to invalid)	0	—	ns
t154	PCSN to PB Read 3-state (high to 3-state)	—	8	ns

* This timing diagram for the PHIF port shows accesses using the PCSN signal to initiate and complete a transaction. The transactions can also be initiated and completed with the PIDS and PODS signals. An output transaction (read) is initiated by PCSN or PODS going low, whichever comes last. For example, the timing requirements referenced to PCSN going low, t45 and t49, should be referenced to PODS going low, if PODS goes low after PCSN. An output transaction is completed by PCSN or PODS going high, whichever comes first. An input transaction is initiated by PCSN or PIDS going low, whichever comes last. An input transaction is completed by PCSN or PIDS going high, whichever comes first. All requirements referenced to PCSN apply to PIDS or PODS, if PIDS or PODS is the controlling signal.

11 Timing Characteristics for 2.7 V Operation (continued)



5-4037 (F).a

Figure 48. PHIF *Intel* Mode Signaling (Pulse Period and Flags) Timing Diagram (2.7 V Operation)

Table 126. Timing Requirements for PHIF *Intel* Mode Signaling (2.7 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t55	PCSN/PODS/PIDS Pulse Width (high to low)	20.5	—	ns
t56	PCSN/PODS/PIDS Pulse Width (low to high)	20.5	—	ns

Table 127. Timing Characteristics for PHIF *Intel* Mode Signaling (2.7 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t53*	PCSN/PODS to POBE† (high to high)	—	17	ns
t54*	PCSN/PIDS to PIBF† (high to high)	—	17	ns

* t53 should be referenced to the rising edge of PCSN or PODS, whichever comes first. t54 should be referenced to the rising edge of PCSN or PIDS, whichever comes first.

† POBE and PIBF may be programmed to be the opposite logic levels shown in the diagram (positive assertion levels shown). t53 and t54 apply to the inverted levels as well as those shown.

11 Timing Characteristics for 2.7 V Operation (continued)

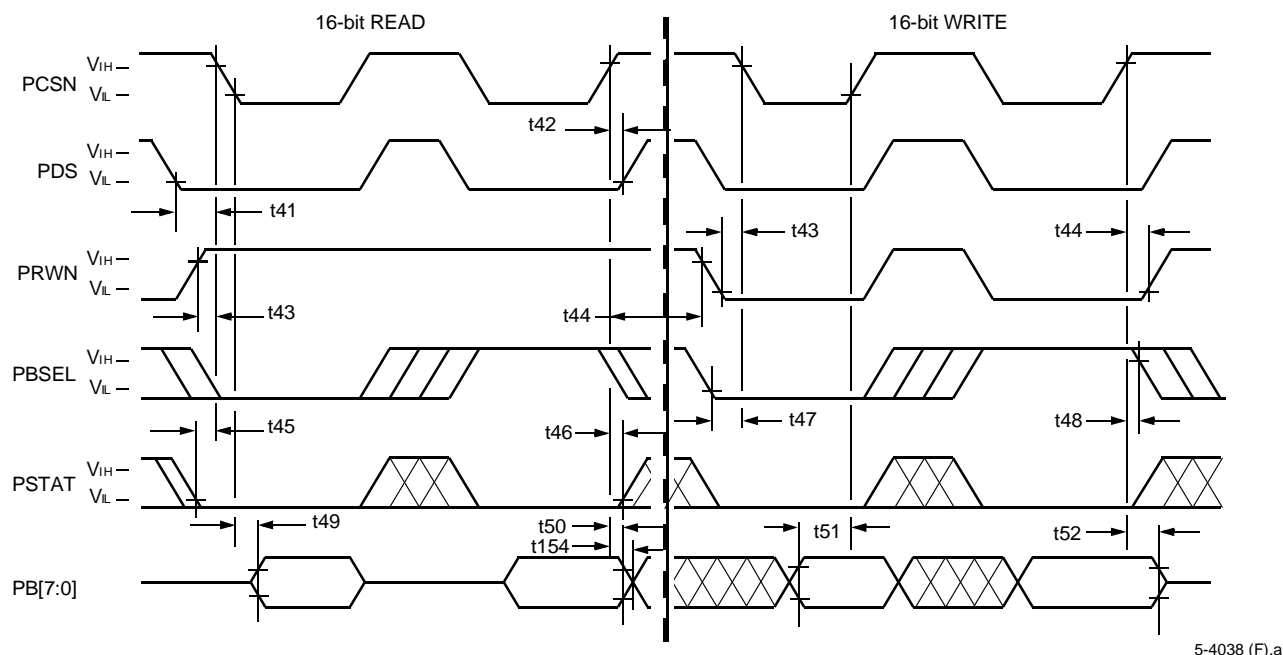


Figure 49. PHIF *Motorola* Mode Signaling (Read and Write) Timing Diagram (2.7 V Operation)

Table 128. Timing Requirements for PHIF *Motorola* Mode Signaling (2.7 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t41	PDS [†] to PCSN Setup (valid to low)	0	—	ns
t42	PCSN to PDS [†] Hold (high to invalid)	0	—	ns
t43	PRWN to PCSN Setup (valid to low)	4	—	ns
t44	PCSN to PRWN Hold (high to invalid)	0	—	ns
t45*	PSTAT to PCSN Setup (valid to low)	4	—	ns
t46*	PCSN to PSTAT Hold (high to invalid)	0	—	ns
t47*	PBSEL to PCSN Setup (valid to low)	6	—	ns
t48*	PCSN to PBSEL Hold (high to invalid)	0	—	ns
t51*	PB Write to PCSN Setup (valid to high)	10	—	ns
t52*	PCSN to PB Write Hold (high to invalid)	4	—	ns

* This timing diagram for the PHIF port shows accesses using the PCSN signal to initiate and complete a transaction. The transactions can also be initiated and completed with the PDS signal. An input/output transaction is initiated by PCSN or PDS going low, whichever comes last. For example, the timing requirements referenced to PCSN going low, t45 and t49, should be referenced to PDS going low, if PDS goes low after PCSN. An input/output transaction is completed by PCSN or PDS going high, whichever comes first. All requirements referenced to PCSN should be referenced to PDS, if PDS is the controlling signal. PRWN should never be used to initiate or complete a transaction.

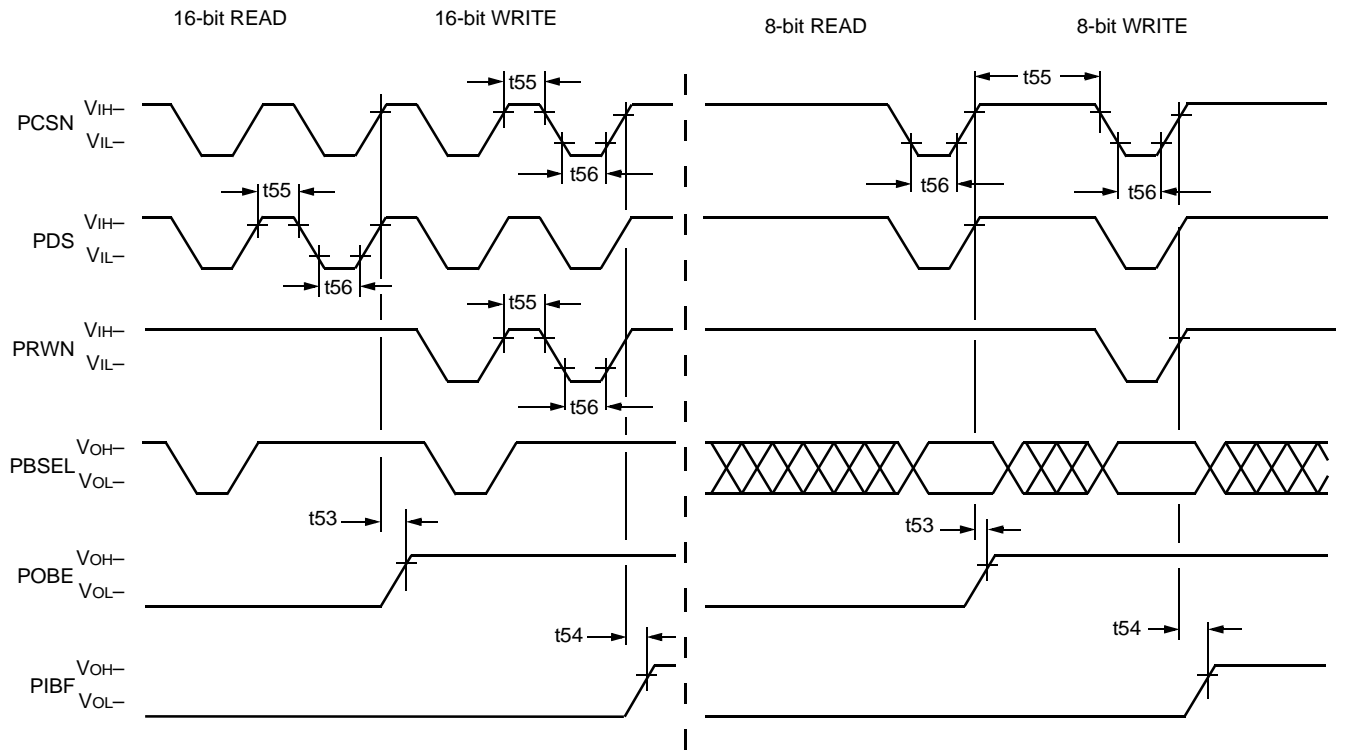
† PDS is programmable to be active-high or active-low. It is shown active-low in Figures 49 and 50. POBE and PIBF may be programmed to be the opposite logic levels shown in the diagram. t53 and t54 apply to the inverted levels as well as those shown.

Table 129. Timing Characteristics for PHIF *Motorola* Mode Signaling (2.7 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t49*	PCSN to PB Read (low to valid)	—	12	ns
t50*	PCSN to PB Read Hold (high to invalid)	0	—	ns
t154	PCSN to PB Read 3-state (high to 3-state)	—	8	ns

* This timing diagram for the PHIF port shows accesses using the PCSN signal to initiate and complete a transaction. The transactions can also be initiated and completed with the PDS signal. An input/output transaction is initiated by PCSN or PDS going low, whichever comes last. For example, the timing requirements referenced to PCSN going low, t45 and t49, should be referenced to PDS going low, if PDS goes low after PCSN. An input/output transaction is completed by PCSN or PDS going high, whichever comes first. All requirements referenced to PCSN should be referenced to PDS, if PDS is the controlling signal. PRWN should never be used to initiate or complete a transaction.

11 Timing Characteristics for 2.7 V Operation (continued)



5-4039 (F).a

Figure 50. PHIF *Motorola* Mode Signaling (Pulse Period and Flags) Timing Diagram (2.7 V Operation)

Table 130. Timing Characteristics for PHIF *Motorola* Mode Signaling (2.7 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t53*	PCSN/PDS [†] to POBE [†] (high to high)	—	17	ns
t54*	PCSN/PDS [†] to PIBF [†] (high to high)	—	17	ns

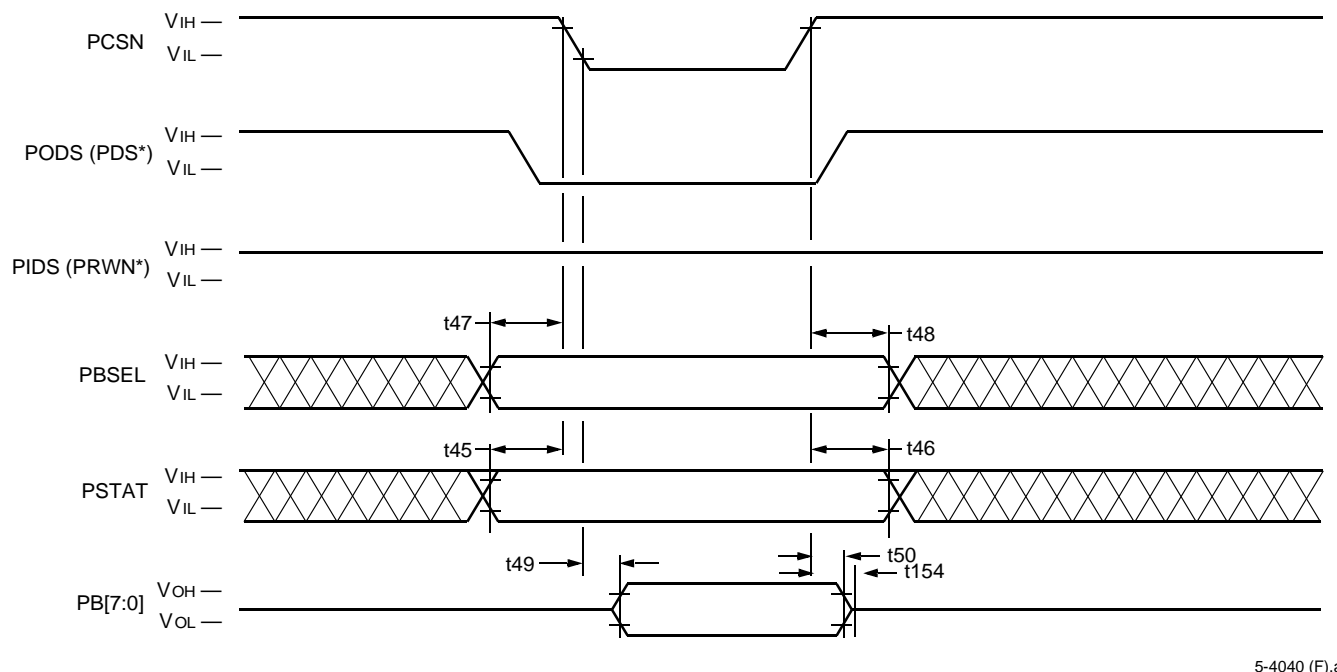
* An input/output transaction is initiated by PCSN or PDS going low, whichever comes last. For example, t53 and t54 should be referenced to PDS going low, if PDS goes low after PCSN. An input/output transaction is completed by PCSN or PDS going high, whichever comes first. All requirements referenced to PCSN should be referenced to PDS, if PDS is the controlling signal. PRWN should never be used to initiate or complete a transaction.

† PDS is programmable to be active-high or active-low. It is shown active-low in Figures 49 and 50. POBE and PIBF may be programmed to be the opposite logic levels shown in the diagram. t53 and t54 apply to the inverted levels as well as those shown.

Table 131. Timing Requirements for PHIF *Motorola* Mode Signaling (2.7 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t55	PCSN/PDS/PRWN Pulse Width (high to low)	20	—	ns
t56	PCSN/PDS/PRWN Pulse Width (low to high)	20	—	ns

11 Timing Characteristics for 2.7 V Operation (continued)



* Motorola mode signal name.

Figure 51. PHIF *Intel* or *Motorola* Mode Signaling (Status Register Read) Timing Diagram (2.7 V Operation)

Table 132. Timing Requirements for *Intel* and *Motorola* Mode Signaling (Status Register Read) (2.7 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t45†	PSTAT to PCSN Setup (valid to low)	4	—	ns
t46‡	PCSN to PSTAT Hold (high to invalid)	0	—	ns
t47†	PBSEL to PCSN Setup (valid to low)	6	—	ns
t48‡	PCSN to PBSEL Hold (high to invalid)	0	—	ns

† t45, t47, and t49 are referenced to the falling edge of PCSN or PODS(PDS), whichever occurs last.

‡ t46, t48, and t50 are referenced to the rising edge of PCSN or PODS(PDS), whichever occurs first.

Table 133. Timing Characteristics for *Intel* and *Motorola* Mode Signaling (Status Register Read) (2.7 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t49†	PCSN to PB Read (low to valid)	—	12	ns
t50‡	PCSN to PB Read Hold (high to invalid)	0	—	ns
t154	PCSN to PB Read 3-state (high to 3-state)	—	8	ns

† t45, t47, and t49 are referenced to the falling edge of PCSN or PODS(PDS), whichever occurs last.

‡ t46, t48, and t50 are referenced to the rising edge of PCSN or PODS(PDS), whichever occurs first.

11 Timing Characteristics for 2.7 V Operation (continued)

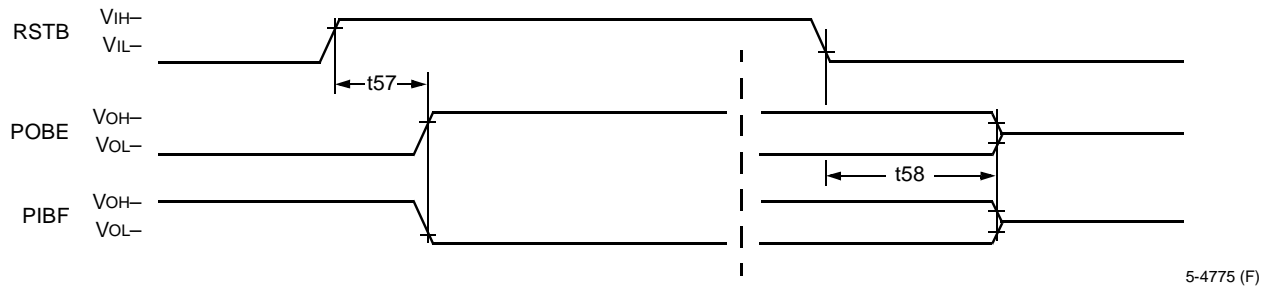
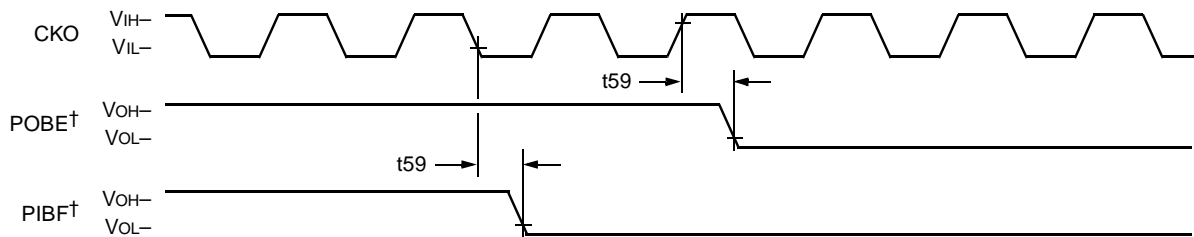


Figure 52. PHIF, PIBF, and POBE Reset Timing Diagram (2.7 V Operation)

Table 134. PHIF Timing Characteristics for PHIF, PIBF, and POBE Reset (2.7 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t57	RSTB Disable to POBE/PIBF* (high to valid)	—	25	ns
t58	RSTB Enable to POBE/PIBF* (low to invalid)	3	25	ns

* After reset, POBE and PIBF always go to the levels shown, indicating output buffer empty and input buffer empty. The DSP program, however, may later invert the definition of the logic levels for POBE and PIBF. t57 and t58 continue to apply.



† POBE and PIBF can be programmed to be active-high or active-low. They are shown active-high. The timing characteristic for active-low is the same as for active-high.

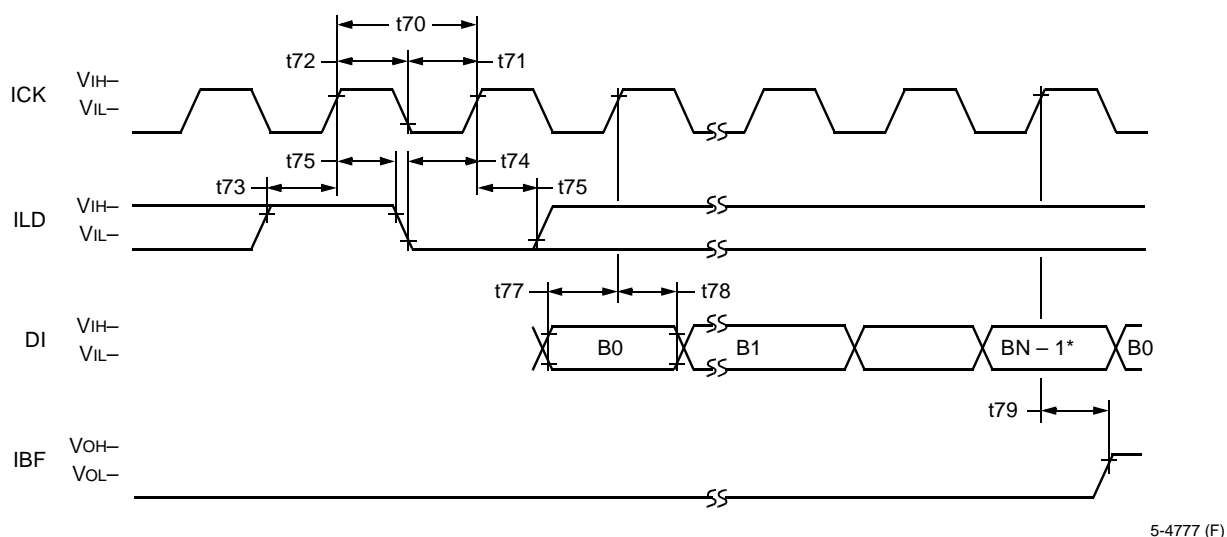
Figure 53. PHIF, PIBF, and POBE Disable Timing Diagram (2.7 V Operation)

Table 135. PHIF Timing Characteristics for POBE and PIBF Disable (2.7 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t59	CKO to POBE/PIBF Disable (high/low to disable)	—	20	ns

11 Timing Characteristics for 2.7 V Operation (continued)

11.9 Serial I/O Specifications (2.7 V Operation)



* N = 16 bits or 8 bits.

Figure 54. SIO Passive Mode Input Timing Diagram (2.7 V Operation)

Table 136. Timing Requirements for Serial Inputs (2.7 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t70	Clock Period (high to high) [†]	40	— [‡]	ns
t71	Clock Low Time (low to high)	18	—	ns
t72	Clock High Time (high to low)	18	—	ns
t73	Load High Setup (high to high)	8	—	ns
t74	Load Low Setup (low to high)	8	—	ns
t75	Load High Hold (high to invalid)	0	—	ns
t77	Data Setup (valid to high)	7	—	ns
t78	Data Hold (high to invalid)	0	—	ns

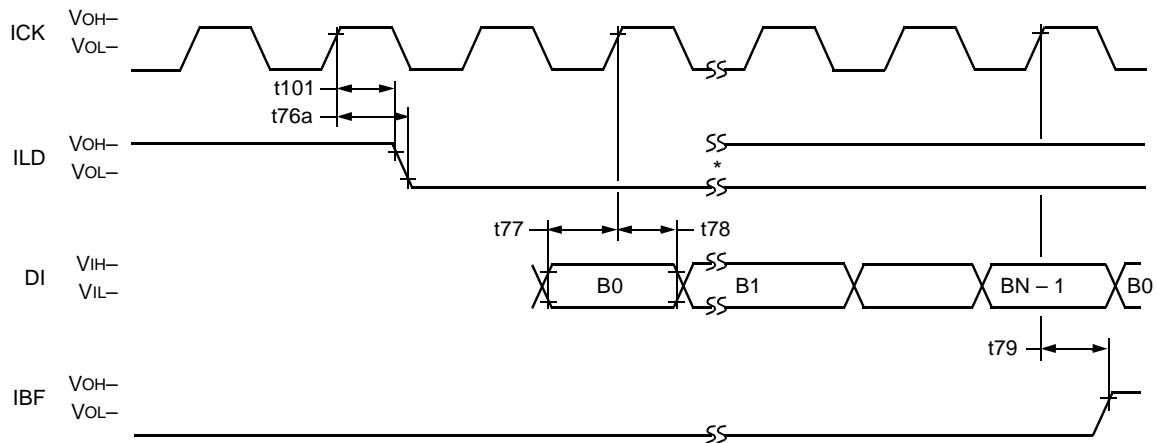
[†] For multiprocessor mode, see note in Section 11.10, Multiprocessor Communication (2.7 V Operation).

[‡] Device is fully static; t70 is tested at 200 ns.

Table 137. Timing Characteristics for Serial Outputs (2.7 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t79	IBF Delay (high to high)	—	35	ns

11 Timing Characteristics for 2.7 V Operation (continued)



5-4778 (F)

* ILD goes high during bit 6 (of 0:15), $N = 8$ or 16.

Figure 55. SIO Active Mode Input Timing Diagram (2.7 V Operation)

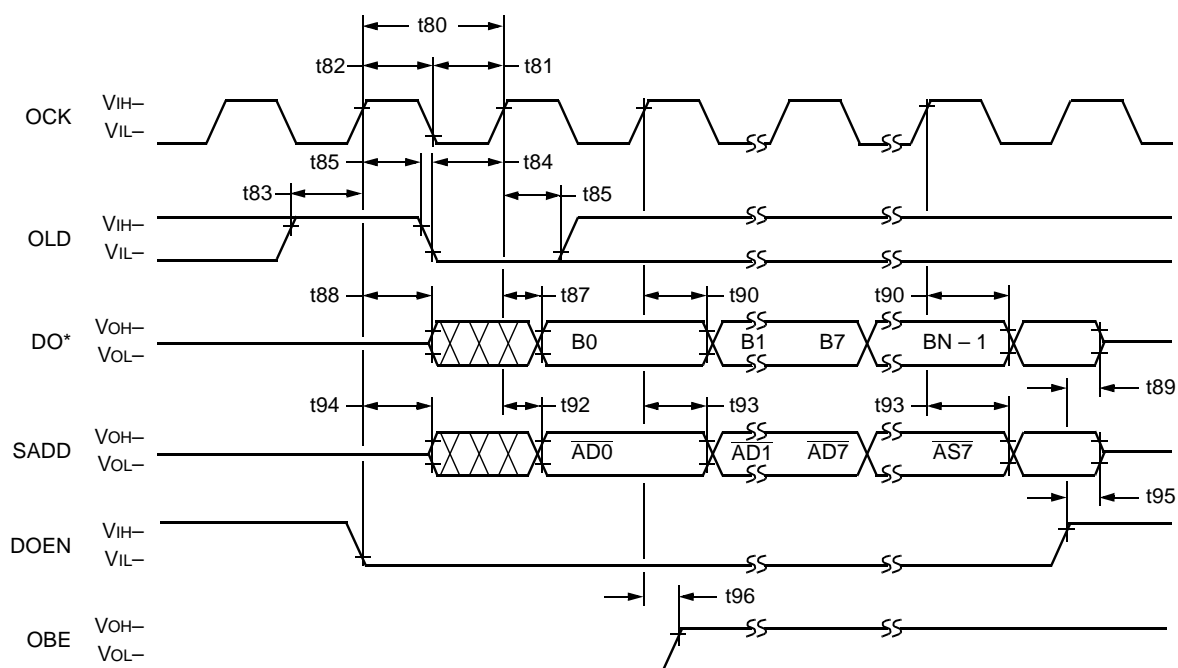
Table 138. Timing Requirements for Serial Inputs (2.7 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t77	Data Setup (valid to high)	7	—	ns
t78	Data Hold (high to invalid)	0	—	ns

Table 139. Timing Characteristics for Serial Outputs (2.7 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t76a	ILD Delay (high to low)	—	35	ns
t101	ILD Hold (high to invalid)	3	—	ns
t79	IBF Delay (high to high)	—	35	ns

11 Timing Characteristics for 2.7 V Operation (continued)



5-4796 (F)

* See **sioc** register, MSB field, to determine if B0 is the MSB or LSB. See **sioc** register, ILEN field, to determine if the DO word length is 8 bits or 16 bits.

Figure 56. SIO Passive Mode Output Timing Diagram (2.7 V Operation)

Table 140. Timing Requirements for Serial Inputs (2.7 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t80	Clock Period (high to high) [†]	40	— [‡]	ns
t81	Clock Low Time (low to high)	18	—	ns
t82	Clock High Time (high to low)	18	—	ns
t83	Load High Setup (high to high)	8	—	ns
t84	Load Low Setup (low to high)	8	—	ns
t85	Load Hold (high to invalid)	0	—	ns

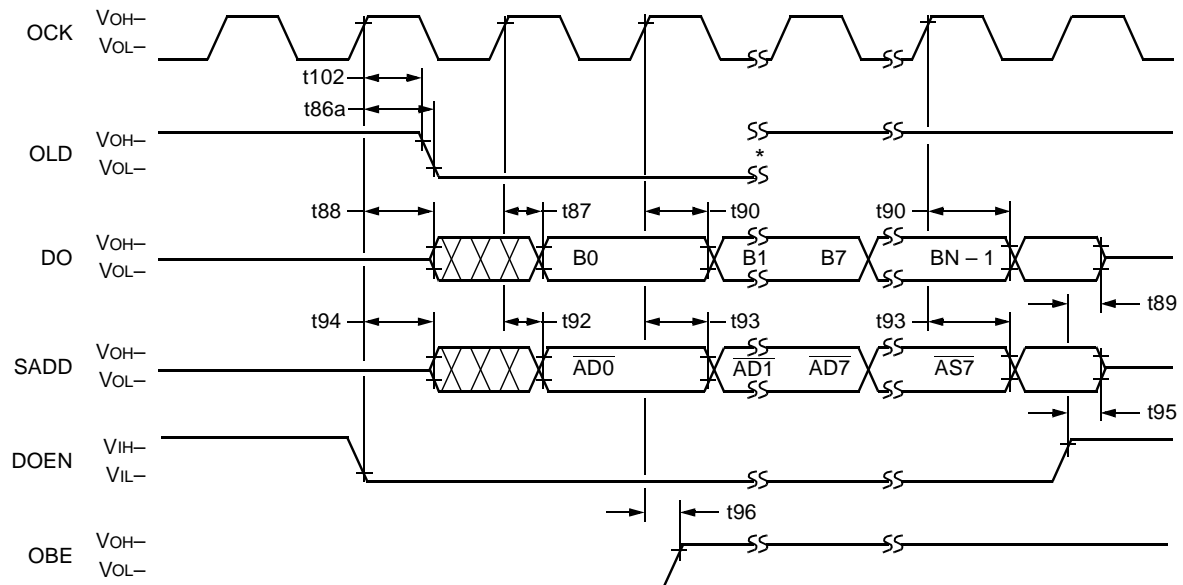
[†] For multiprocessor mode, see note in Section 11.10, Multiprocessor Communication (2.7 V Operation).

[‡] Device is fully static; t80 is tested at 200 ns.

Table 141. Timing Characteristics for Serial Outputs (2.7 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t87	Data Delay (high to valid)	—	35	ns
t88	Enable Data Delay (low to active)	—	35	ns
t89	Disable Data Delay (high to 3-state)	—	35	ns
t90	Data Hold (high to invalid)	3	—	ns
t92	Address Delay (high to valid)	—	35	ns
t93	Address Hold (high to invalid)	3	—	ns
t94	Enable Delay (low to active)	—	35	ns
t95	Disable Delay (high to 3-state)	—	35	ns
t96	OBE Delay (high to high)	—	35	ns

11 Timing Characteristics for 2.7 V Operation (continued)



5-4797 (F)

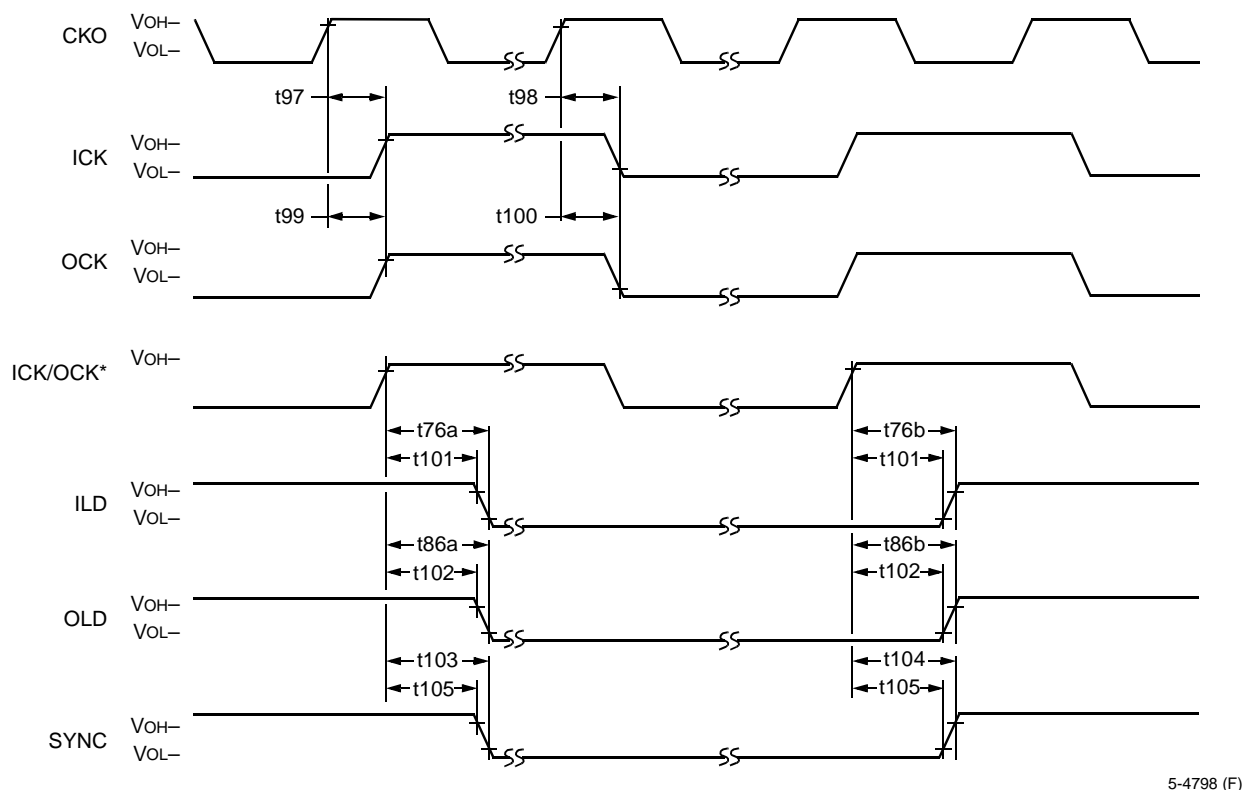
* OLD goes high at the end of bit 6 of 0:15.

Figure 57. SIO Active Mode Output Timing Diagram (2.7 V Operation)

Table 142. Timing Characteristics for Serial Output (2.7 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t86a	OLD Delay (high to low)	—	35	ns
t102	OLD Hold (high to invalid)	3	—	ns
t87	Data Delay (high to valid)	—	35	ns
t88	Enable Data Delay (low to active)	—	35	ns
t89	Disable Data Delay (high to 3-state)	—	35	ns
t90	Data Hold (high to invalid)	3	—	ns
t92	Address Delay (high to valid)	—	35	ns
t93	Address Hold (high to invalid)	3	—	ns
t94	Enable Delay (low to active)	—	35	ns
t95	Disable Delay (high to 3-state)	—	35	ns
t96	OBE Delay (high to high)	—	35	ns

11 Timing Characteristics for 2.7 V Operation (continued)



5-4798 (F)

* See **sioc** register, LD field.

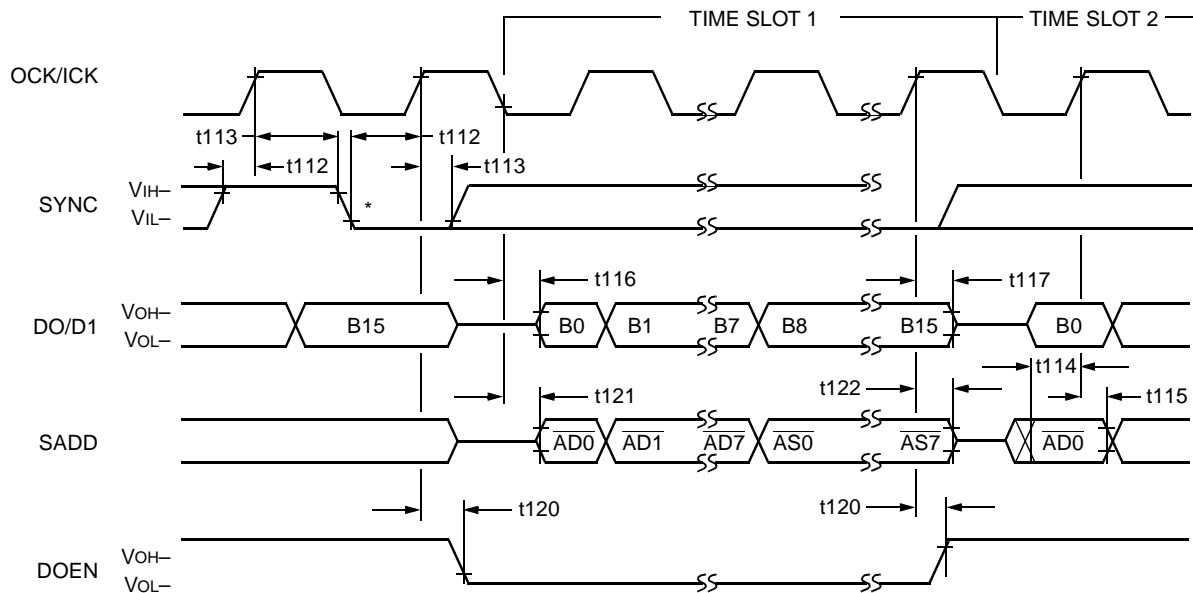
Figure 58. Serial I/O Active Mode Clock Timing (2.7 V Operation)

Table 143. Timing Characteristics for Signal Generation (2.7 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t97	ICK Delay (high to high)	—	18	ns
t98	ICK Delay (high to low)	—	18	ns
t99	OCK Delay (high to high)	—	18	ns
t100	OCK Delay (high to low)	—	18	ns
t76a	ILD Delay (high to low)	—	35	ns
t76b	ILD Delay (high to high)	—	35	ns
t101	ILD Hold (high to invalid)	3	—	ns
t86a	OLD Delay (high to low)	—	35	ns
t86b	OLD Delay (high to high)	—	35	ns
t102	OLD Hold (high to invalid)	3	—	ns
t103	SYNC Delay (high to low)	—	35	ns
t104	SYNC Delay (high to high)	—	35	ns
t105	SYNC Hold (high to invalid)	3	—	ns

11 Timing Characteristics for 2.7 V Operation (continued)

11.10 Multiprocessor Communication (2.7 V Operation)



5-4799 (F)

* Negative edge initiates time slot 0.

Figure 59. SIO Multiprocessor Timing Diagram (2.7 V Operation)

Note: All serial I/O timing requirements and characteristics still apply, but the minimum clock period in passive multiprocessor mode, assuming 50% duty cycle, is calculated as $(t77 + t116) \times 2$.

Table 144. Timing Requirements for SIO Multiprocessor Communication (2.7 V Operation)

Abbreviated Reference	Parameter	Min	Max	Unit
t112	Sync Setup (high/low to high)	35	—	ns
t113	Sync Hold (high to high/low)	0	—	ns
t114	Address Setup (valid to high)	12	—	ns
t115	Address Hold (high to invalid)	0	—	ns

Table 145. Timing Characteristics for SIO Multiprocessor Communication (2.7 V Operation)

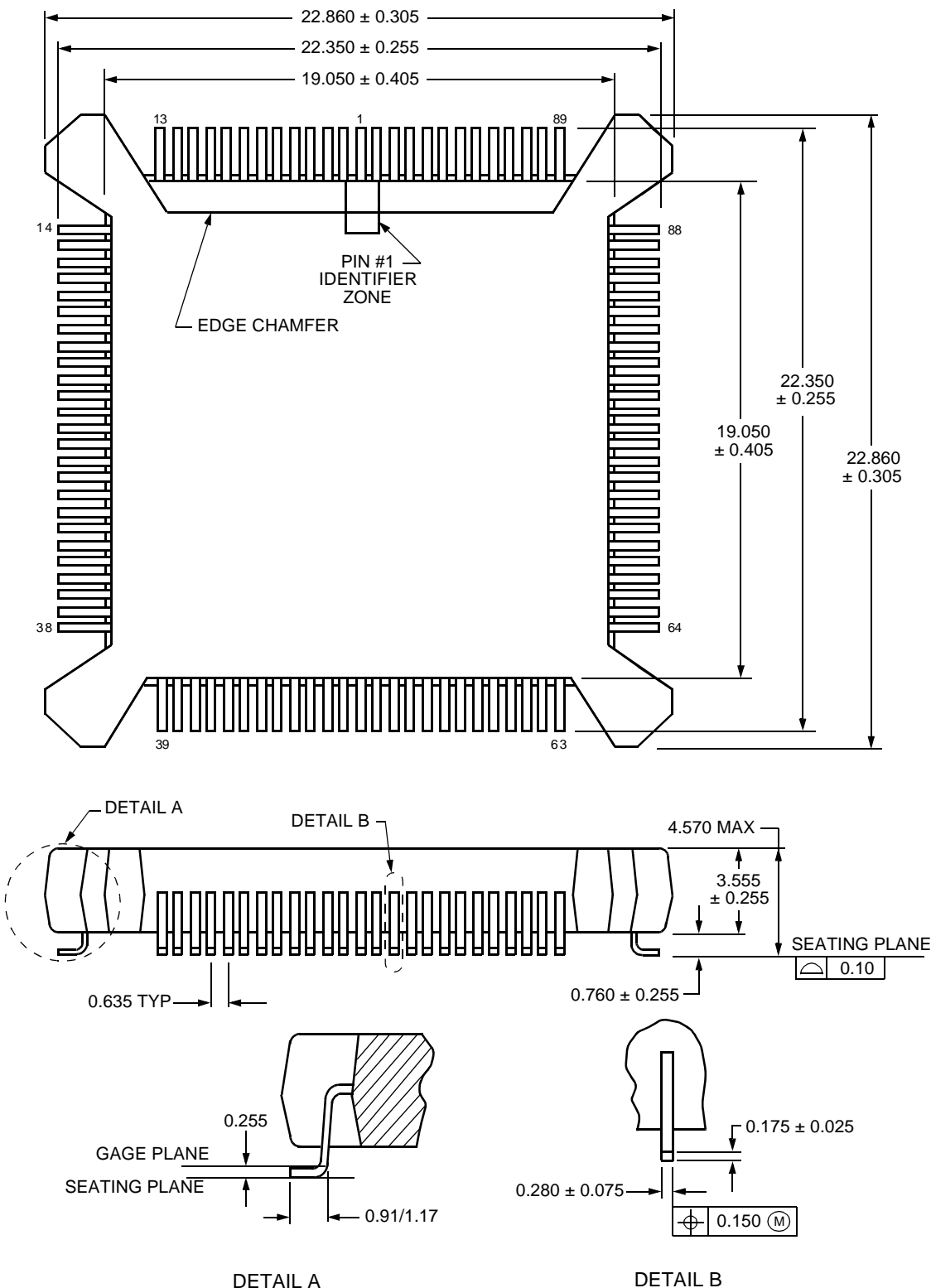
Abbreviated Reference [†]	Parameter	Min	Max	Unit
t116	Data Delay (bit 0 only) (low to valid)	—	35	ns
t117	Data Disable Delay (high to 3-state)	—	30	ns
t120	DOEN Valid Delay (high to valid)	—	25	ns
t121	Address Delay (bit 0 only) (low to valid)	—	35	ns
t122	Address Disable Delay (high to 3-state)	—	30	ns

[†] With capacitance load on ICK, OCK, DO, SYNC, and SADD = 100 pF, add 4 ns to t116—t122.

12 Outline Diagrams

12.1 100-Pin BQFP (Bumpered Quad Flat Pack)

All dimensions are in millimeters.

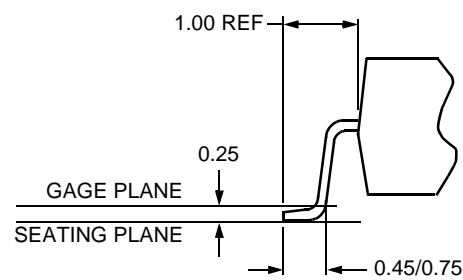
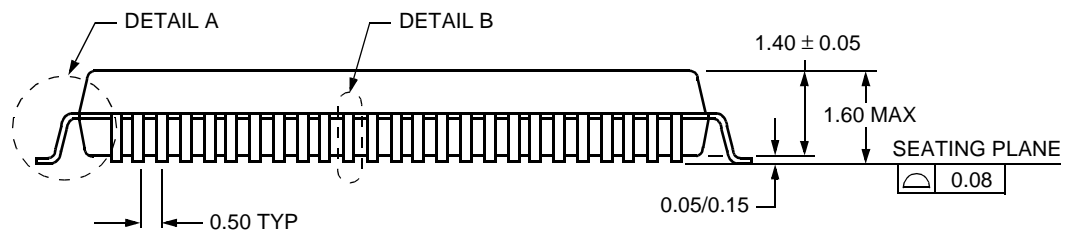
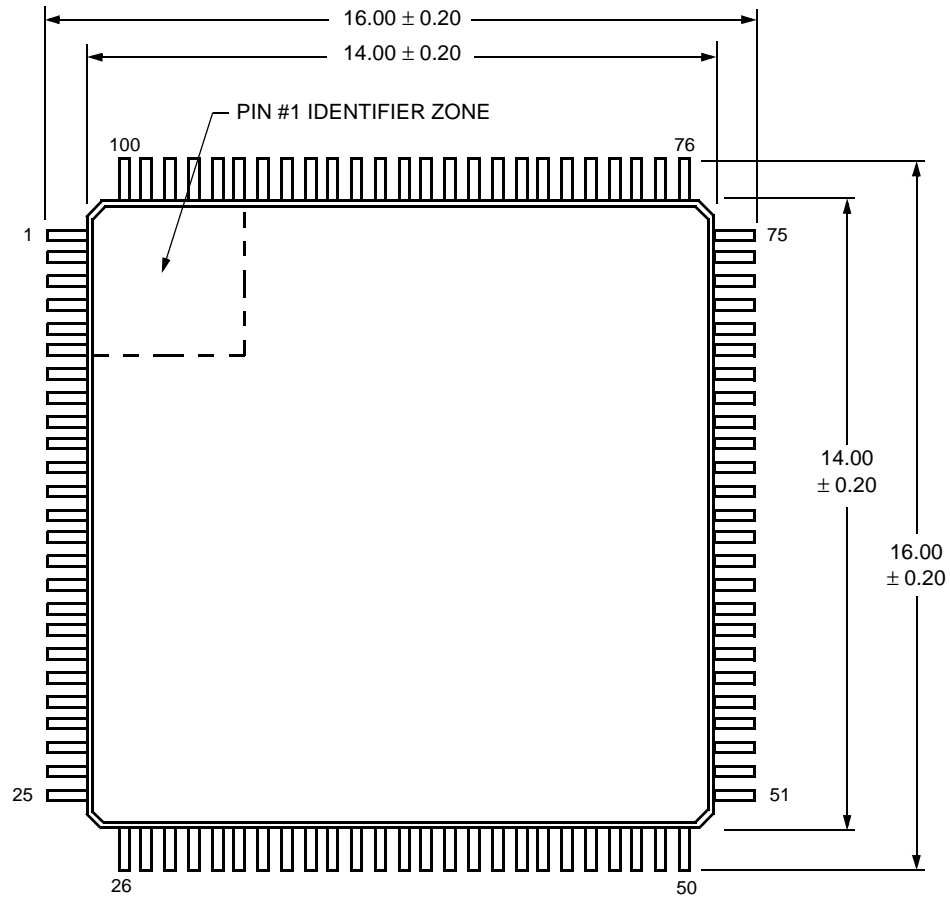


5-1970 (F)r.10

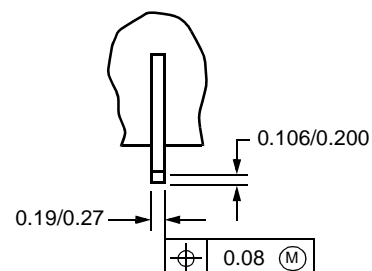
12 Outline Diagrams (continued)

12.2 100-Pin TQFP (Thin Quad Flat Pack)

All dimensions are in millimeters.



DETAIL A



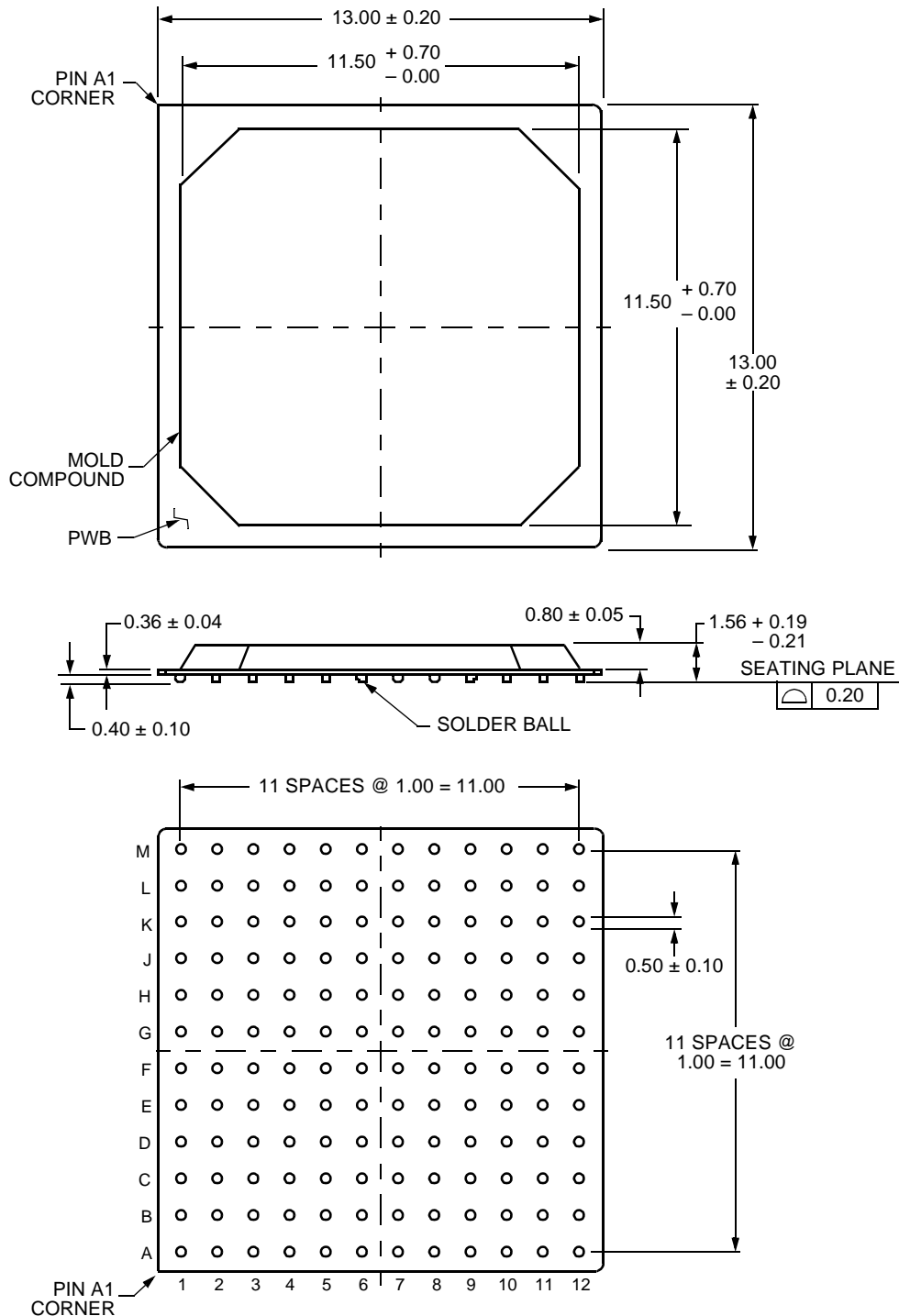
DETAIL B

5-2146 (F)r.14

12 Outline Diagrams (continued)

12.3 144-Pin PBGA (Plastic Ball Grid Array)

All dimensions are in millimeters.



5-5205 (F)

Notes

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